DeltaQualificationMatrix

General
Short product and technology cycles as well as new environmental regulations frequently result in process and material changes of components, printed circuit boards, assembly techniques and circuit layout which have to be evaluated. The ZVEI "Guideline for Customer Notifications of Product and for Process Changes (PCN) of Electronic Components specified for Automotive Applications" describes an appropriate methodology for dealing with changed electronic components. The qualification matrices in this guideline are recommendations for how to assess typical changes of electronic components. These recommendations promote an open risk-based discussion between supplier and customer regarding qualifications.

The DeltaQualificationMatrices were developed by the Industry Task Force Team "PCN DeltaQualificationMatrix" together with component experts from the ZVEI Working Group "PCN-Methodology". Actual content represents state-of-the-art technology and does not claim to be comprehensive. Deviation from proposed guideline should be mutually agreed as customer specific requirements have to be considered.

- <u>DeltaQualificationMatrix Application</u> (completion by component manufacturer)

 a) This table has to be used for changes only. The matrices are not applicable for new product, special qualifications (for instance for encapsulation of module) or Information Notes
- b) If a change is not listed in this table, the qualification plan has to be defined and agreed between customer and supplier.
- c) The matrix for Active Components requires the user to choose between integrated circuits (AEC-Q100 Rev. H) and discrete semiconductors (AEC-Q101 Rev. D1) (cell D4). For Passive Components AEC-Q200 is used. For LED'S the AEC-Q102 is used. For Multi-Chin-Modules the AFC-Q104 is used
- d) All changes as listed in the PCN have to be marked by a cross (x) in column B and will appear colored. The relevant reliability tests are then shown in "Tests, which should be
- considered for the appropriate process change".
 e) In "Tests, which should be considered for the appropriate process change after selection of condition table" is for modification of the found relevant tests under consideration of the weight of change.

 Related table "Conditions" has to be assessed per proposed letters with an (x).
- f) In "Suppliers performed tests" the component manufacturer documents the planned and
- g) In case of deviations from tests, which should be considered this should be notified and commented by the component manufacturer in the area "Reason for exception of tests" Test results in form of generic data (G) are allowed when notified and justified.

Evaluation Levels are categorized as follows_
"C: Component level": The evaluation of a change at component has to be done by the component manufacturer at the component only. Generic data from other relevant evaluations can be used.

"B: Board level": The intended change described in the PCN may influence handling/processability/manufacturability of the component at the customer. Therefore, additional evaluation by the

"A: Application level": The intended change described in the PCN may influence the properties of the application (e.g. ECU). In addition to the evaluation under C or B the influence of the change in the application is evaluated by suitable investigations by the customer. It has to be considered whether the application / assembly requirements are already sufficiently safeguarded by other qualifications (application-specific risk assessment)

" *: Not relevant for qualification matrix": Changes which fulfill neither A,B nor C definitions

Changes indicated as "I" shall not be marked in the DeQuMa. For those changes the Information Note sheet shall be used. As the DeQuMa is desired for PCN only, a marking of "I"-changes would automatically influence evaluation level and test effort.

Important Notes

- To use the matrices in the right form the ZVEI working group provides a Tutorial on its homepage (ZVEI-Tutorial)
- ID number: is a unique identification number for each indicated change defined in the ZVEI PCN DeltaQualificationMatrices. The same ID number is used in the PCN Form sheet to identify the
- change.

 Tests identified by the matrix have **to be considered** and checked if they are necessary to assess the specific change. Test modifications or generic data have to be justified in detail.

 "Further applicable conditions", comments and notes need attention, as they provide important
- hints and limitations.
 In order to use all functions in EXCEL, macros have to be allowed.

Form provided by ZVEI - Revision 5.0 - Dezember 2021

History of DeQuMa

Version	Remarks
2.0	Revised by ZVEI PCN Methodology Workgroup in March 2015
2.1	Released March 2015
2.1.1	Active Components - delete write protection in comments
2.2	Solved problems with some ActiveX configurations
2.2.2	Solved Problems in Active Components
2.2.3	Solved Problems ActiveX, Active Components SEM-DE-02 (Design changes in routing) error fixed
2.2.4	Minor fixes
3.0	General Revision by ZVEI PCN Methodology Workgroup in June 2016
	Changes are indicated by underlining in the read only version named Changes_DeQuMa_rev3_vs_rev2.xlsx
3.0.4	Expert Release
3.0.5	Fixing of macro bugs
3.1	Final Release (orthographic and punctuation corrections)
4.0	General Revision by ZVEI PCN Methodology Workgroup in July 2019.
	Muliti Chip Modules newly added to DeQuMa
	LED Components now based on the AEC Q102
	Further Changes see separate PDF's Excel-File, where changes are indicated by underlining
4.1	LED worksheet: Content of columns had been swapped due to rearrangement and omission of columns.
5.0	General Revision by ZVEI PCN Methodology Workgroup in October 2021.
	Add MEMS pressure sensor

Worked on:	Katherine Cayago, Reliability Engineer	l																						
Signature:	Katherine Cayago																							
Date:	09/08/2022																							
PCN number:	22_0199													ice eval										
ed circuits or discrete ductors select below:	AEC-Q100 Revision H						inclu	udes integra	ated circ	MATE uits (e.g.)	ERIAL PER ASICs. u-(RFORMAN Controller	CE TEST I	RESULTS (s. voltage r	on the b egulator	asis of AEC	-Q100 Re wer devi	evision H) ces. logic (devices. a	analog de	vices)	addition AEC-	onal to	
			Form provided by ZVEI - Revision 5.0 - Desemb	mar 2021	Evaluation level A / B / C			or bissed HAST	ts.	g Ufe	y Ue	ertisn, and		(Prest/down		A		2	5 5			(1000)	anged device hitudion	
	Assessment of impact regarding following aspects -contractual agreements -contractual agreements -form fit function, quality performance, reliability -form, fit, function, quality performance, reliability	Potentia impact	Understanding of semiconductors all experts	Examples to explain	ábor level novel ment bevel nom tilo r qualification restrix:	Further applicable conditions	by data oraudition also check) Revision H	anty) Temperature Humidity Biss	Autodave or Unbased HA Temperature Cycling	Power Temperature Oyclin High Temperature Storage	High Temperature Operati	NVM Endurance, Data Ret Operational Life Wire Bond Shear	Wire Bond Pull Sotterability Physical Dimensions Souther Bull Shour	Lead integrity Bectromigration Time Depending Dielectric	Hot Carrier Injection	Sness Migration Sness Migration Electronic Cischarge Human Body Model	Bectronic Discharge Charged Device Model Latch up	Electrical Distriction Characterisation Description	Short Circuit Characterizati	Lead free Hermetic Package Test	Package Drop Lid Torque Die Shear Internal Water-Napor	Whiston test (RC6006-T2-82, JEDEC JE	Parameter-Analysis Companion of current with di- chara derica for Lef echical dis	Remarks
10	Type of change	No Ye	•		A: Applica B: Boards C: Compo		the evaluation	ok of specific raw material	9 2	PTC HTSL	HTOL. BLFR	EDR	B 2 2 8	- 16 01 02 5 05 01 02	ō (W8 25 E2	мос 01	ED CHAR	2 %	rech WECH	T. T. NW			
- '	ANY		Intended to be used if no other type of chan in				AE SE	5 € A2		A5 A6	B1 B2	B3 C1	C3 C4 C	5 C6 D1 D2	D3 (M D6 E2	E3 E4	E5 E7 E1	9 E10 E1	1 E12 G1-4	us G6 G7 G			
SEM-AN-01	Any change with impact on agreed upon technical contractual agreements	P F	contractual agreements.		٠			1							-							•	-	
SEM-AN-02	Any change with impact on processability/manufacturability at customer, which is not covered in the matrix selow.	P F	Any change which is not covered in the matrix below, but risk assessment at customer is recommended.		В			100							-							-	-	
	DATA SHEET Change of data sheet parameters/electrical specification (min./max./hyp. values) and/or AC/DC		Undate of data about because of backgive shows of	a a recommendation for real units (Lebes - NA)	А																			
SEM-DS-01	peofication	P F	Update of data sheet because of technical change of the product.	pins, MSL	Α																	-	-	
SEM-DS-02 0	Conscion of data sheet or issue of emala		No technical change of product, process or test. New description of behavior which was not specified before or which is different from initial specification. Please indicate clearly, that infoncte contains this type of change! Assessment in application required?	e.g. Errata	A		1								-							-	-	
SEM-DS-03 S	Specification of additional parameters	I F	Description of a new not previously covered parameter. No technical change of the product, (It: Definition of new parameter which was not documented before. (IP): Not known as a single change. Only in combination with other changes.	(f): e.g. adding new bested parameter.	A										-									
	DESIGN											_											!	
SEM-DE-01 g	Design changes in active elements. ¹)	P F	Any device relevant changes in design / layout of elements with effect on with effect on specified eletrical behavior. 1) Not included: Modification to adjust product parameter within appetitied process window and design rules.	e.g. change of ESD structure e.g. add / remove a translator in layout	A	Please check if data sheet is affected (SEM-DS-01).		1		м -		D,J -		- D D	D	D D •					F	-	•	
SEM-DE-02 0	Design changes in routing . ²)	P F	Any change of wiring between elements in chip design / layout with effect on specified elchical behavior. ²) Not included: Modification to adjust product parameter within securities design rules.	e.g. mask changes in metal fix for connective action (based on external 8D report) e.g. Connecting / disconnecting an already existing transistor through notting	С	A: Impact on EMC behavior cannot be evaluated / excluded on component level. A: If impact on electrical function is not excluded on component level. Please check if data sheet is affected (SEM-DS-01).			- A	м -					-						- - - -	-	•	
SEM-DE-03	Die ahrink. ²)	Р	Shrink of active area. 3) Not included: sawing street/kert/scribe line	Typical shrink of die.	А	Please check if change in process technology (SEM-PW-49) is also affected.				м -		D,J -			•							-	•	
SEM-DE-04 F	Finnare modification	I F	Integrated software by design or memory as defined by supplier. (If Pirmware medification or update without effect of functional performance at the customer (bug fix). (P) Pirmware medication or update with effect of functional performance at the customer.	(I): e.g. addition of Firmsears opportunities (P): e.g. bag fix with impact on functional performance	А										-									
	PROCESS - WAFER PRODUCTION											_												
SEM-PW-01	New / change of wafer substrate material	P F	New wafer material.	e.g. different wafer material to currently released material (like change from EPI material into non-EPI material)	С			•							-			• • •				-	_	Qualification effort acc. AEC-Q100: see diffusion/doping
SEM-PW-02	New water clameter	P F	Change of wafer diameter resulting in equipment and process changes.		С	Impact on changes in SEM-PW-03 and/or SEM-EQ-01.			- E	м -		- E	Е		-	• • E	E E	•				-	٠	AEC-Q100: The bread changes that involve multiple attributes (e.g., alte, materials, processes), refer to section AL3 of this appendix and section 2.3 of Q100, which allows for the selection of worst-case test vehicles to cover all the possible permutations.*
SEM-PW-03	New final wafer thickness	P F	Change in final wafer thickness.	e.g. change in final chip/de thickness	С	A: If thermal conductivity is affected (like MODFET; IGBT, BGA package, stacked dies) A: If impact on EMC or ESD behavior cannot be evaluated / excluded on component level.			- E	м -		- E	E		-	• - E	E E	•				-	•	
SEM-PW-04	Change of electrically active doping/implantation element.	Р	Change in electrically active doping / implantation element resulting in a new technology.		А					м -	. #				@•								•	
SEM-PW-05	Change of gate material / dielectrics	P F	Change of gate material (incl. Poly silicon gate electrodes) and / or gate dielectric material or process		А					м -	• @N	D,J -		@	@•								•	
SEM-PW-05	New / change of backside operation (grinding / metallization)	P F	Change of bottom layer of die (between die and leadframe). Change in process, material, or dimensions necessary. Alternative see SEM-PW-09	e. g. change from CriNVIAu to CriNVIAg	С	A: If thermal conductivity is effected (like MOSFET; IGBY, BGA package, stacked dies,) A: If impact on EMIC or ESD behavior cannot be evaluated / excluded on component level.				м -	•				-	м	м •			- н	н -	-	٠	MEQ-Q100: Applicable to all smart power devices
SEM-PW-07	New / change of metallization / vias / contacts	РР	Change in metallization of bondpads, material, layer thickness specifically for chip frontaide and internal layers.	e. g. change from AISICu to AICu e. g. change in over pad metallization	С				• •	м -	•	- •	•		-	- • -		• •	• -			-	•	
SEM-PW-08 P	New / change of passivation or die coating (without bare die)	P F	layers. Change of top layer on die (between mold compound and rie).	e. g. addition of polylmide	С	Change of intrinsic mechanical stress might influence electrical function.				м -	• #	D,J •	•		-	. 							•	
SEM-PW-09	Change in process technology not covered by any other type of change	F		(-); e.g. change from wet to dry etching, e.g. change from horizontal to vertical oven for oxidation (P); e.g. change of layer thickness	A	Please also check changes described under EQUIPMENT. Please check if change is described by specific type of change in this matrix.	•								-							-	•	Qualification effort depends on type of change.
SEM-PW-10 F	Process integrity: turing within process specification	F	Variation within process specification (-): If tuning within process specification does not influence the integrity of the final product. (P): If nemaining risk on product specification is anticipated.	(): e.g. process control	С	Please check if DATA SHEET is affected. Please check if SEB-PW-09 is affected.							- - -		-	- - -							•	
SEM-PW-11 C	Change of water supplier.	F	() If no remaining risk in supply chain solid (P) If the change of varier supplier can influenos the integrity of the final product.	(-): a.g. charge of wafer supplier with same material composition. a.g. same material composition and does not inflamme slorifus behavior. (P): a.g. new supplier with impact on substrate material and / or electrical behavior.	С	Not on component, leasted on test shundare (typical for IC), trianction on component level for discrete components expected, to case of SOI substants HF properties have to be qualified. Please check if SEM-PW-01 and SEM-DS-01 is affected.									-	- -		@•				-		Dadification for C. 6 p. Cortroller difficult on product level. Characterisation on waiter level roly on lest shorture. Not on the shorture of the control
SEM-PW-12 0	Change of specified wafer process sequence (deletion and/or additional process step)	F	Any change which is not covered by another type of change. Impact is to be assessed.	(-): e.g. change of cleaning process in wafer production (P): e.g. additional sinker implantation after standard implantation (to protect circuit against interference imputess).	С	Please check also changes described under EQUIPMENT. A: If impact on application cannot be evaluated on component level									-							-	-	
	Move all or parts of production to a different wafer fab site.		Wafer fab transition with additional changes (described above). Includes transfer as well as additional site.	e.g. dual source / fab strategy	А	Check if any other type of process change is applicable due to the				.,										. н	н .			AEC-Q100: "For broad changes that involve multiple attributes (e.g., site, materials, processes), refer to section AL3 of this appendix and section 2.3 of Q100, which allows for he selection of worst-case test whiches to cover all the possible permutations."

SEM-PW-14 L																								
	Lithography	-	Change in process technique for lithographic process and material (): If the change in process technology does not influence the integrity of the final product. (P): If the change in process technology can influence the integrity of the final product.	Inst []: e.g. eachsange of defect mask [P]: e.g. change from E-beam process to X-ray process e.g. change from contact into projection mode	С	Please also check changes described under EQUIPMENT.			• M		# -	• • •		 •			•					-	٠	
SEM-PW-15 C	Oxida / Veterlayer Dislachic (exct. gate code)	-	Change in process technique for coide (exct. gale caide) / interlayer delectric process (-): if interlayer delectric process (-): if the change in process technology does not influence the integrity of the final product. (P): if the change in process technology can influence the integrity of the final product.		С	Please also check changes described under EQUIPMENT.			• M		#,N D,J	- • - ·		 •						. -		-	•	
SEM-8D-01 N	BARE DIE (Wafer process changes not covered in this section shall be handled according to secti New final wafer thickness	P PROC	P Change in final wafer thickness.	Change in final chip/die thickness	Α						• -				- E	E E	• - -	1.				-	• N	ILFR can only be performed on packaged leat vehicles. BBTI was removed in deviation from the AEC-Q100 Matrix because there it is a combined type of change (Wafer Dimension) Thickness). NBTI is applicable for reafer dimension change only.
SEM-8D-02 C	Change of top metallization or bond pad stack	Р	P Change in bondpads (incl. stack below), material, pad pitch, surface changes, layer frickness	e. g. change from ASICu to AICu e. g. change in over pad metalization	В									 -								-	-	
SEM-BD-03 N	New / change of backside metalization		Change of bottom layer of die (between die and P leadframe). Change in process, material, or	e. g. change from CriNV/Au to CriNV/Ag	А									 -	- м	м •						-		
SEM-8D-04 C	Change of wafer setup or number of possible good dies on wafer.	i	dimensions. Needed information for pick & place machine. (It): amount of possible good dies on wafer (IP): influence on wafer setup and wafer mapping	(I): e.g. change from 350 to 240 good dies on water (P): e.g. information change for pick & place markhine	В									 -				-				-		
SEM-BD-05	Change of optical appearance of wafer edge region (like imide coverage or edge exclusion)	1	P Selection of dies in wafer edge region which have f electrical functionality.	Itali (I): e.g. appearance of wafer edge (rounded instead of square) (P): e.g. polyleride as new costing on die	В									 -				-				-		
SEM-8D-06 D	Dis sorbs or separation	,	 (P): in case of single die is affected Needed information for sawing and pick & place machine. P (ξ): if the change in sawing process does not inflamos the integrity of the final product. (P): in case if product is delivered on wafer 	(I): e.g. if product is delivered as known good die (in tape and reel) (P): e.g. information change for pick & place	В	Please check if SEM-8D-94 is affected.																		
SEM-8D-07 C	Die Preparation / Clean		Change in process technique for die preparation / cleaning P (): If the change in process does not influence the	machine. e.g. information change for sawing machine. (-): e.g. change of cleaning time. (P): e.g. change in cleaning procedure after change of sawing explament.	В	Please check if SEM-8D-95 is affected.																		
SEM-BD-06 N	New / change of passivation or dis coating	Р	integrity of the final product. (P): If impact on product integrity is anticipated. P Change of top layer on die.	of sawing equipment. e.g. addition of polyimide e.g. change of polyimide thickness	В						#,N D,J													
	PROCESS - ASSEMBLY		-					_			_			_	-	_		+	-			_	_	
SEM-PA-01	Change in critical dimensions of package	_	P Change in dimensions of existing package.	 g. changes in package dimensions (further development). 	В				• M	• •	•			 -		• -	•	•	- L F	+	нн	-	-	
SEM-PA-02	Charge of leadinane base material	Р	P New leadframe material in new composition.	e. g. change from alloy42 to copper e. g. change between two different copper alloys	В			•	• M	• -			· · · ·	 -		- -		•	- L F	4	н -	•	-	
SEM-PAGS C	Charge is leadframe dimensions	Р	Change in leadharne dimensions which has impact the specified electrical parameter acc. data sheet or pecification (e.g., heat sink, pin dimensions, die padde sites,) Not included: Variation within specification.	to r e.g. change in lead frame geometry	В	ESD investigations are only recessary if internal ground and power supply connection of leadinane is affected. At if impact on EMC behavior cannot be evaluated / excluded on component level.		. •	• M					 -		- -			- L F			-	-	
SEM-PA-04 C	Change of lead frame finishing material / area (clarrol)	Р	P Change of surface material of die affach pad and second bond area (e.g. influence in adhesion to mo compound, wedge bond reliability)	e. g. change from Ag flash to NP protection layer aid e. g. change from Ag spot to Au spot e. g. increase of silver plating area	С				• M	• -		- c • -	· · · ·	 -					- L F	4	н -	-	. n	for wire bond strength test: Pre- & Post-process change comparison to evaluate rocess change robustness (AEC-Q101).
SEM-PAGS C	Change of lend and heat slag plating material/plating thickness (external)	Р	P Change in material and / or process resulting in a new technology (e.g. pure tin).	e.g. change in heat alug stack e.g. change from Sn into NVPdNu e.g. change of layer thickness e.g. change of edemat burnpo of a BGA e.g. Change of external pins of a hermetic package	В		 	. -	• M	•		- c • -	·						- L F		н -		-	
SEM-PA-06 B	Bump Material / Metal System (internal)	Р	P Stack die or die to substrate (flip chip)	e. g. change to Pb-free material e. g. change of copper pillars	С				• M					 -					• L -			-	-	
SEM-PAG7 C	Die attach melerial	Р	Change of die attach material and / or process resulting in a new technology (e.g. soft solder, epos etc.)		С	A: If impact on EMC behavior cannot be evaluated / excluded on component level (if die atlach has impact on electrical conductivity).	 		• м										- L F	4	нн	-		
SEM-PAGS C	Charge of who bonding	Р	P Malerial, diameter, change in bonding diagram and or change in process resulting in a new technology	e.g. change from Au to Cu malerial e.g. change from 25pm to 25pm diameter e.g. change from slight to double bond e.g. change from slight bond to slight on ball bond.	С	At in case of bond diagram change and EMC cannot be evaluated on component level. Please also check changes described under SEM-EQ-91.			• Q			• •				1	м		F	4		-	P. In	hazamaker Analysis. Statisty required only for Power devices. general Siles audit for malarial change with repeat on brockprocess (e.g. from Au to Cu) constant Control of the Siles of t
SEM-PAG9 S	Substatus Paterposer	Р	P Change of BCA substrate	e.g. changes in rooting	В	A: Impact on EMC behavior cannot be evaluated / excluded on component level. A: I impact on electrical function is not excluded on component level.			• M			• • -	т	 -			@-	•	- L H		нн	-	-	
SEM-PA-10	Die Overcost / Underfill	-	Supporting layers for complex packages like flip chi and / or change in process resulting in a new technology. []: If change does not influence the integrity of the final product. [P]: If impact on product integrity is anticipaled.	ip (): e.g. change of dispensing speed (P): e.g. change of underfill material	С			. .	• M										•		- н		-	
SEM-PA-11 C	Change of mold compound / encapsulation material	Р	P Change of mold compound / encapsulation materia		С	Bi Impact on thermo-mechanical stress caused by mismatch of mold compound, infectormecting bethrology and carrier is anticipated (people, for Prover Dericals). Bi for sures soldered devices in crease of high requestry signals (* 3CHz) is should be assessed if possible changes in parenability of mold compound cated affect signal whereing (e.g. 4) gain garagi processory).		. .	• M			- -	. .			- -			• L -	. .		-	-	
SEM-PA-12	Charge of hermotic sealing	Р	P Affected areas are material and process of herretic (e.g. ceramic) packages, capped de and sealed devices (e.g. pressure sensors)	e.g. change of sealing material for RoHS	В	A: impact on EMC behavior cannot be evaluated / excluded on component level (if encapsulation / sealing has impact on electrical conductivity).			• -	•				 -								-	-	
SEM-PA-13 C	Change of product marking	1	Change of marking on device and / or change in process resulting in a new technology. P (I): If change does not influence the integrity of the final product. (P): If impact on product integrity is anticipated.	(I): e.g. change of appearance (additional marking) (P): e.g. change from inted marking to laser marking e.g. marking of pin 1	В		 					в -		 -	-	- -						-	-	
SEM-PA-14	Change in process technology (e.g. thin and form, leadfarm preparation)	-	(-): If the change in process technology does not influence the integrity of the final product. (P): If the change in process technology can influence the integrity of the final product.	(P): e.g. change from punched to sawn QFN	В	Please also check changes described under SEM-EQ-41. Please check if change is described by specific type of change in this matrix.								 -								-	-	
SEM-PA-15 P	Process integrity: luring within process specification	-	Variation within process specification ((): e.g. process control	С									 -				-						
SEM-PA-16 C	Charge of direct material supplier	-	Change of suppliers for direct materials which are used in assembly process (BOM). (-): If change does not influence the integrity of the final product. (P): If impact on product integrity is anticipated.	(-): e.g. change of wire material supplier. (P): e.g. change to new mold compound supplier. e.g. selforces leadfress supplier with appearin- lauditaress manufacturing technology e.g. Change of BGA substrate supplier, if impact on boxed level infallelity cannot be excluded.	С	Please check if material is changed!								 -									- s	See change of material.
SEM-PA-17 C	Change of specified-assembly process sequence (deletion and/or additional process step)	-	(-): no influence in final product integrity or apecified sequence (P): influence in final product integrity or apecified sequence	(): e.g. additional cleaning step	С									 -				-				-	- 0	Qualification depends on specific change.
SEM-PA-18	Move all or parts of production to a different assembly site.	Р	P Assembly transfer or relocation. Includes transfer as well as additional site.	e.g. dual source / fab strategy	С	A or B: impact on other type of changes described under PROCESS ASSEMBLY and SEM-EQ-01. Check if any other type of process change is applicable due to the transfer.			• M	- .			т.	 -		- -		-	- L F		нн			Whiker leats have to be done on monitoring basis? EC-Q100: "For broad changes that involve multiple attributes (e.g., site, materials, recesses), rifer to section A1 of this appendix and section A2 of Q100, which allows for the selection of wond-case lest whichces to cover all the precisional permutations."
SEM-PA-19	Die scribe or separation	-	Separation process from single wafer to dies. (): If the change in process does not influence the integrity of the final product. (P): If impact on product integrity is anticipated.	s (-): e.g. change of kerf width (P): e.g. change from saveling to laser cut	С				• M					 -				-					-	

SEM-PA-20	Dis Proparation / Clean	Р	Change in process technique for die preparation / cleaning (-)- if the change in process does not influence the integrity of the final product. (P): If impact on product integrity is anticipated.	(-): e.g. change of cleaning time.	С				•	• -	м -	•	-											- н -			
SEM-PA-21	Midding I Encapsulation process	Р	Change in process technique for molding / encapsulation. (-)- If the change in process does not influence the integrity of the final product. (P): If impact on product integrity is anticipated.	(-): e.g. tuning within process specification	С				•		м •	•	-									- L					
	PACKING/SHPPING																										
SEM-PS-01	Packing/shipping specification change	P P	Packing/shipping specification change.										-														
SEM-PS-02	Dry pack requirements change	I P	(I): Relaxation of dry pack requirements (P): Tightening of dry pack requirements	(I): MSL 3 → MSL 1 (P): MSL 1 → MSL 3	В	Please check if data sheet is affected (SEM-DS-01 or SEM-DS- 02).			-				-													-	
SEM-PS-03	Change of carrier (tray, reel)	P P	Change of carrier (tray, reel)		В				-	- -			-							- -			- -		-	-	
SEM-PS-04	Charge of labeling	I P	Change of labelling also on reel. (It: Change of material label without impact on barcode. (P): Changes of material label information which affects data processing at customer.	(f) e.g. additional information (RoHS stamp) (P) e.g. change of defined nomenclature for data processing	В				-				-			-										-	
	EQUIPMENT																										
SEM-EQ-01	Production from a new equipmentitool which uses a different basic technology or which due to its unique form or function can be expected to influence the integrity of the final product	РР	Change in process technique.	Change from single wafer to batch process (e.g. over pad metalization) e.g. dambar cutting (mechanical to laser cutting)	A	Check which other type of change is applicaple due to this equipment change.			-				-							• -						-	
SEM-EQ-02	Production from a new equipmentified which uses the same basic technology (episcensent equipment or estamation of eatring equipment pool) without change of process.	Р	PCN required for dedicated equipment for sensitive component production. (-)- If change does not influence the integrity of the final product. (P): If impact on product integrity is anticipated.	(-): e.g. extension of existing equipment pool (P): e.g. extension of dedicated equipment in case basic technology still need to be proven	С				-				-													-	
SEM-EQ-03	Change in final test equipment type leading to a different test concept.	P P	Change of tester platform with differences in HW or SW that makes a change in test concept recessary (only in case of base die: final test means wafer test)		С															• -						•	Gage RSR / delta correlation
	TEST FLOW																										
SEM-TF-01	Move of all or part of electrical wafer test and/or final test to a different test site.	РР	Tester transfer or relocation. Check impact on SEM-AN-01 Includes transfer as well as additional site.	Dual source strategy	С	Check if any other type of process change is applicable due to the transfer							-							• -						•	Cage R&R / delta correlation
_	Q-GATE								_																		
SEM-QG-01	Change of the last coverage/leating process flow used by the supplier to ensure data sheet compliance (or guinterdischeldfilm of electrical measurement lead flow block; relaxation/serbanoscenet of monitoring procedure or excepting.)	P	 e.g. test flow block, reduction from three temperature measurements to two temperature measurements, change in burn in /ram in processa. (-): If change does not influence the integrity of the final product. (P): If impact on product integrity is anticipated. 	(-): e.g. test implemented without customer requirement (PF): e.g. reduction from three temperature measurements to two temperature measurements to two temperature measurements e.g. change in turn in / run in process.	С							. *		- - -						• .	- -					•	Parameter Analysis: Delta correlation *For Tann in' changes ELFR recommended in case of introduction of new test flow slope consider assessment of influence on product restability.
	•		•	•		•																					
I	Tests, which should be considered for the appropriate process change.				Α		•	•			М -		J	• •						• -			н -	- H -		•	
						•																					
	Tests, which should be considered for the appropriate process change after selection	of conditi	on table.				•	•	•				-	• •		•	•			•						•	
	Suppliers performed tests (mark with an 'X' for done or 'G' for generic)						1	x	G	GG		GG		G G	G	GG	3 G	G x	x x	x						1	
	Reason for exception of tests and/or usage of generic data: Generic assembly data collected on LTC3612 and LT8618, which use the same qualified package and assen	nbly site. Ge	neric fab data collected on LTC3859AL, LTC3859A, LTC	8804-1, which use the same qualified process and fab s	de.																						

Not required.
 Information Note required.
 P PCN required.

A latter or "" inclusion that performence of that stress has alreaded be considered for the appropriate process change.

A (\$ recommended another) by 2/ETI

CONSTITUTE

B For short both reson, five customs forms
C Facet to is satisface.
C Facet t

Signature: Date:											Caulan australia						_	_			_	
PCN number:								м	ATERIAL PERI	FORMANCEE TE	ST RESULTS (on	the basis of AE	C-Q102 Revision	A - April 6, 21	(20)							
		Rehation Need A C B C																			4 1	
	Specialistic CVIII - Respect S.E Deposits 2017	3*4		4 4			_											Ends Med			4 1/	
		4	4 8	a Operation	1 1	5	Micros	S S					1						900			
 contractual agreements sochrical interface of handlingbrocessability/manufacturability of customer form, 16, function, quality performance, reliability 	Understanding of sensiconductors experts Examples to explain	Further applicable conditions	Revision 1	de la constant	angueta Common	la Company	Da.agr. ad	To a second	ā	S S		Ť	90	1		Supplies	ê	90	Accelerate	A Share	des job	Remarks
7	Potential	took of the control o	0.07	and the	Post la		See Levi	in the state of th	Poles CA	Physical Phy	ag g	Territoria Company	OH PER	1	1	Top open	1 1	0000	Constant	Vitra in V	for a	
ID Type of change	Impact7 No Vos	5805. \$893	AEC Comb Forms	1 1	10 0	4 4	8	8 8	а				- 1			н 3	il u	1	1 4	11 1	п	
ARY CECLEDANOT Any chance with impact on agreed upon technical contractual agreements	P P P applicable but the change affects agreed technical										T .		Т.	Т.	Т.Т		T	TT			TT	
	p p Size processability on board sheet sheet	g One FOIC LEDGE ST is affected											-	S,T	-		+-	+-+		.	+.+	-
DATA EMBET	P P Change of application nelevant information (e.g. e.g. change of die substrate naterial manamum pales carrent) due to a technical product or e.g. change of this.	A		. es	gs -	. E.gs	E	_	E	++	 		s	E	Ħ	\pm	=	ε	_	Ħ	Ħ	
CRICLED GROT Change of data sheet parameters/sectrical specification (min. Imax. hyp., values) and/or Pulse DC apecification	P P reasonary puts currently due to a technical product or eng. change of Max. No technical change of product, process or test. New e.g. Einste	1			60	1, 60	-		-		-			-	H		÷	÷		H	÷	
ORICLED CR-02 Correction of data wheet or issue of errata	The Michigan Uniform Control of Section 1 Sect	A .					-	-	-		-		-	-	-			1 - 1			1 - 1	-
																	-	+		\vdash	++	Proceedings of the Royal and a sounder observed
CRC-LED-CR-03 Specification of additional parameters	P P Remainder of an additional parameter attend uses out specified before P if there is a risk on supply chain where at least one additional other PCN-relevant change category will additional temperature coefficient parameter Le.g. additional temperature coefficient parameter additional temperature coefficient parameter additional temperature coefficient parameter additional temperature.	A	• •				-		-		-			-	-							Formation since this is not a product change information: Cassification: C
CRICARD-GROT Design changes in spitzay.	Any-device inferentic thanges in design 1 liquid of epithologist product of epithologist changes within design substantial things by the device of the epithologist changes within design substantial devices, epithologist production, upon the functions, epithologist production should affecting specified functions.	C Sunday from Dadde before to Question with >> OSCLEDOS01					. [T .	Ι.Ι.,			T.T			Τ.Τ				
Seege charges in sphale.	P mm manageme. Challeges within design rates and design specification returned affecting specified functions, dearmanage and rationality. Any change in this design integrate. Provide information of the contract of the contract of the contract of the contract of any change in this peeps integrate. Provide information of the contract of the contract of the contract of the contract of the contract of the contract of the contract of the contract of the contract of the contract of	.,,															4	44	- 1	1	44	
CRICLED CRICO Design changes in routing layout.	Personners and relative larged. Provide information of elegations of the elegation of design larged and elegation of electrical elegations of the elegation of	A sharge in layout of current spreader - OECCLED 601 (institute patient of language) in Ag restor - OECCLED 602 A sharge in Ag restor - OECCLED 602 51 (Frag), industries patient sharges)					•			- в в	D,M	- 1		-	-	. м	м •	- 1				Till right be considered for complex sile bons
CECLEDOROS De divini	P P Strok of active area. Not included: saving streetked/scribe line Typical strok of de.	A Phone check of change in process inchesting (DEC LED PM 06) is also obtained.					•			- в в					-			<u>. </u>	•		-	•
CRCLED-CROS LED package (except leadharre)	p any change in housing thickness e.g. change of dimensions e.g. change of x y, or z dimension of the package	Onesh if DBC LED-DB-d1 is affected which hade to a change of the electrospile parameters or distributions.		•	•		٠	-	-	• B B	D	- 1	•	L	т	- D	D .	-	- 5	5 5	4	•
CECLED CE OS Design of leadflame	P P P my study in Natural graduates	Owin FORC-LED-DB-81 is affected which heads to a change of the electrospile parameters or distributions.							-	• в в	D				т	2 -				5 5	4	
PROCESS - VALVER PRODUCTION		A is case looping of wireland is affected.										4	+	4	Щ			<u> </u>		#	부	
ORCARD-PW41 New I change of water substate or center material	P P Newworks exaction material. e.g. officient solve material to currently inleased staterial (change tree Supplies to Silcon)	C check if CBC-LED-DB 41 is attributed about heads to a change of the ethologytic palamentors or distributions. Transactive trees have all planes abbut sides		р -	•	- Р	٠		•		•	- 1	_	_	-	- Р	P P			نلنا	44	•
DECLED-PW-G2 Wader danseer	p thange of water claimater neutring in equipment and e.g. 4" to 4" process changes	C changes to equipment/process		•		-	٠		•				•		-	-		Р				•
DECLED-FW-GS New Stat water trickness	P Change in final wafer trickness e.g. change in final chipidia trickness	C controllings - Day need to be standard in addition. Check FORCLED-DS-Of in whiched which heads to a change of the electrospile parameters or distributions.		р .	•		•		•	- в в	•			•	-						-	
CBCLED-PW-64 Change of stectrically active doping/implantation stement	P Change in electrically active doping / implantation e.g. change from like to C as opport element resulting in a new technology.	c		с -	с	-	•	-	•		-		-	•	-			•			-	
DECLED-PW-08 Change of stacking	P p change in layer sequence or disckness e.g. change of isolation layer thickness between and p-marketal	A customer application needs to be checked size to potential system satisfies officencies			•	. F	٠		٠		-	- 1	_	-	-			•			-	
	P Disage in metallization of bondpads, material, layer e.g. change in bond pad metallization thickness. Change of bottom layer of die perseen die and	© As in case of shange to Atuminsum medititization					•		•			- b		D,M	-	- M		M,B				
		S sharpe from CVD dep to spaller dep		•	+ +	•	•		•		•	- D,		DM	-	- D,M	ом ом	D,M	D,M -		H	•
CRICARD-PW-06 Change in process technique (e.g. significant process changes like lithography, ecch, oxide deposition, die back surface preparation/backgrind,]	Change fromwest for dry estating, change from horizontale P by versical over-for collabor, change from contact titles are seepper little, Change from leaser custing (sealing) to place on are seepper little, Change from contact little on Change from contact little to employee little Change from contact little to employee little	C for backcole/formbode metallication. In case of new equipment please of other Color of the col	• •				-		-		-		-	-	-			-			•	Qualification what depends on type of change
DECEMPTOR Process broggin; Yuring within specification DECEMPTOR Change of material supplier with no impact on agreed specifications.	P Variation within process specification e.g. process control Drange of water supplier. Change of supplier for P a.o. change of water supplier.	C Change of maler supplier phases check if ORC LEDFW 01 is affected.					-		-		-		-	-	-			-			-	
DECARD-PW-11 Change of specified water process sequence (deletion and/or additional process step)	P D Danger from Engine Congress of Engine for P D Danger from Engine Congress of Engine for P D Danger from Engine Congress of Engine for P D Danger from Engine Congress of Engine P D Danger from Engine Congress for Engine P D D Danger from Engine Congress for Engine P D D D D D D D D D D D D D D D D D D D	C ORCGEOPWell is affected.					-		-		-		-	-	- 1			1-1			1.1	Qualification effort depends on type of change PPAP has to be updated.
ORCARD-PW-12 Change in die coafing or passivation	P Dange in reserved, thickness, and process for costing e.g. change from SICC to SIND	e			р .		•		-	- P P	-	- 1	_	-	-	- Р	P P. @					•
GEC-LED-IN 13 New wafer production location or transfer of wafer production to a different not previously released location/ble-abcontractor.	P Newwafer production location or transfer of wafer production with possible additional changes.	A or E Impact on other type of changes described under PROCESE - WAYER PROCEUTION and EQUIPMENT subgester of the CHAMA	• • •	•			•		•		•			3	-			•	•	1 - 1 -	1 - 1	•
DATE DE CELOTERES (Within process sharper and covered in this section shall be had CELOLED #301) New! change of front side metallization.	ted according to solice "Process : Water Production" p	A in case of chip-on-board technology	M		T • T		•				-	1.1.	-		T - T						1.1	Passinable package type for retability tector supplier and continuer
CECLED-6000 New/change of backside metallization	P P Stange of bottom layer of die (between die and saadhamecamier). Change in process, marerial, or e.g. change from Au to Au alby timesolone.	A is case of chip-on-based inchedings Deals if CRC_LEDES 41 is allowed which has it as change of the subclooping inscreeds or delibrations. A is case of chip-on-based inchedings	M				•		•		•			•	-			D, M	D, M -		1-1	Cushaner application needs to be sheated di- utilized differences. Neurosalite package type for relatifity testing applier and unahance:
CRCLED-80-03 Change of water setup or number of dies on water.	Nee-decintermation for pick & place machine. 1 P conty additional number of chips Richards in season to bettern of the place machine. P change in season to bettern of chips and form of water. P change in season to bettern of chips and form of water.	 As to case of ship-on-board inchestings 	* * * * * * * * * * * * * * * * * * *						-		-		-		-			1-1			1 - 1	Procurable package type for relativity tecting supplier and continuer
OECLED BOOK New Staff wafer thickness	P P Changes in final Chip height (including carrier); very e.g. change on converter thickness locations of carrier represent	B Check of CRC-LED-CR 41 is also abbotion. A is case of object-instead inchestings.	e e P	р -			•		•	• в в				•	- 1		- GP	Р	Р -			Pleasurable package type for relatifity tests supplier and customer
CRICLED 8000 Chance in de southo or passivation	P Change in naterial, thickness, and process for coating e.g. change from SICC to SINC	Own FOEC LED-DE-B1 is also about the in case of ship-on-board inchestings.	. P	•	р .		•		-	- P P	-	- 1	•	-	-	. Р	P @P	р	Р .		-	Resourable package type for relability texting supplier and customer
PROCESS - ASSESSE, Y CECLED PACE Change of least amelyadrouses been reperfed	P P Newinadraminatement naterial (new in composition) e.g. change from copper alog to bare copper	Deck if OSC LEDGS 41 is affected which heads in a change of the electropic parameters of distillations.					Р		. I		٠.	3 /		P.1	Т.Т	P A @•	A.G	T.T			Т.Т	(g) is required for conscious leads FCIS/PMC. Splated accordingly at read revision. Exclusions should be arrested in case FCIS I
	P Personal antiferior instantial of the attach paid and P P except both any a control paid and experience of market and experience in adheritor to social experienced, which is control to the service of market and experienced and experienced and experienced and experienced to the experience of the ex	electrospile parameters or distributions.					P							_		- A@+					++	Explanation should be produced in same HOS I Propositing applicable malerials please whe to (2x in required for communication HOS/PMS application should be produced in same HOS I Explanation should be produced in same HOS I and the HOS I same HOS I in the
	compound, wedge bond relability: Change in raterial and process traditingue for final pin termination (e.g. pure 16). Herein package, e.g. change in head dag stack			к -			P						_	_		K A@•		+	H	H	+	@ is required for consister leads HCEPMS.
CRCLEDPARD Change of lead and heat sky ploting naterial ploting thickness (external)	Obaque in material and process technique for find pin- minimization (e.g. par of herein) paccage, e.g. of change in heat skip stack processability and relatability on hoard bevil can be writted by generic data. Cassaffication depends on special of change.	A .								1							w •	\perp			11	Epidami accordingly at real materials. Explanation should be provided in case HCS I frequenting applicable materials please with to
CRCUIDPAGE Bursp Marerial / Metal System (internal) CRCUIDPAGE Dis attach retariol	P P Stack die or die 1s substate s.g. change 1s Po-free inaterial P P Stack die or die 1s substate s.g. chi solder, epicey. P P Stack die or die 1s substate inaterial (e.g. och solder, epicey. g change of Ag gibe 1s Au-glue; eig. Thereia management munche inaspectual.	B A in case 700 is changing					•				- :	- v			-	- w			- N	N N	##	-
CECLEDPAGE Change of wire bonding	P P Statesia, claimeter, change is tonding diagram and / or 8 g. change from As to Cu crossing to 6 g. change from 25 gm is 3 gm in process resulting in a new bioliniting. Claiming from 25 gm is 25 gm in 25 g	Α		P,D -									٠.	_		-	P,D -			D, GP D, G		Bite audit for material change with impact on As to Culy recommended.
	thange in process resulting in a new technology. e.g. change from single to double-bond e.g. ch	A Clark FORCARDOS OT is also affected.															+	+			+++	Customerania Customerania Customerania
benq with injust on agreed specifications CRICLEDPAGE the Owncoat / Underfile	See June team and childre invite be recessary Supporting layers for complex processes the Sp-Life, P - No Change in product improve processes the Sp-Life, P change can influence the impropy of their product. Change of mate compound, an angulation, or reading.	B alleded and the state of the		@• ·							U		٠,	U		. р	р .		. р	р р		
CREATE PAOR Chance of most consound/engagestation/leasing material	P P P Accessor register of the Community of the American Community of the	A Committee of the state of the							Р			3 1	_	_	т	. р	р .			D, gP D, g		
	assembly and board coating has to be assessed. Mills.					1																
CECLEDPA10 Change of conversion material CECLEDPA11 Change of dreat supplier for converse material	P P Change of numeric class. e.g. change from gravats to noticles - P New supplier with same material specification	© Clark FORC LED-DB 41 is affected for optically followed by page rates ©				- Y	•		P P			- 1				- P	P •	Ħ		Y Y		•
CRICLED PA-12 Change of consenter process technology	P New applier with same material specification tent translaging for converse production. P to including the converse production. B to case of instance and applications of product conversion is a given by the conversion is a given conversion in a given conve	shed DECLED DS-61		•		. Y	•	-	z			- 1	_	Y	-		z z		- Y	Y	1	•
CRICALID PA-13 Change of product marking	Personal or devices on reconstruction of the personal or devices of th					- 0	-		- 1				т	-	т			1 - [- -	1.	-
CECLEDPA16 Change in process technique (e.g., die artach, molding, plating, tilm and firm,)	P P Any change in assembly process technique e.g. change die attached from gluing to soldering:	A or E. Proses close i SQUEPMENT and other type of changes of material (CEC.LEDFA.0408007080810) are allested. Fibe process change is consend in a																				Qualification effect depends on type of change
CRICLEDPA19 Process integrity: Tuning within specification		The process change is control in a expande change ID only this is															+	+			#	
CBCLEDPA18 Change of dreat naterial suppler with no impact on specification	 P Vertizion withi process specification. a.g. process control: p Change of suppliers e.g. for tread finance, wire material. Change of suppliers e.g. for tread finance, wire material. Change of suppliers e.g. for lead finance, wire material. Change of suppliers e.g. for lead finance, wire material. 	C Specially that change material specification remains unchanged. Observation one change of material.															- 1		1	ri Fi		- See sharpe of mulerial.
CECLED PA.17 Change of specified-essentily process sequence (additional analyst deletion of process	P Visitation states principles against based from the state of states and states against account of states and states against a state of states and states against a state of states and states against a state of states and states and states and states and states against a state of states and states and states against a state of states against	Citerates see charge of malerial. C Single case assessment necessary to identify occupies introductors or not.																				Qualification effect depends on type of change
mg)															Н		4	+			##	
	P P Assembly transfer or rebustion. Advantage transfer as well as additional also. A dual source if six strategy	C Broad on other type of changes described under PROCEES ASSESSED and EQUIPMENT ORCLED-EQ-01	• • •			- -					· ·					- -	نك	لت	1 .	نلت	بلت	Qualification effort depends on type of change
CECLEDPECT Curar Packing/shipping specification change	I P dimension changes indirect product packing I same disappe in direction of appearance P counter of result in the packing set disapping						-		- 1					-				-				-
CECLED P3-00 Dry yack requirement change	P (5: Parametrion of dry pack requirements (5) MSE, 3 + MSE, 1 P) Trigitating of dry pack requirements (P) MSE, 1 - MSE, 3	g Own FORC-LEDGE-61 is also allocated.					-		-		-				-			-			-	-
	P P dimension change of direct product packing any SMT pooked in tape changes																	4				

	CECLEDPROI C	Change of labeling	1 6	Change of labeling also on reel. additional information no change of previous softwards Pt change in content of previous information.	() a.g. additional inflamention (NaPS stamp) (P) a.g. shange of customer specific inflamation		Check if CBC LED-CB-01 is also affected.			-	-	-	-	-			-		-	-	-	-		-		-	-		-	-		
•	oscuspager p	Production from a new equipment/bod which uses a different basic technology		Change in process technique which is not stready ownered above. Note: Major changes affecting the product not covered.	e.g change from single nathr to latish process e.g. one paid reticlatation e.g. distribut culting (manhantual to later sulfing)		Orech if LED-DE-01 in also affected. Contractors stability should be assessed.			-		-	-	-			-			-	-			T - I		1.	-		-			Qualification ethni depends on type of change.
.0	OSCURDADO?	Production from a new equipment/bod which uses the same basic technology (replacement equipment or extension of eating equipment pool) without change of	1.	to the table require along programming or productions overthe to the table require along PCN PCN required for dedicated equipment for sensitive component production. []: If change does not influence the ingestity of the final	e.g. change from single side to multi-side hander. (-) e.g. extension of existing equipment pool, already	0														H												
		grower.	- '		qualified. [P) mg estimation of dedicated equipment in case toxic bedrinkings will need to be proven.						ļ ·	-	-	-			++		-		-		- -	\perp		ľ	-		ľ	-	-	Quantum min seperat in type is using.
aD	oscupson c	Change in final text equipment type that uses a different technology		By E impact on product intergetly is anticipated. Change of tweer patients (e.g. major test program. changes (was tracer interface). E product specification is not affected. P. product specification is affected.		c	E is case of bare de delivery		<u> </u>		<u> </u>	•		•	1		-		-		•	-	- т		1	L	•	1	Ŀ	-		Cage NSK! della corrélation
40	ORCLED TP-01 N	Move of all or part of electrical water text and/or final text to a different location/shirkubcontractor Q-GATS				9	E is case of bare de delivery	•		-	В	-	•	В	- -	- в		8 8	В	-	-	•	. т	<u> </u>			•	•		-		Copy NSEC della correlation, additional operationition check. It should be considered for Walter bearing
	ORCHEDQS01	Change of the text coverage testing process flow used by the supplier to ensure data street compliance (e.g. elimination/addition of electrical measurement	- 1	e.g. text fluviolocis, reduction from three temperature reasonments to two temperature measurements, planing in turn in / humin process. (+) if change does not influence the integrity of the final product. (If if invest on conduct integration approximated.)	(-) e.g. led implemented sollrand customer requirement (F) e.g. reduction from three temperature measurements to be temperature measurements	c						-									-											
AGER DIODE		CASHA BOOK (TD)		product. (P) If impact on product integrity is arricipated.	e.g. change in Sum in / nun in process.				_	1																Ш			Ш			
	OECLAS-ANIO1 A	Any change with impact on agreed upon technical contractual agreements		bitended to be used if no other type of change if applicable but the change affects agreed technical contractual agreements.		-				-	-	- 1	-	-			-		-	- 1	-	-		1 - 1		1 -	-	Τ.	-	-		
AGER DIODE	OECLAS-ANGS A	Any change with impact on technical interface or processability/manufacturability of customer, which is not covered in the matrix below.	9 5	g See processability on board level technical interface means component terminals.			Check if QSC-LAS-QS-Q1 is affected Processability should be assessed.				-	-	т	-			-			-	-	S,T		-		-	-		-	-		
ASER DIODE	GECLAS-GS-61 S	onta svest Change of datatheet parameters/electrical specification (nin Insactyp, values) and/or Pulsa DC specification		Change of application relevant information (e.g. equipment pulse current) due to a technical product or process chance.	e.g. change of de subcitate material. e.g. change of reseator cavity length. e.g. change of MS.				£.6	ıs ·	gs	i i	E, gs	E	- 1	: :	H	- -		H	- [s	ε .	Τ·Ϊ	- -	Ť	ε	ε -	-	-	- Е	
				P maintaining take current) due to a technical product or process chance. No technical change of product, process or test. New description of behavior which was not specified betinn-or which is different from intelligencification. Please indicate clearly, that indicate contains this type of chancel.	e.g. Erada e.g. change of typ. values due to new inflamation about component behavior							-									-			-								
-				Assessment in application required	improved statistics.												+	+						+		+					+	Formation since this is not a product chance, ony additional
AGER DIODE		Specification of additional parameters		E Definition of an additional parameter which was not specified before P. Effers is a text on supply chain where it least one additional other PCN-relevant change category will addit.		^		•		-		-	-	•	- -	- -		- -	-	•	-	-	- -	-		-	-	- -	-	•	•	eformation Classification: C
		Design changes in epitasy.		Any-device relevant changes in design, I layout of epitasist layers. Plot included: Changes within design rules and design specification elimit affecting specification element.	e.g. change of barrier thickness. e.g. change of waveguide layers.	c	A: It case of LEAR application is affected										-				н					-				-		
	0601A9-06-02 g		+		e.g. change in injured of current operator; Doubress of Current operator e.g. reduction of load past claim e.g. self-ball disonal past from lawer faced e.g. change of front operator dimension and positioning of e.g. change of front operator dimension and positioning of		Acti case of LDAR application is affected												D.M		м											
			' '	Any change in chip design / layout. Provide information is design fuyur change is optical or electrical. Not included - Changes within design rules and design specification without affecting specified functions, parameters and reliability.					٠.		٠	•	٠		•			вв			ш		- -	-	м	Ľ						TR right be considered for complex die bond technologies
AGER DIODE	0601A9-06-03	De crisk		p Strink of active area. Not included: saving street/softscribe ine		٨	Please check if change in process technology (OEC-LAS-PW-08) is also affected. Check if OEC-LAS-09-01 is affected.	• •		-	•	-	٠	•			-	8 8	٠	-	-	•	•			-	٠	•	-	-	•	
AGER DIODE	OEC-LAS-DE-01	Laser package (exapt leadframe)		P any change in housing thickness. any change in form or dimensions	e.g. change of dimensions e.g. change of x, y, or 2 dimension of the package		Check if OSC-LAS-OS-91 is affected which leads to a change of the electrospic parameters or distributions. A in case of LEAR application is			-	•	-			٠,			вв	D	-	D		L T		D D			- :	5	5	4 .	
			+		e.g. change in teadframe / carrier dimensions in x.y. or 2 direction		At it case of LEAR application is affected. Check if OSC-LAS-OS-91 is affected which issaed to a change of the electrospic parameters or distributions.																	H								
	OEC-LAS-DE-ES			any change of leadhame / submount dimensions any change of outer dimensions	e.g. change in leadframe / carrier dimensions in x,y, or 2 direction e.g. change in wirebond boping e.g. change inner design of the leadfeame not affecting the elo performance & reliability of the direction	•	electrooptic parameters or classifications. At it case looping of wirebond is affected.	•	٠.	-	•	-	•		- 0		•	8 8	D	-	-	٠	• 1	2	-	•	•	•	5	5	4	
AGER DIODE		PROCEES - WANTER PRODUCTION	Ť				Check if OSC-LAS-OS-31 is affected which issaed to a drange of the electrocytic parameters or distributions.		Ť															TT	Ť	Ħ		Ť	Ħ	Ť		
ASER DIODE	GECLAS-PIN-01 N	New I change of water substrate or carrier material		P Newwafer substrate material.	e.g. different water material to currently released material (change from Sapphine to Silcon) e.g. different orientation of epitasial substitute		electrospic parameters or classifuctions. At its case of LEDAR application is	•	• Р	-	٠	-	Р	•			-	- -	•	-	Р	•	• •	-	р р	Р	P	Р .	-	-		
ASER DIODE C	GECLAS-PIN-02 V	Wolfer diameter		change of water clameter resulting in equipment and process changes	eg ChC	c	affected. Typically this type of change affects other changes i.e equipment/process sectocology - they need to be identified in addition.					-	-				-									1	р	р .				
ASER DIODE C	GEOLAS-PINOS N	New final water trickness		P Change in final water thickness	erg change in Soid chighter Discourse.	c	identified is addition. Check if OSC-LAS-OS-01 is affected which leads to a change of the electrooptic parameters or		. Р						. a	е .		8 8								١.	р	р.	١.			
						c	distributions.				с	-	-						-		-	-		-		-			-			
ASER DIODE C	OSCURB-PINOS C	Change of stacking		P change in layer sequence or trickness	e.g. change of autation layer thickness between in and pro-		For LEDAR: Typical change of electrical or optical parameters within apecification needs to be evaluated on application level.					-	,		. e	е .					,											
ASER DIODE C	GECLAS-PINOS N			Change in metallization of bondpask, material, layer		c	on application level.		M			-									м			+	M M	D,M	M,B	M,B -				
ASER DIODE	GEOLAS-PINIST N	New! change of metalization (specifically chip backside)	, ,	Change in metallization of bondpads, material, layer Exchange of bottom layer of die (between die and sadhamelicanies). Change is process, namerial, or	e.g. change from Aurio Auritie	c			м	-	•	-	•	•			-		•	-	D,M	•	D,M -	-	D,M D,I	A D,M	D,M	D,M -	-			
ASER DIODE	GECLAS-PINOS C	Change in process technique (e.g. significant process changes like littingraphy, etch, oxide deposition, die back surface preparation/backgrind,		Change from set to dry extring, change from horizontal to vertical over for osciation, change from contact litho ans stepper litho,	e.g. change from sed with in dry with e.g. change from laser culting (sawing) to placese culting (sawing)	e	Et change from CVD dep to spuller dep for backvide/forebode metallization. In case of new equipment phase check if CSC-LAS-PA-17 is also affected.					-	-				-			-							-					Qualification effort depends on type of change.
ASER DIODE C	OSCURA PISOS p	Process Integrity: Tuning within specification			e.g. process control	c						-	-							-	-			-		-	1		-	-		
ASER DIDDE	060 LAB-PW-10	Change of material supplier with na impact on agreed specifications.	- 1	P Variation within process specification. Diange of water supplier. Change of supplier for chemicals needed for water production. Armonials tanded for water production. Armonials for the covered by another type of change within it not covered by another type of change within it to be assessed.	P. e.g. change of suther supplier.	0 0	Change of wafer supplier please check if OSC-LAS-PW-01 is affected.			-		-	-	-			-		•		-	-		-			-					Qualification effort depends on type of change.
		Change of specified water process sequence (deletion and/or additional process step) New Change of Scott passivation		Proposingly leads in the continue of personal spirit or change. Note in to be assessed. Change of remelal, thickness, process and stacking for Afolder shorr coating.	e.g. additional cleaning process in water production. e.g. reduction of AX reflectivity by reducing ne of stants.	9	Check if QEC-LAS-QS-Q1 is affected which leads to a change of the electrospic parameters or distributions.					-						1		-	· v	•		+ +		, -		-	-	-	-	Qualification effort depends on type of change. PPAP has to be updated.
				ARMR minor coating Change in material, thickness, and process for coating and passivation.							P			-:-				P P			P	•			P P	· @ •	р	P				
				Newwafer proposition location or transfer of wafer production with possible additional changes.			Aur & Impact on other type of changes described under PROCEES - WAPEK PRODUCTION and EQUIPMENT subsystem of this DROMA										+															
ASER DIDDE		pre-locally released to catorichars. Doorbacter BAME DE DELIVEREE (Water process changes and covered in this section shall be hand	led accordi	production with possible additional changes. Ing bit section "Process: Made Production" 1 Change in bondpads, resterial, pad pinds, surface planges, toyer trackerse.			A: It case of this contrator				L	Щ			Ļ					Щ			_	Щ	+	\perp		4	\perp	4	Ļ	
				P Change in bondpads, material, pad pitch, surface shanges, layer frickness.		•	A: It case of chip-on-board technology Check if OSC-LAS-OS-01 is affected which leads to a change of the		м .		•	-	٠				-			-	•		• .	-		-	M, B	м, в -		-		Researching package type for reliability tenting to be aligned between supplier and customer. Customer application needs to be directed due to potential
ASER DIODE	OEC-LAS-RO-02 N	New/ change of backside metalization		Change of button layer of die (between die and badflameicarrier). Change in process, material, or dimensions.	e.g. shange from Jurio du alley	•	Check if OSC-LAS-OS-91 is affected which leads to a change of the electrospic parameters or distributions. A: is case of chip-on-board technology.	1	u .	-	•		•		٠ .	. .	-		•	•	•	٠	•	-		•	D, M	D, M -	-			system outdage differencies Feasonable padrage type for reliability testing to be aligned between supplier and customer
AGER DIODE 0	06C-LAS-90-03	Change of water setup or number of clies on water.		Needed information for pick & place machine. E-only additional number of chips. P-chance in exacting between chips and form-of water.	e.g. information change for pick & place machine.		A: It case of chip-on-board technology							-			-			-	-			-		-			-	-		Reasonable package type for reliability testing to be aligned between supplier and customer
ASER DIODE	OECLAS-RO-01	New final water thickness		Changes in final Chip height (including carrier); very sare and usually contribued with a numerial change (change of carrier material)		٠	Check of OSC-LAS-03-01 is also afficial. At it case of chip-on-board isothering.	•	P P	-	Р	-	Р	Р	٠,	. Р	Р	вв	Р	-	-	Р	Р.			Р	Р	р .	-	-		Passonable package type for reliability testing to be aligned between supplier and customer
		Change in die stating or possilection		P Change in material, thickness, and process for coating and passivation	e.g. shange from SCE to SNS		Check if OSC-LAS-09-01 is also affected. At its case of chip-on-board technology		,	-	Р		•		٠,		-	РР	-		P			-	р р	Р	р	Р .	-	-		Passonable package type for reliability seeing to be aligned between supplier and customer
AGER DIODE		PROCESS - ASSESSELY Change of leadfame/outnount base nativital	, ,	P Newleadfame/autonount naterial (new in composition)			Check if OSC-LAS-OS-01 is affected which leads to a change of the electrospic parameters or			Ť.				р						3	Α		P,1 •	р	Α 4	Ť.						Signature should be provided in case HI'S test is not applicable
							electricoptic parameters or distributions.							P			+				Α .	<u> </u>	P.1 •		.	-						Regarding applicable materials please refer to the Whisker standard. He should be considered for automotive extentor applications.
			, ,	Change of surface material of die attach pad and second bond area (e.g. influence in adhesion to mold compound, wedge bond relability) Change in material and process technique for final pin							Ŀ							+	•		-		-	+-	^ A	Gt.			H	-		exponence should be provided in case HOS test in not applicable. Sectionation should be provided in case HOS test in not
	OECLAS-PR-03		, ,	Change in material and process technique for final pin sminution (e.g. pure tri). Herein package. Processability and misability on board level can be setfled by generic data. Classification depends on impact of change.	e.g. change of layer thickness				M K		-		٠	Р			1		-		A	٠	P,1 •	к	A A	-	-		-	-		Segmenting applicable materials please refer to the Whisker standard.
ASER DIODE G	CECLAS-PR-01 g			P Stack de-or die to substrate Change of die attach namerial je g, oof solder, eposy, on. Thermal proposation of the same and	e.g. Auglie to Audin soldering		At it case Rithis changing	- -	:		:		•	-:-			-		•		W N		• •			•				- N		
		Change of wire bonding		Michigan paraparent must be respected. Miderial, diameter, change in bunding diagram and /or change in promocousting in a new inchestings.	e.g. change from Au to Cu material e.g. change from 25µm to 25µm diameter e.g. change from skich bond to skich on ball bond.				. P.								-		-	-				-	P,D P,0			- D, (ge D, ge	D, @P		Site audit for material change with impact on bondprocess (e.g. from As Tr Ca) recommended.
ASER DIODE 0	OECLAS-PA-07	Change in naturalistic sub-components (excluding Linear drip & Laser package nebmed benny with impact on agreed operations			e.g. change from stich band to stich on ball band. e.g. using a different ESD or photodode in technology and material than previously		Check if OSC-LAS-OS-01 is also affected.			-		-	-	-			-		-	-				-		-			-	-		Qualification effort depends on type of change.
		Die Overcoot / Underfit	- 1	Supporting layers for complex packages like flip thip. — No change in product imaging. P change can influence the integrity of final product.	P. e.g. change of underfit with change of thermal resistance		Check if OSC-LAS-09-01 is also affected.		P. P. C			-					-		U	-	-		U -	-	р р		-	. ,	Р	р		
AGER DIODE	GEOLAS-PA-OS	Change of mold compoundencepsulation/seeiing material	, ,	Consider of the Configuration Complete using different between growing the configuration of t	e.g. PPR rold compound		Check if GSC-LAS-GS-61 is also affected.			-			-			ge p	D		-	3	Р		РТ		р р		-	- D, (ge D, ge	D, @P	4 -	
	OECLAS-PA-13	Change of conversion material		eight be changed. Change of nativital class.	m.g. change hore granule to reliables		Check if QEC-LAS-QS-Q1 is affected for optically/stometric parameters						Y			gs p					Р		Υ .		р р			. ,	Y	Y		
ASER DIDDE					1		to opcopication or parameters									де Р		_									-		р			

LASER DIDDE	060 LAS-PA-12	Change of conventor process technology	Τ.Τ.	newtechnology for converter production to influence on els performance of product	e.g. change tion volume consention to layer consention; e.g. change tion stamping to pricting sifayer e.g. change consents attainfollowlesses		Check if any change in ideato- optical characteristics results in change of data sheet OSO-LISE-OS-					· ·	1.		7			Ι.	7		ν.	. 7	7 7			v v	1.1.	
	060 LAS-PA-13			E no influence on era performance of product Pt in case of impact on product integrity Change in assentity process for internal components		c	change of data sheet OSC-LKS-CS- 01 Check if any change in selectro- optics characteristics results in change of data sheet OSC-LKS-CS- change of data sheet OSC-LKS-CS-		Ť	-	+	+ ·	<u> </u>		-			ļ.,	-	•				H	+			
LASER DIODE		Change of assembly of additional internal components (e.g. tenses)		P in case of impact on product integrity Chance of aussier using different technology/materials	e.g. change from exidering to glaing process			• • •		-		-			-				-	•				-				Qualification effort depends on type of change.
LASER DIODE	OEC LAS-FR-14	Change of material and / or supplier of additional internal components	- P	P: in case of ingact on product integrity	e.g. change of lens material, optic properties e.g. change of submount material	c	Oteck if any change in electro- optical characteristics results in change of data when OSC-LKS-OS- 01		-	•		-	-	-	-		-	-	-	-					-			Qualification effort depends on type of change.
LASER DIODE	OECLAS-PA-15	Generation of hermedicity		new technology for hermedicity	e.g. change of welding process for metal cans. e.g. change of gluing of Yansanisova window	c	Check if any change in electro- optical characteristics results in change of data sheet OSIC-LKS-DS- 01 It in case processability is affected (e.s. issue ocidental)			-	4 -	4	4		-			-	-	4		- 4	4 -	-	4	4 4	4 -	
LASER DIODE	OEC LAS-FR-16	Change of product marking	1 1	Marking on device. E change in appearance; readability not affected. P. change of content or change of appearance of data readils code.	e.g. making of cathode;					-		0	-	-	-			-	-	т	. т			-				
LASER DIODE	OECLAS-PR-17	Change in process technique (e.g., die attach, moleting, paring, tim and firm,)		Any change in assembly process technique	e.g. change die attached fore glüng to saldeing		Air & Phone check if EQUIPMENT and other type of changes of material (OSC-LAS-A-0-05307-0820010) are abused in the process change is converted in a repeatable change is only think, applicable.											-		-								Qualification effort depends on type of change.
LASER DIDDE		Process Integrity: Tuning within specification		Variation within process specification	mig process control	c				-		-						1 -										
LASER DIODE	OEC LAS-FR-19	Change of direct material supplier with no impact on specification		Change of suppliers e.g. for lead frames, wire material, die attach, electronical components		c	Assumption that change material specification remains unchanged. Otherwise see change of staterial.		-	-		-	-		-			-	-						-			See change of national.
LASER DIODE	OEC-LAS-PA-21	Change of specified-assentity process sequence (additional and/or deletion of process disp)	٠	Addison or debtion of a process step in assentily process sequence with potentially significant impact on the product performance. In a influence on product integrity. P. influence on product integrity expected.	e.g. additional or deletion placesa cleaning process.	c	Single case assessment necessary to identify possible interactions or risk.			-					-				-									Qualification effort depends on type of change.
LASER DIODE	OECLAS-PR-21	New assentily location or transfer of assentily to a different not previously released location-toteruponstrator.		Assembly transfer or relocation. Holders transfer as well as additional site.	e.g.dad sauce/filestatingy	c	Acr St Impact on other type of changes described under PROCESS ASSEMBLY and SQUPPMENT OSC- LAS-SQ-01 Attrices LIDAR application is			-		-						-		-								Qualification effort depends on type of change.
LASER DIDDE		MCCNSE4974S	Ħ	dimension changes indirect product packing		-	aficad	1.		_	+	+	+			+		+	<u> </u>						+			
LAGER DIODE		Ourser Pracking/inhipping specification change Dry pack requirement change	1 P	dimension changes indirect product packing E small changes in dimension or appearance the number of ranks in the numbers are observing El-foliastion of dry pask requirements.	* (0 price hos (0 price + 2 mile 1 (P) Mile 1 + Mile 2		Check if OSC LAS-09-01 is also			- 1		1	1	1 1		1 1		+ :							1		1 1	
LASER DIDDE		Dry pack requirement change Ener Packing/hilipping specification change	p p	(E): To function of dry pack requirements. (P): Tightening of dry pack requirements. dimension change of direct product packing	(P) Mil. 1 → Mil. 2 e.g. 2017 pooled in large shanges e.g. shange of take/kinylayasi	-				-											- т			P				
LASER DIODE		Change of labeling	1 P	Change of labeling sits on real. It additional information no change of previous information R change is content of anevious information.	Eq. snarge or samps ay signs. [E] e.g. additional information (MaHS stamp) [P] e.g. sharige of cushamer specific information.		Check if QEC LAS-QS-81 is also affected.		-	-		-	-		-			-	-	-								
LASER DIODE		SCUPMENT					Check if OEC-LAS-09-81 is also			_	+	+				+		÷				_		+	+			
LASER DIDDE	GECLAS-EQ-01	Production from a new equipments on which was a different basic technology	PP	Change in process technique which is not already convent above. Next: Major changes affecting the product not covered by the state require also a PCN PCN required for desicated evaluatest for sensitive		٠	Check if OSC-LAS-03-01 is also affected. Corrosion stability should be assessed. At it case LDAR application is affected.			-		-	-		-			-	-	-								Qualification effort depends on type of change.
LASER DIODE	060 LAS-6Q-02	Production from a new equipment tool which uses the same basic technology (replacement equipment or extension of easting equipment pool) without change of process.		PCN required for dedicated equipment for constitue component production. (-) If sharpy decision influence the imprinting of the final probat. (-) If the constituent is the constituent of the constitu	e.g. change him single side to multi-side hander. (-) a.g. extension of existing equipment joint, already qualified. (9) e.g. reference of deficiated equipment in case basis included of the content of the content.	c				-		-			-				-					- -				Qualification effort depends on type of strange.
LASER DIODE	060 LAS-6Q-03	Change in final test equipment type that uses a different technology	1 P	Shimmani on availabil intervatives artificiated. Change of texture platform (e.g. major text program. changes, reas texture interface,). It product specification is not affected. P. onoduct association is a fell-cated. P. onoduct association is a fell-cated.	e.g. change in sed method from od to lumen e.g. change in sed method from od to lumen e.g. change of macfield measurement (LEDAR)					-		-	-		-				-	-	. т							Gage RBR / delta correlation
LASER DIODE		TEST FLOW				c				_		+-	В			- в	B B	+							+			Gase RSR / deta correlation: additional specification charts
LAGER DIODE	JELOUGH 19-01	Move of all or just of electrical value text and/or trial text to a otherwise location/libris/subcontractor OGATE				c						÷	В		5	- В		÷		<u> </u>	· T	- -		++			11.	is should be considered for Water testing
LAGER DIODE		Change of the text coverage treding process flow used by the supplier to ensure data state of complants p.e., estimation hadden of electrical measurements of their stock; relaxation had became of the coloring procedure or sampling PRIOTO DOCK / PRIOTO TAMBERSTOR (PD).	- P	e.g. Sext flowblock, reduction from three temperature reasourements to two temperature measurements, change in turns in //amin py product. i.e.; if change does not efficience the integrity of the final product. If y if impact on product integrity is anticipated.	(-) e.g. test implemented without outcomer requirement. Fig. e.g. reduction from three temperature reasourcements to two temperature reasourcements. e.g. change in burst in / run in-process.	c	Altr case LIDAR application is affected		ŀ	-	- -	Ŀ	Ŀ		•			-	-	-					-			
PD PD		Any change with impact on agreed upon technical contractual agreements	, .	Intended to be used if no other type of change if applicable but the change affects agreed technical							. .							T					T . L .	Tall	T		1.1.	
PO		Any change with impact on sechnical interface or processability/manufacturability of ductomer, which is not covered in the matrix below		contractual agreements. See processability on board level technical interface means component terminals.			Check if QSC PO-QS-01 suffering Processibility doubline assessed.			-		т			-				-	S,T								
PD		DATA SHEET			e.g. change of die substrate material.						+							+										
PO	060700941	Change of datasheer parameters/electrical specification (nin hearings, valued) and/or PulmicCC apecification		essimum pulse current) due to a technical product or process change. No technical change of product, process or test. New	e.g. PO change of disping level (sensitivity) e.g. shange of Mili. e.g. Errata				E	-		E	E		E			-	-	s	Е -			E 1			- E	
PD	OEC-PD-05-02	Correction of data wheet or issue of errada	1 1	Tomoras company of product, process or feet Man- change of the Manager of product, process or feet Man- ration is different trans intelling specification. He was a feet of the Manager of the Manager of the Manager of the Manager of of changer of the Manager of	ir e.g. change of typ, values due to new information about component behavior e.g. improved statistics. e.g. reduction of mix allowed forward voltage due to interrued statistics.			• •		-		-	-		-			-	-	-					-			
PD	OEC-PD-05-03	Specification of additional parameters		P. Ethers is a risk on supply chain where at least one additional other PCN-relevant change category will 4999.	t e.g.: adding new tested parameter t e.g.: additional temperature coefficient parameter	^		• • •		-		-	-	-	-		-	-	-	•				- -	-		•	Formalism since this is not a groduct change, only additional information. Chassification: C
PD PD	060700641	Design changes in spitale.	PP	Any device minerant changes in design: I bipout of aphtical layers. Not lockeds: Changes within design rules and design specification without all-finding specified functions, services and stability. Any change is this design function provide information lenging function layers in the services. We disclusively change is softed or electrical. We disclusively change in softed or electrical and design provides and control or electrical and design provides and control or electrical personners and reliability.	e.g. change of barrier thickness I.e.g. shange of deprog profile / Jayer thickness	c	A: In case of Avalanche Photodode (APD) and Single-Photon Avalanche Diode (SPAD)			•		-		•	-			-	н	-								
PD	060 P0 06-02	Design changes in routing/layout.	p p	Any change in drip design rasyout Provide information design layout change is optical or electrical. Not included? Changes within design rules and design specification without affecting specified functions.	e.g. reduction of band pad size e.g. shange in pixel size and IE Sation	e	A: Change of optical characteristics		-	•				•	-	- в	в р,м	-	м			- м	м •					TR right be considered for complex die bond technologies
PD	060 PD 06-03	De drok		parameters and initiability. Shrink of active area. Not included: usuing streetker/fucibe line	Typical shrink of dis.		Please check if change in process technology (GEC PD-PW-BE) is also affected.						-		-	- в	в .	1	-			1 - 1 -		1.			- -	
PO	06070-06-04	PD package (scopt lead/sine)		any change in housing thickness any change in form or dimensions	e.g. change of dimensions e.g. change of x, y, or 2 dimension of the package		Check if OSC-PO-08-01 is affected which leads to a change of the electrocytic parameters or databases.									• в	8 D		D		L T	. р	ь .		5	5 5	4 .	
PO	060700666	Design of leadhane		any change of leadbane / extremunt dimensions any change of outer dimensions	e.g. change in teadframe / carrier dimensions in xy, or 2 direction e.g. change inner design of the leadfeame not affecting the eto performance & reliability of the		At it case of LENR appliaction is affected. Check if occupance on is affected which leads to a change of the electrospic parameters or						-			• B	B D				• т	2 -				5 5	4 .	
90		PROCESS - WAPER PRODUCTION	+	1	desire.		UKI KUMIK.			-	+	+				+		÷						H	+			<u> </u>
PD	GEC-PG-PW-01	News! change of water substitute or carrier material	PP	Newwafer substrate material.	e.g. offenent water material to currently released exaterial (change from Supplier to Silicon)	c	At its case of LIDAR application is			Р		Р	-		-			-	Р	•		- Р	р р	P				
PD	GEC PD-PW-02	Walfer diameter		change of water diameter resulting in equipment and process changes	eg en e	c	infection. Typically this type of change affects other changes i.e. equipment/process technology—they resed to be saintfeed in addition. Clinick of OSC-PD-056-01 is affected which leads to a change of the electrologic parameters or	• • •	1	•		-	-	•	-	- -		-	-	•	• -	-		P				
PD	GEO PO-PW-03	New final water trickness	p p	Change in final water trickness	e.g. change in faul chipide trickness	c	Check if OSC-PO-CS-01 is affected which leads to a change of the electrocytic parameters or contributions.		-	Р			-	•	-	- в	в •	-	-	-	•			P				
PD				Change in electrically active doping / implantation element resulting in a new technology.	e.g. change from the to C as dopare	c		c			- с		-	•	-				-	-								
PO		Change of stacking		change in layer sequence or thickness	e.g. sharpe of infation by with three between v- and p- material e.g. sharpe of microbres layer					٠			-	•	-		-	-	*	-								
PD PD		New I change of metallization (specifically drip framelide) New I change of metallization (specifically drip backside)	P P	Change in metallization of bondpads, material, layer blokkness. Change of bottom layer of die (between die and saditame/carrier). Change is process, material, or dimensions ecososary.	e.g. change in bond pad metalization thickness e.g. change from Au to Aurilia	c	A: it case of change to Auminium contribution	N		•								-	M. D,M	•	ом -		M D,N					
PO		Change in process technique (e.g. significant process changes the lithography, etch, oxide deposition, die back surface preparationbackgrint,)	- Р	Change from set to dry extring, change from horizonta to vertical over for calculors, change from contact timo into experi timo,	e.g. change floorwer eich to dry eich e.g. change floorisser cutting (sawing) to plasma cutting (sawing) e.g. change floor contact litho to stepper litho	c	Bit change from CVD dep to sputter			-								-	-	-								Qualification effort depends on type of change.
PO PO	GEO PO PW 10	Process imaginy: Yuning within specification Change of resterial supplier with no impact on agreed specifications	- P	Variation within process specification. Change of water supplier. Change of supplier for chemicals needed for water production.	e.g. process control P-e.g. change of water supplier.	c	Change of water supplier please check if OSC-PO-PW-01 is affected.																					Qualification effort desends on trop of change
PO	0ECP0-PW-11	Change of specified wafer process sequence (debtion antior additional process step)	- P	Any change which is not covered by another type of change. Risk is to be assessed.	e.g. additional cleaning process in water production	c				-						- 1												Chalification effort depends on type of change. Chalification effort depends on type of change. PRAP has to be updated.
PO	060 P0-PW-12	Change in die stading or passivation	p p	Change in material, thickness, and process for coating and passivation	e.g. change from SiCO to SIND e.g. shange of not refinitive scaling e.g. shange of microlresityre (Austinobe Photostode (MPO)	c	In case-optical characteristics of anti-influsion coating (ARC) are changed				. Р				-	. Р	р .		Р			. р	рр	P				
PO	QECPOPW13	New worke production function or transfer of water production to a different not previously released trustion/viales/autoritractor		Newwater production location or transfer of water production with possible additional changes.	y negor-musin-haldanihe Disale (IPRO))	c	A or B Impact on other type of changes cleanized under PROCESE - WAYER PROCECTION and ECOMPMENT categories of the DROMA A in case of LEDAR application is														a .							
PD		MANUE COR. CONT. NEW PROCESSES Charges not convered in Dissection shall be have	niled according	h seder "Posen - Male Postuder"			affected.			_	+	\vdash				+		+					4	#	+	Щ	Н.	
PD	060708061	New! change of front side metallization	PP	Change in bondpads, nuterial, pad pitch, surface changes, layer flickness	e.g. change trom Au to Au alby e.g. change in over pad metalization		A: It case of chip-on-board technology	N		•		•	-	•			•		•		•	•	•	M, B M	в -			Reasonable package type for reliability testing to be aligned between supplier and customer

PO	060704043	New! change of backside metallization	p	P Change of bottom layer of die (between die and leachtamectanier). Change in process, material, or dissensions.	e.g. change from Au to Au alloy		Check if OSC-PO-06-01 is affected which leads to a change of the electrocytic parameters or clastifuctions. At it case of chip-on-board technology.	w		•		•	•	-						•		•				•	D, M	D, M -	-			Sustainer application needs to be checked-due to potential yettem voltage differences basecusable package-type for reliability testing to be aligned etseen supplier and customer
PD	060 PD 80-63	Change of water setup or number of dies on water.		P to only additional number of chips P change in epacing between chips and form of water	e.g. information change for pick & place machine.	٠	At its case of chip-on-board technology		÷	-	-		-			-	-		-	-	-		-		-	-			-		- 1	biasonable package type for reliability testing to be aligned elseen supplier and customer
PD	CECPDIDO	New Snat water trickness	P	Changes in final Chip height (including carrier); very tare and usually contained with a national change (change of carrier national)			Check if OSC-PO-CG-O1 is affected which leads to a change of the electropid parameters or classifications. At it case of chip-on-board technology		-	Р	-			-		-	•	вв		-	-				-	- 1	р	Р.	-			basionable package type for reliability testing to be aligned estenen supplier and customer
PD	OEC/PD-BD-05	Change in die stading or passivation	p	P Change in material, thickness, and process for coating and passivation	e.g. change from 3/02 to 3/03 e.g. change ann-eductive coating e.g. change of micro tens toyer (APID, SPAD)		Check if OSC-PO-CG-01 is affected which leads to a change of the electrooptic parameters or claributions. At it case of chip-on-board terrooptics.	e e		•		P		-				РР	-		Р	•	-		Р	Р	р	р.	-			brasonable peckage type for reliability testing to be aligned letween supplier and customer
PD		PROCEES - ASSESSELY					soroog												1													
PD	060PDPA41	Change of leadflame/submount base naterial	P	P Newleadframe/submount material (new in composition)	e.g. change from copper alloy to bare copper		Check if QEC-PO-09-01 is affected which leads to a change of the electrooptic parameters or distributions.		-	٠	-	-	٠	-	Р .	-	-		•	3	A	٠	P,1	• 1	Α.	Α .			-		- 88	Optanation should be provided in case FOS test is not applicable legacing applicable materials please refer to the Whisker tandand. 4th secundants be considered for automotive extension.
PD	0E0 PD PA-02	Change of leadthame/submount finishing naterial (internal)	P	Change of surface material of de attach pad and second bond area (e.g. influence in adhesion to mold compound, sedge bond reliability)					-	٠	-	-	٠	-	Р .	-	-		٠	-	Α	•	P,1	•	A	Α	gP -		-			401 les should be considered for automative eithersor applications, should be provided in case HDS test is not applicable.
PD	OEC/PDPA43	Change of lead and heat slag pixting material-pixting thickness (external)		Change in material and process technique for final pin smithation (e.g. pure 16). Herein packing. P processably and reliability both band few can be writed by greater, cars. Cleantication depends on second of Chantel. P State die or die to subdistate.	e.g. change in heat slag stack e.g. change from in into NPAIAu e.g. change of layer trickness			M	-	к		-	•		Р .	-	1		-	-	Α	•	P,1		. A	A			-		- 1	Splanation should be provided in case HTS test is not applicable to garding applicable materials please refer to the Whisker bandand.
PD	OEC-PD-PAGE	Surep Misserial / Metal System (Internal)		P Stack die or die to substrate	e.g. change to Po-free material					•	-	•	•	-	•	-	-			1 - 1	w	•			w	w			1 - 1			
PD	OEO PD PAGS	De attach resterial		etc). Thermal management must be respected.	e.g. change of Ag glue to Au-glue;				-	•		•	•			-	-			-	N	•	•		Q	Q .		- N	N	N -	1 - 1	
PD	OEC/PD/PAGE	Change of wire bonding	P	P Staterial, diameter, change in bonding diagram and / or change in process resulting in a new technology.	e.g. change from Au to Cu material: e.g. change from 25 jm 10 25 jm dameter e.g. change from sign to double bond e.g. change from stich bond to stich on ball bond.				-	P,D	-	•		-	•	-	-		-	-	-	٠	-		P,D	P,D	-	- D, @	gP D, gP	D, @P -	- 1	its audt for nutwist change with inpact on bondprocess (s. iom Au ts Cu) recommended.
PD	GEOPO-PAGE	Change in material for extromponents (sectuding photodode/transistor chip & package misred being with impact on agreed	P	P Change of sub-component supplier using different technology/materials	e.g. using different NTC dode in technology and material than previously		Check if GEC-PO-69-61 is also affected.		-		-	-	-	-			-		-	-	-		-		-				/ - 1		- 1	Qualification effort depends on type of change.
PD	OEC-PD-PA-08	Die Overcout / Underfüll	-	Supporting layers for complex packages like flip-chip. P -: No change in product integrity P change can influence the integrity of final product.	P. e.g. change of underfit with change of thermal resistance		Check if QSC-PQ-QS-01 is also affected.	. • P	-	ρ.	-	•	٠	-	•	-	-		U	-	-	•	U		Р	р .		. Р	Р	р .	-	
PD	OECPDPAGE	Change of moid compound encapsulation leading material	,	Change of mild compound, encapsulation, or easing restented might be affected optical function in case of package restented effect (e.g. snowleg). Component assembly and board costing has to be assessed. Milk, eligit be chanced.	e.g. PPA rold compound	*	Check if QSC-PO-09-01 is also affected.		-	٠		•	-		•	-	D		-	3	Р	٠	Р	т .	Р	р		- D, @	ge D, ge	D, @P 4	-	
PD	OEC/PDPA-10	Change of product making		solet be channed. Saving on device. E change in appearance, needably not affected. P change if content or change of appearance of data static code.	e.g. marking of cathode;	٠			-	-	-	-	0	-		-	-		-	-	-	т	-	т -	-	-	- -		1-			
PD	060/PD/PA-11	Ownge in princess technique (e.g., die alliach, molding, plating, tim and fam,)		P Any change in assembly process technique	e.g. change die attached from gluing to exidering		A or B. Please check if EQUIPMENT and other type of changes of material (DEC PD PA decent Dates), an affected. If the process change is covered in a separate change ID only this is applicable.		-	-	-	-	-	-		-			-	-	-	-	-		-	-	-		-		- 4	builfication effort depends on type of change.
PD	060 PD PA-12	Process Megity: Turing withis specification.	-	P Variation within process specification	e.g. process control	c				-	-	-	-	-		-	-		-	-	-		-		-				4 -			
PD	060 PD PA-13	Change of direct material supplier with no impact on specification.	-	P Change of suppliers e.g. for lead flames, wire material, de attacts, electronical components	Change of suppliers e.g. for lead frames, wire material, SSD-dode	e	Assumption that change malerial specification remains unchanged. Otherwise see shange of malerial.		-	-		-	-	-		-	-		-	-	-	-	-		-		-		-			ise change of nativisis.
PD	OEC/PDPA16	Change of specifinducementary process sequence (additional and/or detertion of process step)	•	Addition or deletion of a process step in assembly process sequence with potentially significant impact on the product performance. It no influence on product integrity. Profluence on product integrity and influence on scoolact integrity.	e.g. additional or deletion plasma cleaning process		Single case assessment necessary to should possible interactions or not. Acr St. Impact on other type of		-	•	•		•	•		-	-		-	-	-	-			-	-			1		- 0	Qualification effort depends on type of change.
PD	OEC/PD/PA15	New assembly limition or limite of assembly to a different out personally retrained limitary literature constitution.	P	P Assembly transfer or relocation. Includes transfer as well as additional sits.	e.g. dual source / fels strategy	c	Acr & Impact on other type of changes described under PROCESS ASSSMELY and SQUPMENT OSC- PO-50,411 A In case LICAR application is affected.	• • •	-			+	-	-		-	-		-	-	•		-	- -	-	- 1			-		- 4	builfication effort depends on type of change.
PD		MCKNOSHPRING																	-											_		
PD	060707941	Outer Fastinghripping specification shange	1	P t snat changes indirect product packing P t snat changes in dimension or appearance	mg passeless				-		-	-	-	-		-	-		-	-	-		-						/ -		1 - 1	
PD	06CPD-P9-02	Dry pack requirement change		P (Filtering of dry park requirements P) Tylering of dry park requirements	(I); MSL 2 à MSL 1 (P); MSL 1 à MSL 2	٠	Check if ORC PD 08 41 is also affected.		-		-	-	-	-		-	-		-	-	-	-	-		-	-	-					
PD	060/99/943	bree Paskingshipping specification change		P dimension change of direct product packing	e.g. XXIII pooled in lape changes									-		1	1			1				т -	+ -		р	Р.	4	خلانے	1	
PD PD	OEC/PD/PS-04	Change of Infanting EQUIPMENT		Change of tabeling also an real: E additional information no change of previous information E change in content of analysis information	(F) = g. shallound information (Fid-III stamp) (F) = g. shange of container specific internation	٠	Check if OBC PD OB et is also affected.	• •	-	-	-	-	-	-			-		-		-	-		- -	1 -	-			1		Ų	
PD	060/904041	Production from a new equipment/find which uses a different basic behindings	P	Diange in process technique which is not directly covered above. Male Major changes affecting the product not covered by th falls require above PCH.	e.g change from single water to ballsh process. e.g. over pail metablishin. e.g. dandar culling (newhereal) to laser culling)	٠	Check if GEC-PO-DS-01 is also affected. Comparison stability should be assessed.	• • •	-	-	-	-	-	-		-	-		-	-	-	-	-		-	-	- -		-		- 4	auditation effort depends on type of change.
PD	060906040	Production have a new equipment/find which uses the same basic technology (replacement equipment or enhancing of according equipment pool) without shange of process.	-	PCN required for declinated equipment for sensitive immunities described production. p. (-) if shape does not influence the ingesting of the final product. p. if impact are product intergrity is entirelysted.	e.g. change him single site in multi-site hander. (-) e.g. extension of existing equipment past, direally qualified. (9) e.g. extension of dedicated equipment in case lasts belonsingly till need to be proson.	c		• •	-			-	-	-			-		-	-	-		-						-		- 4	qualification effort depends on type of shange.
PD	060/90-60-63	Change is find feel equipment type that uses a different leabhology		Diange of beder platfore (e.g. major bed program changes ever feeter interface,) § product specification is not athleted P product specification is athleted	e.g. change illumination methods / spectrum				-	-	-	-	-	-	-		-		-	-	-	-	-	т .		-		•	-		• 4	Dage RBR / delta correlation
PD	OEC-PD-TF-01	TEST FLOW Since of all or part of electrical wade lend and/or final lend to a different location-toler-subscripts/lend	,	P Yester transfer or relocation.	e.g. Dust source stategy	c	Bt to case of bars die delivery			•	- 1	В		-	в -		1 - 1	в в	В	1 - 1	- 1		- 1	т -	T	- 1	1.1		1.1	- 1	. 1	lage R&R / deta correlation; additional specification check is should be considered for Water testing
PD		GEARM		· · · · · · · · · · · · · · · · · · ·																				_				_				
PD	050P0-Q9-01	Chappe of the test connectatively prices has east by the explicit to ensure data sheet emplace by a discontinuabilitie of enclosed measurement feet the block established answered of meeting procedure or sampling).	-	e.g. sext flowblock, reduction from three temperature necessariements to the temperature measurements, change in two in finance specials, (e) if change does not officeroe the integrity of the fina product. PS if impact on product integrity is anticipated.	(c) 4.g. Set implemented althout outcomer requirement. (***)** 9. a. in reduction from three temperature measurements to two temperature measurements to two temperature measurements, e.g. change in burs in / run in process.	c	A: In case LEDAR application is adecided		-	-			-	-		-	-		-	-	-	-	-	-	-	-			-		•	
	Texts, which sh	hould be considered for the appropriate process change.					ı									١.				1.1					1.							
									Ė																							
		hould be considered for the appropriate process change after a	lection	of condition table.					-				-			-	I - T			·]				- -		-			1 - 1		1 · I	
	Suppliers perfo	ormed tests (mark with an 'X' for done or 'G' for generic)																														
	Bassas for	ception of tests and/or usage of generic data:																							_			-	_		_	
	reduced for exc	September of the Andrew State of Generic Cases:																													للسك	

Г	_	Not required.
г	_	Information Note required.
г		PCN required.

Α.	Not for Ap plated devices applicable (Ap intended to fall for this test)	
	Non-Enror Coated Contras retu	
M		
0	Close If marking technology changes	
	Central Circumit Na in selfantant	
T	Only if Stoard Reliability is affected	
v	Pelu for non-harmatir Assiras	
w	Challe Make of commains in increasion	
Y	Only for layer technology	
Z		
	Only Vidata should narrameters are affected.	
	Only if outer dimensions are citized	

Signature: Date:		ł														Dev	ice eva	luation	,									_					
PCN number:		-					_					N	IATERIAL	PERFOR	MANCE TEST					Revision -	Septemb	er 14, 20	117			_	_	_		addition:	nal to		
		1			valuation level A / B / C		14, 2017		or biased HWST		yding rage Life walng Life		me years								2					Fo Zopos				AFC.01	a map pad.		
_	Assessment of impact regarding following aspects -contacting agreements -control integrating of harding-pieces sability/mendacturability of costomer -term, fit, furction, quality performance, resability	Potentia impacti	Understanding of semiconductors experts	Examples to explain	at level	Further applicable conditions	ydusor audion sie mekk tevision September		Temperature Humidity Blas	Autoclave or Unbiased HMS Temperature Cyding	Power Temperature Cyding Hgh Temperature Storage I Hgh Temperature Operatin	Early Life Februs Plate	rente brandenske Data Para Operational Life Wire Bond Shear	WintBondPu1 Solderablity	Physical Dimensions Solder Ball Shear mailtreamby	Control CSAM	Electronic Discharge Human Body Model Electronic Discharge Changel Device Model	dh upper	Electrical Distribution	Guachriaton	Deciromagne to Computibility	Soft Error Parks Hermatic Package Test	Package Drop	Lid Tonque Die Stear	Informal Water Vapor Board Level Period By	Low Temperature Stringel. Start Up and TemperatureS	MCMD pp Test	DelitrockVerryshorrer	Acoustic Microscopy	Wisher test (80 00008 T240, JEDEC JES (90 40008 T240, JEDEC JES)	Parender Arrayan Computation of camerant in the christ of railory, electrical of the	Re	emarks
а	Type of change	No Yo			A Application level B Board evel C Component level		is prevalent		92	9 2	PTC 4TSL 4TOL	B.R.	MBS	wap SO	Oc 881 -	GWY	MOS	2	0 2	CHARR	DWC	MECH	DROP	.T	WV SLR	.TBL. STEP	WOM DROP	DIR	100				
	ANY Any change with impact on agreed upon technical contractual agreements		Intended to be used if no other type of change is applicable but the change affects agreed technical	1			58 Z	58		A3 A4	AS AS B1	82	B3 C1	C2 C	C4 C5 C		E2 E3	E4	E5 E	5 E7	E8 :	E9 G1-4	G5	G8 G7	G8 H	1 H2 H3	H4 H	S HS	Н7		-		-
	Any change with impact on processability/manufacturability at customer, which is not covered in the matrix below.		contract all assessments Any change which is not covered in the matrix below, but tisk assessment at customer is recommended.		В				-																	1.1.		+			_		_
			+							<u></u>									_		_			4		#	#	+	#	#	_		
MCM-DS-01	Change of data sheet parameters/electrical specification (nin./max./kgc. values) and/or ACDC specification	P P	Update of data sheet because of technical change of the product. No technical change of renduct, process or test	f e.g. recommendations for pull-up/pull-down or NC pins, MSL	A			-	-			-						-			-		-				11		1				
MCM-DS-02	Correction of data sheet / errats		Update of data sheet because of sochrical change of the product. No technical change of product, process or lest. Now december of behavior which was not specified below or which is different ben intell specified below or which is different ben intell specified soches or which is different ben intell specified soches (mich in the product of the product of the product of the product of the product of the product of the product of the face of the face of the face of the face of the face	e.g. Errota	A			4	-			-	- -			- -			-				-			-	-		-	-	-		
MCM-DS-03	Specification of additional parameters	1 1	Assessment in anotice stone sensined: Description of a new not prescularly covered parameter. No technical change of the product, dip Catellion of new parameter which was not documented before. By: Noticenous as single change. Only in combination with other changes.	(R) e.g. adding new tested parameter.	A				-			-				- -		-	-		-		-				-		-	-	-		
	DESIGN	Ħ		<u> </u>						Ť																Ť	Ħ	Ŧ	Ħ		一		
MCM-DE-01	Filmwater modification	1 P	Integrated nothwave by design or memory as defined by applier. If, Firmwave modification or update without effect of functional performance at the customer (bug fix). If Firmwave modification or update with effect of functional or reliability performance at the customer.	(it) e.g. addition of Firmware opportunities (P); e.g. bug fix with impact on functional performance	A			٠	-			-						-	-		-		-						-	-	-		
MCM-0E-02	Change that adds or subtracts sub-components from the module BOM	P		e.g. addition of passive elements in filter circuit	A			٠	e•		e• e• •	٠						٠	•		•	M @ •.	. d	- @F			-		-	-	٠		
	Substate change affecting module schematic (Changes to the internal dimensions and for schematica) PROCESS -ASSEMBLY-MATERIALS	P P	Design change and routing Change in substrate, leadthares dimensions which has impact to the specified electrical parameter ac- date sheet or specification (e.g. heat sink, pin dimensions, disp paddle sines, Not included: Variation within specification.		A	if the number of layer will be changed see also PA-09		٠	e•	• •	@к . •	٠	- @•	e• -				•	•		•	м -	-				- G	9•	-	-	•		
MCM-PA-01		Ι.Ι.	Change from an AEC Qualified sub-component to a Non-AEC Qualified sub-component or		A				.	Л.		1.				TI								. @F	П	\mathbf{T}		3 . 0 .					_
MCM-PA-01	Replacement of any sub-component by a Non-ASC qualified sub-component	, ,	Change from an ABC Qualified sub-component to a Non-ABC Qualified sub-component or Change from a Non-ABC Qualified sub-component to another Non-ABC Qualified sub-component		•			•	-	٠.			•									nn (g.+,t	D 66.	- lgr		41.	. 6		8.		4		
MCM-PA-02	Replacement of any sub-component by an ASC qualified sub-component	P P	Change from one AEC Qualified sub-component to sonbar AEC Qualified sub-component to sonbar AEC Qualified sub-component Durage from a Nov-AEC Qualified sub-component e.g., with impact on electrical robustness (SSD, letch pr.) — electrical tractionality, set or component properties of the properties of the properties of properties of the properties of the properties of properties of the properties of the properties of properties defined to the properties of properties of the properties of properties of the properties of properties of properties properties of properties of properties properties of properties of properties		4	Requires additional evidence that new sub-component is AEC qualified		٠	-			-	•			- -		٠	•		•	M @*,i	D @•	. @F			. @	a• @•	@•	-	•		
MCM-PA-03	Replacement of any sub-component by an AEC qualified sub-component Critical characleristics of sub-component are <u>next</u> effected	1 P	Critical characteristics are those which have the greatest effection form, 5t, function, yield, and/or reliability. Use of SPC controls and 190% testing are		с	Requires additional evidence that new sub-component is AEC qualified					e		e• ·				e• e•		e• e		. e	0.•@ M g	D @•	. @ F		/	- e	g • @ •		- 1			
	Change within a sub-component that has been requalified Critical characteristics of sub-component are affected	Н.	malability. Use of SPC controls and 900% testing are common. Ordical characteristics are those which have the greatest effect on form, 8t function, jelds, anotice reliability, time of SPC controls and 900% testing are common. Other interesting and section and section are section and common.		A											+								- @F		+	+	+	+	+			_
			reliability. Use of SPC controls and 100% testing are common. Orisical characteristics are those which have the greatest effect on form, fit, function, yield, and/or reliability. Use of SPC controls and 100% testing are		c	component		_	-	+		+				+		+	-+		-	_	+	_		#	H	H	H				_
MCM-PA-05	Change within a sub-component that has been requalified Critical characteristics of sub-component are net affected	1 P	common	•	С	active, passive component) for qualification of the changed sub- component		٠	-		@	- 1	e• ·				e• e•	. 6.	• 6	. 6.	• @	0,+@ M g	D -	- @F		++-	1	#	<u> </u>	4	٠		
MCM-PA-07	Change to the processes used in module assembly (e.g., pick 8 place, die attach, bonding, relfow, encapsulation, singulation, die overcost, underfill, die preparation, die clean)	. P	(r) I the change in process schoology can influence the integrity of the final product.	(-j: e.g. tuning within process specification	с		•	-	٠	- •	@к - @		- •	•	• •	•			@н	@•	-		-			11	- 6	9• -	1		1		
MCM-PA-08	Process integrity turing within specification	- P	(P): If impact on product specification is anticipated.		с			-	-			-						-	-		-		-					Ŀ		•			
MCMPA-09	Change to maintais used in module assembly (e.g., adhesive, underfil, encapsulate, solder, epong, bump malerial, die attach-malerial, bord vier, die overcost, substrate, lauoffame base malerial)	P	Change of used material (e.g. bump material, die attach material, soft adder, epoxy, etc.) Change of bond wire material, diameter, change in bonding diagram	e.g. Stack die or die to substrate (flip chip) e.g. change to Pi-fine material e.g. change of copper pillars e.g. change from Sninto NIP dilvu e.g. in number of layers or thickness of the substrate	с	Brouting is affected see also DE-O3 B: Impact on thermomechanical stress caused by mismatch of mold compand, dissonneiting technology and carrier is articipated B: external lead finishing material is affected		٠	٠		@ K @ • @	@ E		٠.				-	•	@•	-		-				· @	9•	-		•		
MCM-PA-10	Change of direct material supplier	- P	Change of suppliers for direct materials which are used in assembly process (BOM). (-): E change does not influence the integrity of the final product. (P): If impact on product integrity is anticipated.	(-j: e.g. change of wire material supplier. (P)F. e.g. change to new mold compound supplier e.g. additional leadstame supplier with specific leadstame manufacturing technology e.g. additional or new substrate supplier	с	Please check if material is changed!			-			-						-	-	-	-		-			- -	-		-	-		change of material.	
MCM-PA-11	Change to assembly location (blow all or parts of production to a different assembly site)			e.g. dual source / fab strategy	с	A or B: Impact on other type of changes described under PROCESS ASSEMBLY and SEM-80-01. Incase of Cuwire product please consider AEC-0006.			•		@к - •	•	-		• @T •			-	•	@•	-		-				e	g •	-	@•	AEC proc the i	sker tests have to be done on monitoring 3-Q100. "For broad changes that involve sesses), refer to section A1.3 of this appr selection of worst-case test vehicles to co	, basis! i multiple endix and cover all th
MCM-PA-12	Change of product marking PACNING/SHIPPING		Change of marking on device and / or change in process resulting in a new technology. (i): If change does not inflamos the integrity of the final product. (P): If impact on product integrity is articipated.	(R: e.g. change of appearance (additional marking) (P): e.g. change from inked marking to laser marking e.g. marking of pin 1	В			-				-	- -	- в		- -		-	-		-	- -	-					- -	-	-	-		
MCM-PS-01		P P	Packing/shipping specification change.									ы	- [-]	- [-			- -		- [- [-]	- [1-1		- -	1-1-	T.	45		4	-		
	Dry pack requirements change	1 P		(I; MSL 3 → MSL 1 (P); MSL 1 → MSL 3		Please check if data sheet is affected (MCM-DS-01 or MCM-DS- 02).												-	-		-		-					4	-	-	-		
MCM-PS-04	Change of carrier (hay, real) Change of labelling	1 9	Change of carrier (tray, reel) Change of labelling also on reel. (It: Change of material label without impact on barcode. (P): Changes of material label information which effects of the procession of craticoper.	(i) e.g. additional information (Roll-G stamp) (P) e.g. change of defined nomenclature for data processing	В				-			-						-			-		-						-	-	-		
MCMEOns	EQUIPMENT Production from a new equipment/loof which uses a different basic technology or which due to its unique from or function can be expected to influence the integrity of the final product.	p p	Change in process technique.	Check which other type of change is applicable due	A	Check which other type of change is applicable due to this			.				- -					1.1		. @•									Ħ	寸	一		_
		ĦŤ	PCN required for dedicated equipment for sensitive	to this equipment change.		equipment change.														-					Ħ	+	H		+		7		
MCM-EQ-02	Production from a new equipment fool which uses the same basic technology (replacement equipment or extension of existing equipment pool) without change of process.	- Р	PCN required for dedicated equipment for sensitive component production. (-)-: F change does not influence the integrity of the final product. (P): if impact on product integrity is anticipated.	(P): e.g. extension of dedicated equipment in case basic technology still need to be proven	с				-			-						-			-	-	-	-					-				
MCM-EQ-03	Change to testing platform (Change in final test equipment type leading to a different test concept)	p p	Change of tester platform with differences in HW or SW that makes a change in test concept necessary	e. g. change tester equipment from LTX to Teradune	с													-		@ •	-				I . I .	4.			4 . 1		• Gage	e R&R / delta correlation	

MCM-QG-01	Copy of the basic consequence of the second basic particles of the second basic control of the second basic contro	The second secon
	Tests, which should be considered for the appropriate process change.	
	Tests, which should be considered for the appropriate process change after selection of condition table.	
	Suppliers performed tests (mark with an 'X' for done or 'O' for generic)	
	Reason for exception of tests and/or usage of generic data:	

Not received
 Information Note received.
 P PCN required.

A date or ** indicate the performance of that dream had shread be considered for the appropriate process programs and differently by PCE.

A discrepancy of the performance of the perfo

		n: 3) Max Mustermann																									
	Signatur														Devic	e evaluat	ion										
	PCN numbe	c											MATERIAL	PERFORMAN	ICE TEST RES	SULTS (on the	e basis of AE	C-Q200 Revis	ion D)						ad	ditional to AEC- Q200	<u> </u>
Mark change with an "x"			Form associated by ZVEL - Revision 5.0 -	Desperature 2021	Evaluation level A / B / C		(to sale chook)	Q.														5				(SCOOT) hanged device stribul on	
		Assessment of impact regarding following aspects - contractual agreements - inchrisical infurface of handling-joroceasability/manufacturability of customer - form, fit, function, quality performance, reliability	Understanding of component experts	Examples to explain	A: Application level B: Boardlevel C: Boardlevel "Not retirement level "Not retirement for qualification matrix.	Further applicable conditions	out and by data or sasting	A Temp Spoure (Strong	stactive Physical Analysis	status Pasistance seed Hamilday	erational Life	ysical Dimension reinal Breegh (Leaded)	sistance to Sockerts chartost Shock	ration sistems to Soldering Heal	errad Shock. chrostad o Discharge (BSC	ideratility off od Characterization	emends By and Plex	reind Breegh (BAD) are Lood Test	me Potandance	tation Life rgeVd tage	LSpray	cht cal Terrebert Conduct	At Carrest Durability	d d'ulte Mode Verfication epistement	al Dump Endeance	C 6009-1240, 400-bra meter-Antysis: riperson of curest with or moleculating electrical of	Romarka
Selection of	10	Type of change	Impact?		A. Agato B. Baard C. Comp		EC.C	2 2	4 8	4 7 8	5 G	£ £	2 2	5 & 14 11	£ 5	8 5	2 2	2 B	2	2 3	20	a n	2	S 2	3 \$	8 285	
NETWORKS & RESISTORS		NETWORKS & RESISTORS			8		38 % 08	>																			
NETWORKS & RESISTORS	PAS-RES-AN-01	ANY Any change with impact on agreed upon technical contractual agreements	P P Intended to be used if no other type of cha	nge Net selected for technical availables														T . T .	Τ.Τ		T . T		T . T		T . T .		
NETWORKS & RESISTORS	PAS-RES-AN-02	Any change with impact on processability/manufacturability at customer, which is not covered in the matrix before		Technical interface means component terminals.	В																				- 6	D• -	
NETWORKS & RESISTORS		DATA SUPET																		_						_	
NETWORKS & RESISTORS NETWORKS & RESISTORS	PAS-RES-05-01	The change of the parameters which can be perforable (risk) man hyp. where) and in ACCC with the change of the parameters which can be perforable in the change of the perforable in	New description of behavior which was not specified before or which is different from initial specification. Please indicate clearly, that infoncis contains the type of change! Assessment in application required!	e.g. data sheet correction because of new information about component behavior ms	A	Raic assessment depending on change for each application																	-				
NETWORKS & RESISTORS	PAS-RES-DS-03	Specification of additional parameters MATERIAL	Disscription of a new not previously covere parameter. No technical change of the product. I P(it no inflamon P(Risk assessment depending on change such application to provide evidence of additional parameters (staf. evaluation)	d e.g. adding new (lested) parameter.	*															- -	-	- -	-				
NETWORKS & PESISTORS			P P Change of link / Wire material	e.g. resistor paste, NCr, resistor wire, bulk metals	С						• -	- W			• F	- B		• -	R		-		- 1			- @•	
NETWORKS A PESISTORS	PAS-RES-MA-02		P Change of Ink / Wire material	e.g. AgPd paste, Ag paste, lead sine , NCr for si- termination	ide B						• -	- w			• F	- B			R		-		-			- @•	
NETWORKS & PESISTORS	PAS-RES-MA-03	Change of material composition - Packagel Mold	P P Charge of Package	e.g. for chip res.: final costing, epoxy	В	Consider potential change of CTE of material		•		• •			•	•				•	R		-		-				Check whether AOI at Ser 1 can be affected.
	PAS-RES-MA-04	Change of malerial composition - Passivation	P P Change of Passivation /Inner protection		с	B: in case geometric changes of resistor design due risk of electro chemical reaction (e.g. corrosion, electro			• -		• -		• -		• -		• -		R		N		-				
NETWORKS & RESISTORS	PAS-RES-MA-05	Change of material composition - Substrate material	P P Change of substrate material substrate material substrate material class (AZXX), etc.) will no be channed only downstead tall he channed	at .	с	maraoni										• B			-		-		-			- @•	
NETWORKS & RESISTORS	PAS-RES-MA-06	Change of supplier of material	P Change to a new or additional material supplied component manufacturer.	pler e.g. for 2nd source purpose	с						-					- B			R		N		-			- @•	Assumption material specification remains unchanged. Otherwise see
NETWORKS & RESISTORS NETWORKS & RESISTORS		DESIGN																									chance of material.
NETWORKS & RESISTORS		Changes of terrination, surface finish, shape, color, appearance or dimension shucture			В	B: in case geometric changes of resistor	•				•	•		•		•		· ·			-					+-	
NETWORKS & RESISTORS	PAS-RES-DE-02	Changes of inner construction - Passivation	- P Change of passivation/Inner protection	e.g. change of glass, laquer, eposy,	С	B: in case geometric changes of restallor design due risk of electro chemical reaction (e.g. corrosion, electro migration)		• •	•	• •	•		•		•		•		R		N		-				
NETWORKS & RESISTORS	DATESTON OF	PROCESS	- P Change of ink fire process	e.g. change of firing profile								- R				- B		т т					П			_	
NETWORKS & RESISTORS				e.g. change of firing profile e.g. change from normal atmospher to nitrogen atmospher	c						•								R					1 1		- @• - @•	
NETWORKS & RESISTORS	PAS-RES-PR-03 PAS-RES-PR-04	Changes in process technology or manufacturing methods - Trim Changes in process technology or manufacturing methods - Lead Form	P Change of ink print process P Change of trin process P Change of lead form process	e.g. change from mill trimming to laser trimming	C B						:		: :			- B					- N					- @•	
NE INCIOS A NESISTORS	PAS-RES-PR-05	Changes in process technology or manufacturing methods - Termination Attach	P Change of termination attach process	e.g. change from bending to punching e.g. chip resistors: electroplating process e.g. selding of leads for through put devices.	В											- B	1 1	1 -	-		N		-			- @•	
NETWORKS & RESISTORS	PAS-RES-PR-06	Changes in process technology or manufacturing methods - Marking	- P Change of marking process	e.g. change from tempon printing to laser marking	В								• -								-		-				
NETWORKS & RESISTORS NETWORKS & RESISTORS	PAS-RES-PR-07 PAS-RES-PR-08	Changes in process technology or manufacturing methods - Molding Process integrity: tuning within specification	P Change of molding process P Variation within process specification.	e.g. process control	B C			• •			: :			•			• •		R -		-		-			-	
NETWORKS & RESISTORS	PAS-RES-PN-01	Process inlegify: having within specification PACKING / SNRPPING - NEW MATERIAL, CRITICAL DIMENSIONS Packing / shipping specification change (bosening of tolerances)	B D Channe of parking specification	e.c. number of pieces on reel.	В																						
AL INCOCA PLACE COCA	PAS-RES-PN-02	Dry pack requirements change	Change of dry pack requirements. I P (8: Releasion of dry pack requirements (P): Tightening of dry pack requirements	e.g. change in dry pack assurance (HC, MEB) (8: MSL 3 -> MSL 1 (F): MSL 1 -> MSL 3	В																-		-				
NETWORKS & RESISTORS	pasaes eum	Change of carrier (tray, reel)	(P): Tightening of dry pack requirements P P Change of carrier	(F): MSL 1 → MSL 3 e.g. change by material e.g. change by geometry.	В												.								H. H.		
NETWORKS & RESISTORS		PACKING / SHIPPING - VISUAL INSPECTION		e.g. crange by geometry.																						_	
	PAS-RES-PV-01	Change of labeling	I P Change of labeling, also on reel.	(B) e.g. additional information (RoHS stamp) (P) e.g. change of customer specific information	В														-		-		-				
NETWORKS & RESISTORS	PAS-RES-PV-02	Change of product marking	P Marking on device.	e.g. change of content of marking e.g. change of method of marking	В														-								
NETWORKS & RESISTORS	PAS-RES-PV-03		P Change in packing specification which doe not described a change of dimensions or material of the packing.	e.g. change of appearance of marking																			H			4	
NETWORKS & RESISTORS	PRG-9825-PV-03	Change of packing/shipping specification LIDGISTICS / CAPACITY / TESTING - EQUIPMEMENT	P P not described a change of dimensions or material of the packing.	e.g. change of documentation in packing specification					- -	111			1 1	1 1		1 1		1 1 -								خلك	
NETWORKS & PESISTORS	PAS-RES-EQ-01	Production from a new equipment bot which uses a different technology or which due to its unique term or function can be expected to influence the integrity of the final product.	P Drange is process technique which is not sineady covered above. Note: Changes affecting the product not covered by the table require also a PCN.	e.g. new equipment supplier with different process concept.					• -	•	• -					- В			-		-		-			- @•	process change.
NETWORKS & RESISTORS	PAS-RES-EQ-02	Production from a new equipment/bol which uses the same basic technology (replacement equipment or extension of existing equipment pool)	PCN required for dedicated equipment for sensitive component production.	e.g. additional equipment to increase production capacity e.g. replacement of same equipment	С		•		• -	• -	•				• •	- B			-		-		-	-		- @•	Test effort depends on final risk assessment. Performance test according to affected process change.
	PAS-RES-EQ-03	Change in final test equipment type that uses a different technology	P P Change of final test equipment which use different technology. PCN required for dedicated equipment for sensitive parameters.	e.g. change of teater platform	С											- @B			-		-					- @•	Gage RSR / delta correlation
NETWORKS & RESISTORS NETWORKS & RESISTORS		LOGISTICS / CAPACITY / TESTING - PROCESS FLOW																									
	PAS-RES-PF-01	Manufacturing sile transfer or movement of a part of production process to a different location/site	P P Change of manufacturing site. P P Includes transfer as well as additional site. Note: Reorganization inside one plantisite	e.g. movement or transfer of manufacturing site or process step(s) to a different location/site.	В											- В			R		N		-		- @	2• @•	
NETWORKS & RESISTORS	PAS-PES-PF-02	Elimination or addition of a manufacturing process step	not affected P Change of manufacturing process sequence	e.g. dual source / fab strategy	С											- @B										- @•	Characterisation depends on impact of production flow.
NETWORKS & RESISTORS NETWORKS & RESISTORS		LOGSTICS / CAPACITY / TESTING - Q-GATE			Ť											@B								<u></u>		e.	p-43/301 TOK
NETWORKS & RESISTORS	PAS-RES-QG-01	Change of test coverage used by the supplier to ensure data sheet compliance (e.g., elimination/addition) of electrical measurement/lest flow block, releasticoler/hancement of month/oring procedure or sampling) INDUCTORS	. P Change of fast coverage.	e.g. change from 100% to sample inspection e.g. test flow block, reduction from three to two temperature resourcements e.g. change in burn infrun in process.	С				- -	- -									-				-			- -	R (electr-funct): test coverage. R (reliability) only for change in burn in process.
INDUCTORS	PAS-IND-AN-01	Any change with impact on agreed upon technical contractual agreements	P P Intended to be used if no other type of char is applicable but the change affects agreed	nge Net released for technical availables														T . I									
INDUCTORS	PAS-IND-AN-01 PAS-IND-AN-02		P P is applicable but the change affects agreed fechnical contractual agreements. P P	Not relevant for technical evaluation. Technical interface means component terminals.																				1 1	- @	0.	
INDUCTORS INDUCTORS	Arthura	DATASPEET		*																					- (4		
INDUCTORS	PAS-IND-DIS-DI	Change of datasheet parameters/electrical specification (min./max./lyp. values) and / or AC/DC specification		e.g. Sighten of electrical parameter distribution	A	Risk assessment depending on change for each application.													-		-		-				
NAME TO BE	PAS-IND-05-02	Correction of data wheel or issue of emals	No technical change of product, process o teat. No technical change of behavior which was not have considered before or which is different from initial specification. Please indicate clearly, that Intronsis contains this type of change! Assessment in adoculation results self.		A																-		-				
INDUCTORS	PRG-INEX-DS-02	MARTINGARINA OF CREAT REPORT OF BERRIE OF BETTER	initial specification. Please indicate clearly, that infoncts contain this type of change! Assessment in application required?	information about component behavior	A																		•				

										_																			
			Description of a new not previously covered parameter. No suchnical change of the product. No suchnical change of the product. (IP: no influence (IP: Flask assessment depending on change for such application to provide evidence of additional parametes (stat. evaluation)																										
PAS-IND-DIS-03	Specification of additional parameters	I P	(R): no influence (P): Risk assessment depending on change for	e.g. adding new (tested) parameter. or	A			-											-		-	-		-			-	-	
			each application to provide evidence of additional parametes (stat. evaluation)																										
	MATERIAL		Material without magnetic function ("Spulenköper") typically made by plastic	1						_														т т	_	_			
PAS-IND-MA-01	Change of material composition - Biobbin Material		material			A: in case the thermal or mechanical stability of bobbin is negatively affected								• •			- '		-			-					-	-	
PAS-IND-MA-02	Change of material composition - Core Material	P P	Change of core material, which is material with magnetic function	th e.g. change from NZn into MhZn	A	Consider also if PAS-IND-DE-05 is affected		@•	•			• .		• -			В		-			-		-			-	@•	
PAS-IND-MA-03	Change of material composition - insulation Material	P P	Change of insulation material	e.g. wire insulation, insulation tapes, e.g. change from Polyurethane to Polyamide	с	affected										Α -	в												
					-	A: in case of HV components (rated voltage >= 100V) (final judgemend by tier 1. if used in HV application)																							
PAS-IND-MA-04	Change of material composition - Lead Material	РР	Change of lead material	e.g. change from tin coverd to non-coverd lead material	В			-			- •	• -	• -	- •	• -				-		-	-		-			@•	-	
PAS-IND-MA-05	Change of material composition - Mold Compound	P P	Change of mold compound material	e.g. change to green mold	В												в	. . .										@ ACL	trical function affected if hanical stress distribution changes wave soldering and board coating to be assessed. MSL might
				e.g. change to green mold										1														has to chance	o be assessed MSL might sec.
PAS-IND-MA-06	Change of material composition - Solder Material	РР	Change of solder material at internal connection.	e.g. change of SnAgGu composition	В			-				• .	• .		@• •				-		-	-		-			@•	-	
PAS-IND-MA-07	Change of material composition - Wire / Foll Material	РР	Wire for wound inductors. Foil for multitayer inductors (inner electrode).	e.g. change of Cu composition	В	A: In case of sire wound inductors, where the wire is not 100% fixed by mold or epoxy within the inductor		@•						- @•			В											@•	
		-				or epoxy within the inductor		0.	+	_							+-+		-					+			+ +		
PAS-IND-MA-08	Change of material composition - Glue	P P	Foil for multilayer inductors (inner electrode).	e.g. change from glue A into glue B	С		• • •	-	@•		@• -	@• -		- @•	@• -	- @•	@B		-		-	-		-			-		sidere in case of core-core glue sir gap.
PAS-IND-MA-09	Change of supplier of material	. Р	Change to a new or additional material supplie at component manufacturer.	e.g. for 2nd source purpose	с			-			@• -						В		-			-		-			-	@• Assur	imption material specification sins unchanged. Otherwise see age of material.
PAS-IND-MA-10	Chance of material composition - Poting Material	РР	Change of polling material	e.c. change from epoxy resin to silicon	c	A: If influence on other connections on PCB or laquer expected.			@•		@• -	@• @•		- @•	@• -	- @•	@B		-									@•	ge or maseria.
	DESIGN		-			PCB or laquer expected.		_	0.	_	6.	0. 0.			6.										_			6.	
PAS-IND-DE-01	Changes of termination, surface finish, shaps, color, appearance or dimension structure - Bobbin	I P	Meterial without magnetic function ("Spulenkörper") typically made by plastic	e.g. construction / dimension change of bobbin	В				•					• -	- •	•	В		-			-		-			-	@•	
PAS-IND-DE-02	Changes of termination, surface finish, shape, color, appearance or dimension structure - Lead Terminals	I P	Change of lead/terminals	e.g. Change of lead or terminal design (shape, dimension,)	А			-					• -		• -				-		-	-		-			@•	@• Effect	ct regarding EMC relevant for high sency only.
PAS-IND-DE-03	Changes of termination, surface finish, shape, color, appearance or dimension structure - Mold		Change of mold	e.g. new mold material with different color	В						@• -						В					-		-				@• Param	emeter Analysis only for powerts where mold material has
PAS-IND-DE-04	Changes of inner construction - Core Construction		Change of core construction, which is material	al e.g. change fromdrum core & shield core into pot core & cover plate core	A												В											@•	atic function
	and the second s	-	Change of insulation system																					H				e*	
PAS-IND-DE-05	Changes of inner construction - insulation System	. Р	An electrical insulation system (EIS) is comprised of a unique combination of materia	de e.g. wire insulation, insulation tapes, mold, polling,	С	A: in case of HV components (rated voltage >= 100V) (final judgement by tier 1, if used in HV application)		@•								Α -	В					-		-					
			An electrical insulation system (EIIS) is comprised of a unique combination of materia that have been verified for chemical compatibility when used all certain maximum temperatures, (see week U.c.com)			1, if used in MV application)		3.																					
PAS-IND-DE-06	Chances of inner construction - Wire / Foil Construction	. р	Change of wire / foil dimensions	e.g. change from round cross section to rechangular cross section e.g. from single wire to litz wine	В									- @•			В											@•	
PAS-IND-DE-07	Changes of termination, surface finish, shape, color, appearance or dimension structure - Potting Material			e.g. from single wire to litz wire e.g. change of polling (filling) height		If data sheet is affected (PAS-IND-DS- 91)						@• @•			@• -		@B		-			_	_	+ - 1				@•	
- NOVE CO	Material PROCESS	1117	crange or posing cimension	eg change or pound (rang) neight		01)			@• .			@• @•		. @•	@• ·		60		1 - 1										
PAS-IND-PR-01	Changes in process technology or manufacturing methods - Insulation Strip	. Р	(Mechanical) removal of insulation.	e.g. change from mechanical removal to laser	В				@•					- @•		- @•			-								-	Mech impac	hanical damage of wire, act on solderability in case of ping process is affecting soldering
PAS-IND-PR-02	Changes in process technology or manufacturing methods - Lead Prep. / Plating		Change of lead prep. / plating	e.g. change from hot dip tinning to electropisting	В																	_					@•		ence regarding reliability of solder
PAS-IND-PR-03	Changes in process technology or manufacturing methods - Terminal Allach	. P	Connection of wire terminal and / or connection of termination to constrain.	e.g. change from Nanual winding to Semi-automic winding (winding of wire on terminal)	c			Ť			@• -		-		Α •				+ -		+ -						@•	joint	
PAS-IND-PR-04	Changes in process technology or manufacturing methods - Terminal Atlach Changes in process technology or manufacturing methods - Marking		connection of termination to cone/bobbin. Change of marking process	winding (winding of wire on terminal) e.g. change from ink marking to baser marking	В			_	•			•			^ •	<u> </u>			-			-		-		-	@•	* Incres	use of contact resistance.
PAS-IND-PR-05	Changes in process technology or manufacturing methods - Molding	. P	Change of molding process	e.g. change from one component molding to two component molding (other technology needed)	В												В												
PAS-IND-PR-06	Changes in process technology or manufacturing methods - Soldering Internal Connections		Change of soldering internal connection	e.g. change from hot tip tinning to resistance welding	с	in case solder connection is used as solder connection to PCB.													-			-		-			-	-	
PAS-IND-PR-07	Changes in process technology or manufacturing methods - Winding Insulation	. Р	Change of winding - insulation	e.g. change from manual to automatic process	В		•										В		-			-		-			-	-	
PAS-IND-PRI-08	Changes in process technology or manufacturing methods - Winding Wire	. Р	Change of winding - wire	e.g. change from semi-automatic winding to full automatic winding	С		• • -					• -					В		-		-	-		-			-	@•	
PAS-IND-PR-09 PAS-IND-PR-10	Process integrity: tuning within specification	. Р	Variation within process specification.	e.g. process control	С			-											-			-		-			-	-	
PRG-RE-PR-10	Changes in process technology or manufacturing methods - Polling PACKING / SHIPPING - NEW MATERIAL, CRITICAL DIMENSIONS			e.g. change from manual polling process to automatic polling process	С				@•	- -	@• -	@• @•		- -		1 - 1 -	1 - 1 -	. . .		- -	-	- 1		1 - 1	- -			-	
PAS-IND-PN-01	Packing / shipping specification change (sossering of tolerances)	РР	Change of packing specification.	e.g. number of pieces on reel.	В			-											-			-		-			-	-	
PAS-IND-PN-02	Dry pack requirements change	ı P	Change of dry pack requirements. (B: Relaxation of dry pack requirements (P): Tightening of dry pack requirements	e.g. change in dry pack assurance (HC, MES) (I): MSL 3 -> MSL 1 (IP): MSL 1 -> MSL 3	В														-								-	-	
PAS-IND-PN-03	Change of carrier (tray, reel)		(P): Tightening of dry pack requirements Change of carrier		В															_									
PRG-REPHYGS	PACKING / SHIPPING - VISUAL INSPECTION	РР	change or carrier	e.g. change by material e.g. change by geometry.	В				1 - 1 -	- -		1 - 1 -	1 - 1 -	1 - 1 -	1 - 1 -	1 - 1 -				- -		-	- -	1 - 1			1-1	-	
PAS-IND-PV-01	Change of labeling	I P	Change of labeling, also on reel.	(B) e.g. additional information (RoHG stamp) (P) e.g. change of customer specific information	В			-											-			-		-			-	-	
PAS-IND-PV-02	Change of product marking	I P	Marking on device.	e.g. change of content of marking e.g. change of method of marking	В			-									-		-			-		-			-	-	
PAS-IND-PV-03	Change of packing/shipping specification	РР		e.g. change of appearance of marking e.g. change of documentation in packing specification																									
	LOGISTICS / CAPACITY / TESTING - EQUIPMEMENT	ئيت	material of the packing.	specincason	_	-																							
PAS-IND-EQ-01	Production from a new equipment/bol which uses a different technology or which due to its unique	Π.	Change in process technique which is not already covered above.	e.g. introduction of polling process	с												@B											@• Test e	effort depends on final risk sument. ormance lest according to affected
PAS-IND-EIQ-01	Production from a new equipment/bod which uses a different technology or which due to its unique form or function can be especial to influence the integrity of the final product	PP	Note: Changes affecting the product not covered by the table require also a PCN.	e.g. reroduction of polling process	С												(GD												
PAS-IND-EQ-02	Production from a new equipment/bod which uses the same basic technology (replacement equipment or edention of existing equipment pool)	. Р		e.g. duplication of existing winding machine	С																	-		- T				@• Test o	effort depends on final risk sament. Iornance test according to affected assa change.
		\vdash	Change of final test equipment which use																++								+ +		
PAS-IND-EQ-03	Change in final test equipment type that uses a different technology	P P	Change of final feet equipment which use different technology. PCN required for dedicated equipment for sensitive parameters.	e.g. change of teater platform	С			1	- -								@B		-		-	-		-			-	@● Gago	e RSR / delta correlation
	LOGISTICS / CAPACITY / TESTING - PROCESS FLOW								1 1				1 1		1 1														
PAS-IND-PF-01	Manufacturing site transfer or movement of a part of production process to a different location/site	P P	Change of manufacturing site. Includes transfer as well as additional site. Note: Recognization inside one plantisite is not affected.	process step(s) to a different location/site.	В		•	٠	•	- I •	@• •	@• -	• •				В		-			-		-			@•	@•	
PAS-IND-PF-02	Elimination or addition of a manufacturing process step		not afforted. Change of manufacturing process sequence.		с																	-						@• Chara	racterisation depends on impact of luction flow.
PAS-IND-PT-03			Reduction of final testing.																								-		
PAS-IND-PF-03	Elimination of final electrical measurement / lest flow block LOGISTICS / CAPACITY / TESTING - Q-GATE	I P	Reduction of final testing. PCN required for dedicated final test reductions for sensitive parameters.	e.g. elimination of High-voltage measurement	С																							@• Chara final b	racterisation depends on impact of test flow.
			T	e.g. change from 100% to sample inspection																								Riele	ectr. funct): test coverage.
PAS-IND-QG-01	Change of test coverage used by the supplier to ensure data sheet compliance (e.g., elimination/addition of electrical measurement/test flow block, relixation/enhancement of monitoring procedure or sampling)	- Р	Change of fast coverage.	e.g. change from 100% to sample inspection e. g. test flow block, reduction from three to two temperature measurements e.g. change in burn infrun in process.	С				-		-	• •										-					-	- R (reli proce	lectr. funct.): test coverage. slability) only for change in burn in sea.
	CERAMIC / TANTALUM ANY			<u> </u>																									
PAS-CER-AN-01	Any change with impact on agreed upon technical contractual agreements	РР	Intended to be used if no other type of change is applicable but the change affects agreed	Not relevant for technical evaluation.				-											- 1		-	-		- 1			-		
PAS-CER-AN-02	Any change was rejective agreed upon scientific constitution agreements. Any change with impact on processability/instrutuckrability at customer, which is not covered in the mallist below.	РР	second contacted sessents	Technical interface means component terminals.	В			-									<u> </u>		-		-	-		-			@•	-	
	DATASHEET																						_						
PAS-CER-DS-01	Change of datasheet parameters/electrical specification (min./max./typ. values) and / or ACIDC specification	P P	Change of application relevant information Not included: Editorial changes.	e.g. Sghlen of electrical parameter distribution	A	Plak assessment depending on change for each application.		-									-		-		-	-		-		-	-	-	
			No technical change of product, process or test. New description of behavior which was not specified belone or which is different from initial specification. Please indicated classify, that infoncie contains this type of change! Assessment in anolication required!																										
PAS-CER-DS-02	Correction of data sheet or issue of emats	1 1	specified before or which is different from Initial specification.	e.g. data sheet correction because of new information about component behavior	A			-											-		-	-		-			-		
		1 1	Presse indicate clearly, that Infoncte contains this type of change!	1																									

MOLECUS
MOL

CERAMIC / TANTALUM

CERAMIC / TANTALUM

İ				L	1																							_	
	PAS-CER-OS-03	Specification of additional parameters		Description of a new not previously covered parameter. No technical change of the product. (6): no influence (67): Flask assessment depending on change for each application to provide evidence of additional parametes (elist. evakation)	e.c. adding new (leated) parameter.	A																						1.1	
				(P): Risk sassument depending on change for each application to provide exidence of additional parameter (stat. evaluation)		^																							
CERAMIC / TANTALLIM CERAMIC / TANTALLIM		MATERIAL							_																			#	
CERAMIC / TANTALUM CERAMIC / TANTALUM	PAS-CER-MA-01 PAS-CER-MA-02	Change of malarial composition - Ceramic Binder Change of malarial composition - Tantakun Binder	PF	Binder material (ceramic) Binder material (tantal)	e.g. change from sex 1 to wax 2	c	-				1 1			: :	1 1	- :	: :				1 1	- :		-	1 1		: :		
	PAS-CER-MA-03	Change of material composition - Dielectric	Р	Dielectric change (ceramic only) ceramic material class (8a1903, Ca2r03, etc.) will not be changed, only dopands will be	e.g. change from ceramic A into ceramic B	с			. .										в -	С -						_		4 . //	
CERAMIC / TANTALUM				changed														-			-								
CERAMIC / TANTALUM		Change of malerial composition - Electrode Attach Change of malerial composition - Electrode Melerial	PF	Electrode attach (only tantal, glue, carbon, Ag) Electrode Material (only ceramic, inner alctrode)	adventire e.g. change from spehric to flake shape (N paste)	c	•		•			•				•	c •			C •			-	-		-		+	
CERAMIC / TANTALUM			1				Consider effect on usage on coaled PSA (printed board assembly)																						
	PAS-CER-MA-06	Change of material composition - Encapsulation	P	Encapsulation	e.g. change from epoxy1 into epoxy2	С	S: In case component is used in costed			• -	• •	-	•	• -	• -	-							- -	-		-	- -	4 - 7	- Check whether ADI at Tier 1 can be affected
CERAMIC / TANTALLM	PAS-CER-MA-07	Change of material composition - Lead material / Termination	Р Б	Lead material / Termination All changes outside ceramicitantal body	e.g. change from SnPb to pure Sn e.g. change of soft termination material e.g. change of any galantic layer	В	PEA (printed board assembly)												в -										
CERAMIC / TANTALUM	PAS-CER-MA-08	Chance of supplier of material	-	All changes outside ceramic/tantal body Change to a new or additional material supplier at component manufacturer.		c															С -							-	Assumption material specification nerwins unchanged. Otherwise see
CERAMIC / TANTALLIM CERAMIC / TANTALLIM		DESIGN	- '	at component manufacturer.	e.g. for 2nd source purpose	c			· '	نب	<u> </u>	٠.		بنب	<u> </u>				В -	<u> </u>	С -	1 - 1 -		-				اند	change of material
CERAMIC / TANTALLIM	PAS-CER-DE-01	Changes of fermination, surface finish, shape, color, appearance or dimension structure - Lead	I F	Change of lead diameter	e.g. change from 0.8mm into 0.6mm	А		• -					•										-			-		- 1	-
CERAMIC / TANTALUM	PAS-CER-DE-02	Changes of termination, surface finish, shape, color, appearance or dimension structure -		Change of Termination area	e.g. change in width of termination from 0.1 -0.3mm into 0.2 - 0.4 mm	В		• -					•										-	-		-		- 1	
CERAMIC / TANTALUM	PAS-CER-DE-03	Territration Area Changes of territration, surface finish, shape, color, appearance or dimension structure - Territrat Interface	1 6	Terminal interface	e.g. additional layer in termination	В		• -	•			•	-	- •		•			В -				-			-		-	-
CERAMIC / TANTALUM		Changes of Inner construction - Electrode Thickness Changes of Inner construction - Layer Thickness	- F	Electrode thickness (ceramic only) Layer thickness (delectric thickness)	e.g. N layer change from 2.5µm into 3.5µm e.g. Cleramic layer thickness changes from 3µm into 5µm.	c	•	•				•	-			•		•	В -	@• -			-	-		-		-	@•
CERAMIC / TANTALUM	PAS-CER-CE-05	Changes of inner construction - Number of Layers		Number of layers (ceramic only). Always in combination with PAS-CER-DE-OS.		c				СС				С -						@C -	С -						•	+	
CERAMIC / TANTALLIM CERAMIC / TANTALLIM		PROCESS	- '	combination with PAS-CER-DE-05.	and and siyer structures	·			- '		- -	C		٠ . ا	- -		- -	<u> </u>	В,С -	ec .	, .	1.1.			- -			بند	
CERAMIC / TANTALUM	PAS-CER-PR-01	Changes in process technology or manufacturing methods - Dicing				c											c c		B - B,C -	c -	С -							-	
CERAMIC / TANTALUM		Changes in process technology or manufacturing methods - Electrode apply Changes in process technology or manufacturing methods - Firing	- 1	Electrode apply (dielectric bayer process) Change of firing profile	e.g. change from well to dry process e.g. separation of decarbonization and firing profile.	c			С .		- C	•					C C		B,C -		C -								
CERAMIC / TANTALLIM CERAMIC / TANTALLIM		Changes in process scrinology of manuscraining memors: - ining Changes in process technology or manufacturing methods - Lamination		Change of lamination / press techinque		c		• •	-				-	1 1					В -	•	c -			-		-			
CERAMIC / TANTALUM	PAS-CER-PR-05	Changes in process technology or manufacturing methods - Particle Size		Change of powder particle size. Allways in combination with PAS-CER-MA-03.	e.g. change D50 from 0.5µm into 0.4µm	с			- -		- •		-			-	• -		В -	• -			-	-		-		-	
CERAMIC / TANTALIM	PAS-CER-PR-05	Changes in process technology or manufacturing methods - Screening/Printing	- F	Change of screening / printing	e.g. change from screen printing into offset printing	С			-						- C		_		-10		С -		-	-		-		-	-
CERAMIC / TANTALLIM	PAS-CER-PR-07	Changes in process technology or manufacturing methods - Termination	- 1	Change for termination preparation like plating or apply of termination base layer.	e.g. change in plating technology (final termination) e.g. change from dip in paste to plating (apply)	В	•		•							•	• .	- •	В -				-			-		- 7	
CERAMIC / TANTALUM CERAMIC / TANTALUM	PAS-CER-PR-08	Process inlegify; turing within specification PACKING / SHIPPING - NEW MATERIAL, CRITICAL DIMENSIONS	- 1	Variation within process specification.	e.g. process control	С			- 1				- 1	- -				- -						- 1					-
CERAMIC / TANTALUM					e.g. number of pieces on real.	В				- 1 - 1			- 1	1		1 - 1							-	- 1		- 1			-
	PAS-CER-PN-02	Dry pack requirements change		Change of dry pack requirements.	e.g. change in dry pack assurance (HC, MBB) (8: MSL 3 -> MSL 1	В							-													-		- 1	
CERAMIC / TANTALLIM	PAS-CER-PN-03		_		(P): MSL 1 → MSL 3 e.g. change by material e.g. change by geometry.	В										+ . +												+	
CERAMIC / TANTALLIM CERAMIC / TANTALLIM		PACKING / SHIPPING - VISUAL INSPECTION																										_	
CERAMIC / TANTALUM	PAS-CER-PV-01	Change of labeling			(i) e.g. additional information (RbHS stamp) (P) e.g. change of customer specific information	В	•						-			-								-		-			-
CERAMIC / TANTALLIM	PAS-CER-PV-02	Change of product marking	1 8		e.g. change of content of marking e.g. change of method of marking e.c. change of appearance of marking	В			-			-	-			-							-	-		-		/ - I/	•
	PAS-CER-PV-03	Change of packing/shipping specification	Р	Change in packing specification which does not described a change of dimensions or material of the packing.	e.g. change of documentation in packing specification				-				-			-										-			-
CERAMIC / TANTALLIM CERAMIC / TANTALLIM		LOGISTICS / CAPACITY / TESTING - EQUIPMEMENT			,										_														
	PAS-CER-EQ-01	Production from a new equipment/bol which uses a different technology or which due to its unique fermor function can be expected to influence the integrity of the final product	Р	Change in process technique which is not already cowered above. Note: Changes affecting the product not covered by the table require also a PCN.	e.g. change from wet to dry technology.	С								• A					в -		С -					-		4 . 7	Test effort depends on final risk assessment. Performance lest according to affected
CERAMIC / TANTALLIM			_						-	4																	_		process change.
CERAMIC / TANTALUM	PAS-CER-EQ-02	Production from a new equipment/tool which uses the same basic technology (replacement equipment or extension of existing equipment pool)	- F	PCN required for dedicated equipment for sensitive component production.	e.g. elimination of manual handling processes	С	•	• -		• -		•	-	• A		•			В -		С -		-	-		-		4 - 7	Test effort depends on final risk assessment. Performance test according to affected
CERAMIC / TANTALUM				Change of final test equipment which use																									process charge.
CERNANC / TANTAI I M	PAS-CER-EQ-03	Change in final test equipment type that uses a different technology	PF	Change of final test equipment which use different technology. PCN required for dedicated equipment for sensitive parameters.	e.g. change of tester platform	С	•		-				-			-	- -		@B -							-		4 1 1	@● Gage RSR / delta correlation
CERAMIC / TANTALUM CERAMIC / TANTALUM		LOGISTICS / CAPACITY / TESTING - PROCESS FLOW	_	Change of manufacturing site. Includes transfer as well as additional site. Note: Recepanization inside one plantisite is	e.g. movement or transfer of manufacturing site or process step(s) to a different location/site.				_																			_	
CERAMIC / TANTALLIM	PAS-CER-PF-01	Manufacturing sits transfer or movement of a part of production process to a different location/site	P F	Includes transfer as well as additional site. Note: Reorganization inside one plant/site is ont affected.	process step(s) to a different location/site.	В	•	•	•		• •	•	•	• •	• •	•		• •	В -	• •	С -		-	-		-		@•	@•
CERAMIC / TANTALUM	PAS-CER-PF-02	Elimination or addition of a manufacturing process step		Change of manufacturing process sequence.	e.g. washing / cleaning process e.g. change of order of processes	с	•		-			-	-			-							-	-		-		/ - //	Characterisation depends on impact of production flow.
CERAMIC / TANTALIM		LOGISTICS / CAPACITY / TESTING - Q-GATE	÷		a a shared from 1999, to sense to recorder					_																		_	
	PAS-CER-QG-01	Change of test coverage used by the supplier to ensure data sheet compliance (e.g., elimination/addition of electrical measurement/test flow block, relaxedion/enhancement of membring procedure or sumpling)	- F	Change of fast coverage.	e.g. change from 100% to sample inspection e.g. test flow block, reduction from three to two temperature measurements	С			-			-	-			-							-	-		-		4 - 7	R (electr funct): test coverage. R (reliability) only for change in burn in process.
Film capacitors		FILM CAPACITORS	_	1	The standard control to baconin																								
Film capacitors	PAS-FLM-AN-01	Any change with impact on agreed upon technical contractual agreements	Р Б	Intended to be used if no other type of change is applicable but the change affects agreed isotheral contractual assessments	Not relevant for technical evaluation.							T . T				Τ.Τ													
Film capacitors	PAS-FLM-AN-02	Any change with impact on agreed upon isotrical contractual agreements Any change with impact on processability/imanufacturability at customer, which is not covered in the matrix below. DATASHEET	P F	Sechelical contractival accessments	Technical interface means component terminals.	В							-			-										-		@•	
Film capacitors		DATASHEET	Ť	Ť	· I																	1 1							
Film capacitors	PAS-FLM-DS-01	Change of datasheet parameters/electrical specification (min/max/hyp. values) and / or ACIDC specification	P	Change of application relevant information Not included: Editorial changes.	e.g. fighten of electrical parameter distribution	A	Risk assessment depending on change for each application.		-			-	-			-							-	-		-			-
				No technical change of product, process or test.						الحالة																			
	PAS-FLM-DS-02	Correction of data sheet or issue of emats	1 1	specified before or which is different from initial specification.	e.g. data sheet correction because of new information about component behavior	A			-			-	-			-							-	-		-		-	-
Film capacitors				test. New description of behavior which was not specified before or which is different from risks apportination. Please indicate clearly, fast infoncts contains this type of change! Assessment in application required?																									
	PAS-FLM-DS-03	Specification of additional parameters	1 8	Cleaniption of a new not previously covered parameter. No technical change of the product. (8: no influence (P): Risk assessment depending on change for such application to provide widence of additional parameter (stit. esikustion)	e.g. adding new (leated) parameter.	A			-			-	-			-							-	-		-		-	
Film capacitors				each application to provide evidence of additional parametes (stat. evaluation)																									
Film capacitors Film capacitors		MATERIAL	Ŧ	T			A: in combination with PAS-FLM-DS-01 or if change of sealing compound with effect to mechanical properties.					T	Ī																
				Typicaly change within sposy or PU sealing without effect to mechanical properties.			or in change of sealing compound with effect to mechanical properties.																						
	PAS-FLM-MA-01	Change of malerial composition - Sealing Compound	P	Typically change within spony or PU sealing without effect to mechanical properties. Note: Change from spony sealing into PU sealing (both direction) will lead to generate a new product.	e.g. change of epoxy or PU composition	С	A: in case of high voltage components (rated voltage >= 100V) (final judgement by tier 1, if used in HV	• •		• -	• •	•	•	• @•	• •	•	- •		•			1 -							 Consider vibration in application
Film capacitors			_		Characterist of annual		application)					\square																##	
Film capacitors	PAS-FLM-MA-02	Change of material composition - Package	P F	Change material of package	Change material of package, e.g. change from PST to PPS e.g. change of glas fiber ratio	В	•	• •	- '	• -	- •	•	٠		@•	•		- •	- @•				-	-		-			 Consider ADI and processability
	PAS-FLM-MA-GS	Change of material composition - Lead Termination	١,	Change of Lead Termination Note: If change of lead frame material leads to an ESR change, than change of data sheet (PAS-FLM-DS-01) has to be respected.	e.g. change of basis material from Cu to Fe e.g. change of finishing from SnPb to Sn	В	A: in combination with PAS-FLM-05-01												в -									@•	Change of base material: Consider ESR, high frequency parameter
Film capacitors			1		e.g. change of finishing from SnPb to Sn						•			•	•				3 .									@•	
	PAS-FLM-MA-GI	Change of material composition - Metal Spray (Schoop)	Р	Change of Metal Spray (Schoop): Use different material for metal spray process for bosed and	e.g. from Zn to Al	с	s: for risked SMD		- @	2• -	@• -	@•		- @•	- @•	@•		- @•						-		-			Consider ESR Solderability Test for naked SMD
Film capacitors	PAS-FLM-MA-05	Change of material composition - Film	P F	maked types Change of film material for boxed and naked types	e.g. change of additives (<1%) of film composition fearne case material)	С	B: for naked SMD		- @	20 -	- @•	@•	@• 6	@• -		- 6	ე• -		@• -										components.
Film capacitors	PAS-FLM-MA-05		Р	Change of metal foil for inner electrode	e.g. change from Al to Al-Zn alloy	С			- @		- @•					- `			@• -				-	-		-			@•
	PAS-FLM-MA-G7	Change of supplier of material		Change to a new or additional material supplier at component manufacturer which are described above.	e.g. for 2nd source purpose	с	Check if other PAS-FLM-MA is affected						-										-	-		-			Assumption material specification nemains unchanged. Otherwise see change of material.
Film capacitors Film capacitors		DESIGN	_	percriped above.	L																								change of material.

March Marc												1 . 1									- 1	- 1			- 1				
March Marc	Film capacitors	PAS-FLM-DE-01	Changes of termination, surface finish, shape, color, appearance or dimension structure - Lead Dameter / Thickness	I P Change of lead diameter thickness (for soldered THT components)	e.g. change and durinar from 0.5 to 0.4 mm e.g. change of thickness of terminal			• •				@•	@• @•	- @	g• @• -			@B -	@• @•	-		-		-		•		•	
March Marc		PAS-FLM-DE-02	Changes of termination, surface finish, shape, color, appearance or dimension structure - Termination Area	I P which are affecting the area for connection of component and PCB	e.g. change of termination layer thickness e.g. change in termination dimensions / shape	В			- @		- - -						@•		@• @•	-	- -	-		-		-	- @•		
March Marc	Film capacitors	PAS-FLM-DE-03	Changes of inner construction - Inner Connection	. P Change of inner connection	e.g. change from soldered connection to welded				- @	-	@	· @•	- @•	- @	e e e		-	@• -	@• @•	-		-		-		-		-	
March Marc				Change of appearance. (i): Change in appearance without impact on		Che	ck if MATERIAL is affected.																						
March Marc		PAS-FLM-DE-04	Changes of termination, surface finish, shape, color, appearance or dimension structure - Appearance	product integrity. I P (P): Change in apparance with impact on product integrity.	e.g. change or adding of color on component	В				-		-					-			-	- -	-		-		-		-	
March Marc	Film capacitors			Note: Marking on device is defined as seperate change (PAS-FLM-PV-02).																									
March Marc	Film capacitors	PAS-FLM-DE-05	Changes of inner construction - Film/Foil	. P Change of film or foll design		C Acin	combination with PAS-FLM-05-01	• •	- •	-		-				- •				-		-		-		-		@•	
March Marc		PAS-FLM-DE-06		Change of inner insulation to protect winding element against housing.	e.g. change of poting material e.g. change of number of inner insulation layers (december of insulation material thickness)	с				-		-					-	В -		-		-		-		-		@•	
Marche M	Film capacitors	PAS-FLM-DE-07	Changes of termination, surface finish, shape, color, appearance or dimension shucture - Package	p Change of packaging	e.g. change of dimension or shape e.g. change of surface	В			- @	- 6	9 •	@•	@• -	@• @	g• @• -		-	- @•		-		-		-		-			
March Marc	Film capacitors		PROCESS																										
March Marc	Film capacitors	PAS-FLM-PR-01	Changes in process technology or manufacturing methods - Package	P Change of resin filling or hardening process (released for bosed types only)	sequences, poling,) e.g. change in hardening process (temperature, firm)	С		• •	• •	-	- •	•		•			-					-		-		-		-	
March Marc		PAS-FLM-PR-02	Changes in process technology or manufacturing methods - Terminal Attach	Change Terminal Attach Process to winding alarment for broad and nuclear broas	e.g. spraying and / or galvanic process,	C B: 1:	or naked SMD					-					-	в -										@● Consider E Solderability	ESR By Test for naked SMD
March Marc	Film capacitors	PAS-FLM-PR-03	Chances in crocess technology or manufacturing methods - Winding	Change of winding, flattening or tempering		С				+ - +	- @•	-				- ·	-	В -				-		-				component	rts.
March Marc	Film capacitors Film capacitors		Process inlegitly: tuning within specification	P Variation within process specification.						-		-					-			-		-		-					
Property	Film capacitors	PAS-FLM-PN-01		P P Change of packing specification.	a.n. number of nieres on real	В				Т.Т		1 - 1										.		T . T					
March Marc	Film capacitors																												
Part	Film capacitors			(P): Tightening of dry pack requirements																		-		1					
March Marc	Film capacitors	PAS-FLM-PN-03		p p Change of carrier	e.g. change by material e.g. change by geometry.	В				-	- - -	-		- -	- - -		-			-	- -	-		-		-		-	
March Marc	Film capacitors									T		T					\top							Т					
March Marc		PAS-FLM-PV-01	Change of labeling			В		1 1		-		-								-				-		-		-	
March Marc	Film capacitors	PAS-FLM-PV-02	Discovered recorded markings	I P Materia on Ambre	e.g. change of content of marking	В										T													
March Marc	Film capacitors				e.g. change of appearance of marking							+					+					-	H						
March Marc	Film capacitors	PAS-FLM-PV-03		P P not described a change of dimensions or material of the packing.	e.g. crange of documentation in packing specification	•				-		-					-			-		-		-		-		-	
Part	Film capacitors																											Task officer of	d depends on English
Part		PAS-FLM-EQ-01	Production from a new equipment/bol which uses a different technology or which due to its unique formor function can be espected to influence the integrity of the final product	p p sheady covered above. Note: Changes affecting the product not	e.g. implementation of new machines	с			- •		. @.	@•	@•				-	В -	- •	-	- -	-		-		-		@• assessment	n depends on time nak ent. ence test according to affected
Part	Film capacitors											+					+					-	_	+				Test effort o	change. rt depends on final risk
Part		PAS-FLM-DQ-02	Production from a new equipment/bol which uses the same basic technology (replacement equipment or extension of existing equipment pool)	 PCN required for dedicated equipment for sensitive component production. 	e.g. extension of existing machine capacity	С		• •	- •		. @•	@•	@•		- - -		-	В -	- •	-	- -	-		-		-		@• Performance	ent. ence test according to affected
Part	Film capacitors			Change of final test equipment which use																									
Part	Film capacitors			P PCN required for dedicated equipment for sensitive parameters.		С				-		-					-	@B -				-		-		-		@◆ Gago R&R.	R / delta correlation
Part	Film capacitors		LOGISTICS / CAPACITY / TESTING - PROCESS FLOW	Change of manufacturing sile.	e.g. movement or transfer of manufacturing site or			_									$\overline{}$	$\overline{}$							=				
Part	Film capacitors	PAS-FLM-PF-Q1	Manufacturing sits transfer or movement of a part of production process to a different location/site	p Includes transfer as well as additional site. Note: Reorganization inside one plantisite is not affected.	process step(s) to a different location/site.	В		• •			• • •	•	• •	• •	• • •		•	В •	• •	-	- -	-		-		-	- @•	@•	
Part		PAS-FLM-PF-02	Elimination or addition of a manufacturing process step	P Charge of manufacturing process sequence.	e.g. washing / cleaning process e.g. change of order of processes	с				-		-					-					-		-		-		@ Characteria production	risation depends on impact of on flow.
This imports to the imports	Film capacitors		LOGISTICS / CAPACITY / TESTING - Q-GATE							+							+							-					
This imports to the imports		PAS-FLM-QG-01	Change of feet coverage used by the supplier to ensure data sheet compliance (e.g., elimination/addition of electrical measurement/lest flow block, releasion/enhancement of	. P Change of test coverage.	e.g. change from 100% to sample inspection e.g. lest flow block, reduction from three to two temperature measurements	с																						R (electr. ft. R (reliability	funct.): test coverage. Bty) only for change in burn in
Part										- 1		- 1								-	- -	-		-					
Mary and the part of the par	QUARTZ CRYSTAL / SAW		QUARTZ CRYSTAL / SAW		e.g. change in burn infrun in process.					11	- - -	1 - 1										-						process.	
March Marc	QUARTZ CRYSTAL / SAW QUARTZ CRYSTAL / SAW		QUARTZ CRYSTAL / SAW																			-		<u> </u>				ргосени.	
	QUARTZ CRYSTAL / SAW		QUARTZ CRYSTAL / SAW NY Any change with Impact on agreed upon lechnical contractual agreements	P P Intended to be used if no other type of change is applicable but the change affects agreed sorbotical contempts of someoneds	Not relevant for technical evaluation.						- -	-			- - -		-			-		-				-		process.	
1	QUARTZ ORYSTAL / SAW		QUARTZ CRYSTAL / SAW ANY Any change with impact on agreed upon incinical contractual agreements Any change with impact on processability/immediacturability at customer, which is not covered in the matrix below.	P P Intended to be used if no other type of change is applicable but the change affects agreed sorbotical contempts of someoneds	Not relevant for technical evaluation.			· · ·		-		-					-			-		-		-	- -	-	@•	process.	
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Mary	CUARTZ CRYSTAL / SAW CUARTZ CRYSTAL / SAW CUARTZ CRYSTAL / SAW CUARTZ CRYSTAL / SAW	PAS-QUA-AN-02 PAS-QUA-05-01	COMPATE CONTRACT SAW Any Company of the Security of the Secur	P P P Interested to be useful if no other type of changes P P P Interested to the change of the capy and the	Not relevant for lachical endation. Technical inferior revers compresed territoria, #ag lighter of electrical parameter destination #ag data feed correction because of new information shall compressed behavior.	B Risk for e		· · · · · · · · · · · · · · · · · · ·					· · · · · · · · · · · · · · · · · · ·				-											POC68.	
Marcola Marc	OLIMITZ CRYSTAL / SAW OLIMITZ CRYSTAL / SAW OLIMITZ CRYSTAL / SAW OLIMITZ CRYSTAL / SAW	PAS-QUA-0IS-01 PAS-QUA-0IS-02	OWNET CONTRACT SAW Any changes of the September of the S	P P P Interested to be useful if no other type of changes P P P Interested to the change of the capy and the	Not relevant for lachical endation. Technical inferior revers compresed territoria, #ag lighter of electrical parameter destination #ag data feed correction because of new information shall compressed behavior.	B B Risk	, ssessment depending on change such application.			-												-				-		POC686	
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Part Day of the control property	CUNTEZ CRISTAL, FAMO CUNTEZ CRISTAL C	PAS-QUA-NA-02 PAS-QUA-03-01 PAS-QUA-03-02 PAS-QUA-03-03 PAS-QUA-03-03 PAS-QUA-03-03	Country Control (s) SWW WY Any rich age of the Sympton and Sympton Statistical and parameter Any rich age of the Sympton and Sympton Statistical and parameter Any rich age of the Sympton Statistical Sympton Statistics Any rich age of the Sympton Statistics Control Statistics Control Statistics Control Statistics Control Statistics Control Statistics Statistics Control Statistics Statistics Control Statistics	P	Not release for technique consideration. **Inchination development in research compressed between the search compressed between the search of technique and technique consideration and technique con	A Residence of the control of the co	executed depending on durings in a significant			- 6		·				• @• -	-	- @•		-		-						-	
Part Day of the control property	CUNTE CHISTN, FANY CHISTNET CHISTN CHIST	PAS-QUA-05-01 PAS-QUA-05-01 PAS-QUA-05-02 PAS-QUA-05-02 PAS-QUA-05-02 PAS-QUA-06-02 PAS-QUA-06-03 PAS-QUA-06-03	Country Control (a Sew) WY Any sharped by Seyder in a great upon the broad and shaded any served. Any sharped by Seyder in a great upon the broad and shaded any served. Any sharped by Seyder in a served by the shaded of the shade and served in the shaded of the sh	P	No visual for indirect analysis. **The state of the first analysis of the state of	A Rain A A A A A A B	, assessment depending in ribrings with application.			- 6		·				• @• -	-	- @•		-		- (@• -					-	
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## 150.04.06 Deep changed companies - Can being from a change of part of the management of the manag	CLANTE CONSTAL, FORM CLANTE CONSTAL CLANTE	PAS-QUA-DS-01 PAS-QUA-DS-01 PAS-QUA-DS-02 PAS-QUA-DS-03 PAS-QUA-DS-03 PAS-QUA-DS-03 PAS-QUA-DS-03 PAS-QUA-DS-03 PAS-QUA-DS-03 PAS-QUA-DS-03 PAS-QUA-DS-04 PAS-QUA-DS-04 PAS-QUA-DS-05 PAS-QUA-DS-05 PAS-QUA-DS-05 PAS-QUA-DS-05 PAS-QUA-DS-05 PAS-QUA-DS-05 PAS-QUA-DS-05	OWART CANNERS AND WAY AND	P	Not relative the hardward enduration. The following defines areas compared the tribute. The following defines areas compared the tribute. The following defines areas considered destination and of the control of th	A Roberts A A A B B A A	assumed depending or charge an application	· · ·		@• C	8	•				• @• -	-	- @•		-		- (ĝ• . ĝ• .	-			· ·	- X-Ray insp when sealer	spection may be influenced along is containing Pb
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March 2004-04-10 Deep of transport contribution Part Part Deep of transport contribution Part Deep of	CUNTED CONSTITUTE FRANCISCO CO	PIG-QUA-MI-GD PIG-QUA-GE-GD PIG-QUA-GE-GD PIG-QUA-MI-GD PIG-QU	Country Control (1999) We want to be a second or the control of the country of t	P	Not relative the habitual analysis. The statement is habitual analysis and several manufactures of the several compounds the statement of the	A Ran A A A B B A C C C C	essenance of opportung on charge, and the opportunity of the opportuni	· · · · · · · · · · · · · · · · · · ·	@•	@•	2 · · · · · · · · · · · · · · · · · · ·	•	· · · · · · · · · · · · · · · · · · ·	• • • • • • • • • • • • • • • • • • •		@• -		B - 00 - 00 - 00 - 00 - 00 - 00 - 00 -	• • •	-		- (20 - 20 - 20 -	-			· ·	X-Pay Important with a state of the sta	spection may be influenced sing is containing Pb influenced and property of fluencion affected in case of call sheet distribution change, a subdering and board coating assessed. MSL might be
## ACCURATION OF THE PROPERTY	CUNTED CONSTITUTE FRANCISCO GAMETED CONSTITUTE FRANCISCO CUNTED CONSTITUTE FRANCISCO CONSTITUT	Pri-Cus-In-III Pri-Cus-III Pri-Cus-II Pri	Country Coversion Country Any Country of Country Any Country A	P	Not consent to individual evaluation. The desired definition are seen comprome formation. In Street of Medical definition of the Medical Medical def	A Page A A A A A B B A A C C C C C C C C	assessment depending on charge- son hypothesis.	· · · · · · · · · · · · · · · · · · ·	@•	- (c)			• • •	@Y		@•		B - @ B - @ B - @ B - @ B - B - B - B -	• • •	-		- (20 - 20 - 20 -	-			· ·	X-Day Impose who easie Electrical fi michanical ACI, was characial suppodence	apection may be influenced degli is containing the influenced and is containing the influenced and influenced in case of an ideas debt-blook change and based coaling and based coaling assessment fact, regist to only be influenced.
## ACCURATION OF THE PROPERTY	CAMPE CHISTAL FORM CAMPE CHISTAL	Print Cala Min Bit Min Cala Color Bit Min Cala Color Bit Min Cala Color Bit Min Cala Color Bit Min Cala Min Bit	Country Control (1998) We want of the post of any and approximate and the dark approximate for the post of a post o	P P P Service in the least of must design of change of the particular and the service of the ser	Not received to inclinate an extension of the control of the contr	A Residence of the control of the co	executive of depending on charge exch application.		@ @ @ @ @ @ @ @ @ @ @ @ @ @ @ @ @ @ @	- (c)			· · · · · · · · · · · · · · · · · · ·	@Y		@• -		B B B B B B B B B B B B B B B B B B B	· · · · · · · · · · · · · · · · · · ·	-		- (20 - 20 - 20 -	-			· ·	X-Play Important ACT chack	opedion may be influenced by a milestrative of the contenting Pin Number of the Contenting Number of
## 15-04-05-05 Deeper Terminal Annual Annu	CAMPE CHISTA, FAMO CAMPE CHISTA,	Print Cala Min Bit Min Cala Color Bit Min Cala Color Bit Min Cala Color Bit Min Cala Color Bit Min Cala Min Bit	Country Control (1998) We want of the post of any and approximate and the dark approximate for the post of a post o	P P P Service in the least of must design of change of the particular and the service of the ser	Not received to inclinate an extension of the control of the contr	A Residence of the control of the co	executated depending on their pe- min hyperbolism.		@ @ @ @ @ @ @ @ @ @ @ @ @ @ @ @ @ @ @	- (c)			· · · · · · · · · · · · · · · · · · ·	@Y		@• -		B B B B B B B B B B B B B B B B B B B	· · · · · · · · · · · · · · · · · · ·	-		- (20 - 20 - 20 -	-			· ·	X-Play Important ACT chack	opedion may be influenced by a milestrative of the contenting Pin Number of the Contenting Number of
## 50 0.05 Co. Co. Compared frameworks service finance, degree conference micrors - Cold 1 2 Compared framework in the finance of the conference of the cold	CAMPET CONTROL, FORM CAMPET CONTROL CAMPET	PRE-QUANTED PRE-QUA-CE-SE PRE-QUA-CE-SE PRE-QUA-CE-SE PRE-QUA-GE-SE PRE-QUA-	Consection of deliberary processing of the content	P	Not insert the helicide evaluation. The desired definition are compromed heritodic. In place of definition are compromed heritodic. In place of definition are considered definition or 40, defined of definition and or second or definition and definition	A A A B B A C C B B C C	summeror depending or charge- ment application.		@•	- (c)	\$ • • • • • • • • • • • • • • • • • • •	@•	• • • • • • • • • • • • • • • • • • •	@Y	· · · · · · · · · · · · · · · · · · ·			B - B - B - B - B - B - B - B - B - B -	· · · · · · · · · · · · · · · · · · ·			- (20 - 20 - 20 -	-			· ·	X-Play Important ACT chack	opedion may be influenced by a milestrative of the contenting Pin Number of the Contenting Number of
Mode Compared Females, surface thank, regin, class, generation diseased and pull and	CAMPET CONTROL, FORM CAMPET CONTROL CAMPET	PIC-QUA-M-00 PIC-QUA-M-00 PIC-QUA-M-01 PIC-QUA-M-01 PIC-QUA-M-01 PIC-QUA-M-02 PIC-QUA-M-02 PIC-QUA-M-02 PIC-QUA-M-03 PIC-QUA-M-03 PIC-QUA-M-04 PI	OWATE CAST AND SET OF THE	P	Not retirement to historical residualities. Sectional designation reteres compound to introduce designation are compound to introduce designation are compound to introduce designation and control processed retirements and control processed ret	A A A B B A C C C C C B B C C	execution dispending on disrep-		@•	- @ - @ - @ - @ - @ - @ - @ - @ - @ - @	\$ • • • • • • • • • • • • • • • • • • •		· · · · · · · · · · · · · · · · · · ·	@Y		@ · · · · · · · · · · · · · · · · · · ·		B - B - B - B - B - B - B - B - C - C -	· · · · · · · · · · · · · · · · · · ·			- 1	@•	-			· ·	A Fifty I have when water water water water water water make the control of the c	operation may be influenced using an contenting the contenting and
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THE COLUMN TO TH	CUNTED CONSTRUE, FORMY	PIG-QUA-PIG-ED PIG-QUA-CE-ED PIG-QUA-CE-ED PIG-QUA-CE-ED PIG-QUA-CE-ED PIG-QUA-PIG-ED PI	Constitution of the Section of the S	P	Not relative the hall-cold analysis. The following the first companies the installation. The legities of deficient companies the installation of the legities of deficient companies the installation of the second of the secon	A Rose A A A A A A A A C B B B B C C C B B B B	assumented depending on charge part of special depending on the special			- @• - @• - @• - @• - @• - @• - @• - @•			· · · · · · · · · · · · · · · · · · ·	@Y		@ · · · · · · · · · · · · · · · · · · ·		B - @ - B - B - B - B - B - B - B - B -				- 1 - 1 - 1 - 1	8	-			· ·	Silvy may have selected and sel	appelion may be influenced degree containing the co
1 P Out that follows (a fine control of the contr	CAMPEZ CONTROL, FAMO CAMPEZ CO	PIG-QUA-PIG-ED PIG-QUA-CE-ED PIG-QUA-CE-ED PIG-QUA-CE-ED PIG-QUA-PIG-ED P	Constitution of the Section of the S	P	Not relative the hall-cold analysis. The following the first companies the installation. The legities of deficient companies the installation of the legities of deficient companies the installation of the second of the secon	A Rose A A A A A A A A C B B B B C C C B B B B	execution of depending in other purchase the special data.			- @• - @• - @• - @• - @• - @• - @• - @•	\$		· · · · · · · · · · · · · · · · · · ·	@Y		@ · · · · · · · · · · · · · · · · · · ·		B - @ - B - B - B - B - B - B - B - B -				- 1 - 1 - 1 - 1	8	-			· ·	Silvy may have selected and sel	appelion may be influenced degree containing the co
	CAMPEZ CONTROL, FAMO CAMPEZ CO	PIG-QUA-PIG-ED PIG-QUA-CE-ED PIG-QUA-CE-ED PIG-QUA-CE-ED PIG-QUA-CE-ED PIG-QUA-PIG-ED PI	Country of medical competition - Class State Congreg of medic	P	Not relative the hall-cold analysis. The following the first companies the installation. The legities of deficient companies the installation of the legities of deficient companies the installation of the second of the secon	A Read A A A B B C C C B B C C B B C C B B C C C B B C	executated depending on the rep-	1		- @• - @• - @• - @• - @• - @• - @• - @•	\$		· · · · · · · · · · · · · · · · · · ·	@Y				B - @B - B - B - B - B - B - B - B - B -	· · · · · · · · · · · · · · · · · · ·			- 1 - 1 - 1 - 1	8	-			· ·	Silvy may have selected and sel	appelion may be influenced degree containing the co
## 50-34-568	CAMPIE CHISTAL, FAMI CAMPIE CHISTAL CAMP	PIG-QUA-MIGO PIG-QUA-GE-GI PIG-QUA-GE-GI PIG-QUA-GE-GI PIG-QUA-MIGO	Country Control Country The Country Country Country The Country Country The Country Country The Country	P	Not interest to individual analysis. As a faller of deficient companies formation. In a faller of deficient companies formation. In a faller of deficient companies of deficients In a faller of deficient companies. In a faller of deficient companies. In a string may (pushed) promotion In a string may (pushed) but advance gas In a string may (pushed) promotion In a string may (pushed) promotion In a string may (pushed) In a str	A Paint A A A A A A A A A A A A A A A A A A A	assumment depending on drong put to have p	1			6 6 6 6 6 6 6 6 6 6 6 6 6 6 6 6 6 6 6		· · · · · · · · · · · · · · · · · · ·	@Y			-	B - QB - B - CB - CB - CB - CB - CB - CB				- 1 - 1 - 1 - 1	8	-			· ·	Silvy may have selected and sel	appelion may be influenced degree containing the co
	CAMPIE CONSTAL FORM CONSTAL FORM CONSTAL FORM CAMPIE CONSTAL FORM CONSTAL FORM CONSTAL FORM CAMPIE CONSTAL FORM CONSTAL FO	PIC-QUA-M-00 PIC-QUA-M-00 PIC-QUA-M-01 PIC-QUA-M-01 PIC-QUA-M-01 PIC-QUA-M-02 PIC-QUA-M-02 PIC-QUA-M-02 PIC-QUA-M-02 PIC-QUA-M-02 PIC-QUA-M-02 PIC-QUA-M-03 PI	Compared or analysis compared to the Compared of the Compared	P	As a second to inclinate an execut compound behavior. ***Ballook of delibbor an execut compound behavior. ***Ballook of delibbor an execut compound behavior. ***Ballook of delibbor and executed of delibborior. ***Ballook of delibborior and executed of delibborior. **Ballook of deliborior and executed of deliborior. **Ballook of	A A A B B C C C C C C B B C C C C C C C	security of depending on diving the charged depending on the charged depending on the charged depending on the charged depending dependi	1					· · · · · · · · · · · · · · · · · · ·	@Y				B				- 1 - 1 - 1 - 1 - 1 - 1 - 1 - 1 - 1 - 1	20 - 20 - 20 - 20 - 20 - 20 - 20 - 20 -	-			· ·	Silvy may have selected and sel	appelion may be influenced degree containing the co
THE CONTRACT OF STATE	CAMPE CONSTAL FORM CAMPE CONSTAL	PIG-QUA-MIGO PIG-QUA-GE-GI PIG-QUA-GE-GI PIG-QUA-GE-GI PIG-QUA-MIGO	Compared or analysis compared to the Compared of the Compared	P	Not interest to individual analysis. As a faller of deficient companies formation. In a faller of deficient companies formation. In a faller of deficient companies of deficients In a faller of deficient companies. In a faller of deficient companies. In a string may (pushed) promotion In a string may (pushed) but advance gas In a string may (pushed) promotion In a string may (pushed) promotion In a string may (pushed) In a str	A Paint A A A A A A A A A A A A A A A A A A A	assumed depending to charge and the special depending to charge and the special depending to charge and the special depending.	1					· · · · · · · · · · · · · · · · · · ·	@Y			-	B				- 1 - 1 - 1 - 1 - 1 - 1 - 1 - 1 - 1 - 1	8	-			· ·	Silvy may have selected and sel	appelion may be influenced degree containing the co

		PROCESS																										
CRYSTAL / SAW	PAS-QUA-PR-01	PROCESS Changes in process technology or manufacturing methods - Quartz Blank		Comment Comb Block comme						_									R .			 T . T		- 1				
CRYSTAL / SAW	PAS-QUA-PR-02	Changes in process schoology or manufacturing methods - Stank Etching / Cleaning		Change of Stark DichClean revous	e.g. change of cutting or tapping technology e.g. change from liquid eliching to plasma etching	c		-									@•		В -									
CRYSTAL / SAW		Changes in process technology or manufacturing methods - Blank Elching / Cleaning	- P		e.g. change from liquid etching to plasma etching	е		•								@• -					-			-		-		
	PAS-QUA-PR-03	Changes in process technology or manufacturing methods - Electrode Formation	. P	Change of Electrode Formation process	e.g. change from evaporation to sputtering	С				•		-	• -			• -	@•		В -	• -	-	 -		-		-		
CRISIAL/SAW	PAS-QUA-PRI-04	Changes in process technology or manufacturing methods - Trimming		Change of Auto Trim process (Method of final frequency tuning)		С											@•		в -									
CRYSTAL / SAW	PAS-QUA-PROR	Changes in process sectionary or manufacturing memoral - immining			e.g. change from exaporation to ion beam	е		•		•		-			•	•	@●		ь -	•	-			-		-		
	PAS-QUA-PR-05	Changes in process technology or manufacturing methods - Bonding / Annealing		Change of Blank bonding / annealing process. Change of method how apply conductive meterial to base or blank		с					@• @Y	/ @Y							в -			 	2Υ -					
CRYSTAL / SAW				material to base or blank																		. 6	31					
	PAS-QUA-PR-06	Changes in process technology or manufacturing methods - Can / Cap Attaching	. P	Change of Cap/Can attaching process	e.g. change of the sealing process e.g. change from batch oven to reflow oven	С				•	@• @Y						•		В -	•	-			-		-		
CRTSTAL / SAW	PAS-QUA-PR-07	Changes in process technology or manufacturing methods - Molding	-	Change of Cuprum assuring process. Not relevant for typical SMD.	eg. charge incircated data braidwidth	с																						
CRYSTAL / SAW	PAS-QUA-PROF	Changes in process sectionary or manufacturing memoral - sectoring	- Р	for typical SMD.	e.g. crange or overmos process parameter			•								•	•••		ь •	• •	-	 -		-		+ -		
	PAS-QUA-PR-08	Changes in process technology or manufacturing methods - Marking	. P		e.g. change from inked marking to later marking	В				-		-					-				-	 - 6		-		-		ACI check necessary!
CRYSTAL / SAW			-	Comment to the control of the contro	e.g. making of pp. 1 e.g. change of appearance (additional marking)						_	+		_		_	+		_		_	+				+ -	-	
CRYSTAL / SAW	PAS-QUA-PRI-09	Changes in process technology or manufacturing methods - Aging	- Р	Change of Aging process. Typically no aging done on quartz crystals. Variation within process specification.	temperatures	с			. @•	•		-				•	•		В -	• .	-	 -		-		-		
CRYSTAL / SAW	PAS-QUA-PR-10	Process inlegify: tuning within specification PACKING / SHIPPING - NEW MATERIAL, CRITICAL DIMENSIONS	- P	Variation within process specification.	e.g. process control	С				-								- -	- -			 	- -					
CRYSTAL / SAW					1							_							_			 						
CENSTAL / SAW	PAS-QUA-PN-01	Packing / shipping specification change (loosening of tolerances)		Change of packing specification.	e.g. number of pieces on reel.	В				-		-						- -			-			-		-		
	PAS-QUA-PN-02	Dry pack requirements change		Change of dry pack requirements. (§: Relaxation of dry pack requirements (P): Tightening of dry pack requirements	e.g. change in dry pack assurance (HCC, MESS) (I): MSL 3 -> MSL 1 (P): MSL 1 -> MSL 3	В																						
CRYSTAL / SAW		Dry pack requirements change	I P	(it: Relaxation of dry pack requirements (P): Tightening of dry pack requirements	(I): MSL 3 → MSL 1 (P): MSL 1 → MSL 3				-			-									-			-		-	-	
	PAS-QUA-PN-03	Change of carrier (tray, reel)	P P	Change of carrier	e.g. change by material e.g. change by geometry.	В				-		-					-				-	 -		-		-		
CRYSTAL / SAW	_	PACKING / SHIPPING - VISUAL INSPECTION			eg. crange of geomes.																			_				
	PAS-QUA-PV-01	Change of labeling		Change of labeling, also on real.	(8) e.g. additional information (RoHS stamp) (P) e.g. change of customer specific information	В																						
CRYSTAL / SAW	PAS-QUA-PV-01	Change of labeling	I P	Change of labeling, also on reel.		В				-											-			-		-		
	PAS-QUA-PV-02	Change of product marking		Marking on device.	e.g. change of content of marking	В				_																		
CRYSTAL / SAW	PARAMITA	Charge or product making		manufig on care.	e.g. change of content of marking e.g. change of method of marking e.g. change of appearance of marking																	 		-				
	PAS-QUA-PV-03	Change of packing/shipping specification	P P	Change in packing specification which does not described a change of dimensions or material of the packing.	e.g. change of documentation in packing																	 						
CRYSTAL / SAW				material of the packing.	specification																							
CRYSTAL / SAW		LOGISTICS / CAPACITY / TESTING - EQUIPMEMENT																_									_	
	PAS-QUA-EQ-01	Production from a new equipment/bot which uses a different technology or which due to its unique form or function can be espected to influence the integrity of the final product		Change in process technique which is not already covered above. Note: Changes affecting the product not covered by the table require also a PCN.	e. g. new equipment supplier with different process concept	с													@B -								- @•	Test effort depends on final risk assessment. Performance test according to affected process change.
	780-UUN-ED-01	form or function can be expected to influence the integrity of the final product	F P	Note: Changes affecting the product not covered by the table require also a PC*N	concept	c																				1	@•	Performance test according to affected process change.
CRYSTAL / SAW		+																									_	Test effort depends on final risk
	PAS-QUA-EQ-02	Production from a new equipment/bod which uses the same basic technology (replacement equipment or extension of existing equipment pool)	- P	PCN required for dedicated equipment for sensitive component production.	e.g. additional equipment to increase production capacity	с				-		-					-		<u>@</u> B -		-	 -		-		-	- @•	Test effort depends on final risk assessment. Performance test according to affected
CRYSTAL / SAW					e.g. replacement of same equipment												+				\perp	+				\perp	فالم	process change.
	PAS-QUA-EQ-03			Change of final test equipment which use different technology.	e.g. change of teater platform	с													@B -									Gage RSR / delta correlation
CONCERN CONTRACTOR	/AD-UUN-EID-63	Change in final test equipment type that uses a different technology	PP	Change of final test equipment which use different technology. PCN required for dedicated equipment for sensitive parameters.	way wange or sessor pastorm	С						-							Ro .							-	- @•	wegle HBH/ data correlation
CRYSTAL / SAW	_	LOGISTICS / CAPACITY / TESTING - PROCESS FLOW				_				_																	_	1
				Change of manufacturing site.	e.g. movement or transfer of manufacturing site or process step(s) to a different location/wise.																							
	PAS-QUA-PF-01	Manufacturing sile transfer or movement of a part of production process to a different location/site	P P	Change of manufacturing site. Includes transfer as well as additional site. Note: Reorganization inside one plantfeite is not affected.		В			•	•		•	• •				•		в •	• •	-	 -		-		-	@•	
CURYSTAL / SAW	PAS-QUA-PF-02	Elimination or addition of a manufacturing process step	-	to middled	e.g. dual source / fab strategy e.g. seating / cleaning process	С												_									-	Characterisation depends on impact of monkering first
CORYSTAL / SAW	PAS-QUA-PF-02		- P	Change of manufacturing process sequence.	e.g. change of order of processes	С						1			لنانا				- -		لتل		- -		- - -	لتا	. @•	production flow.
CORYSTAL I SAW		LOGISTICS / CAPACITY / TESTING - Q-GATE			a n channe from 100% to recent increase.				_			1							-1		-	 				1 -	_	
	PAS-QUA-QG-01	Change of test coverage used by the supplier to ensure data sheet compliance (e.g., elimination/addition of electrical measurement/lest flow block, relaxation/enhancement of monitoring procedure or sumpling)	. P	Change of test coverage.	e.g. change from 100% to sample inspection e.g. test flow block, reduction from three to two temperature measurements	с				-											-			-		-		R (electr funct.): set coverage. R (reliability) only for change in burn in
CRYSTAL / SAW					e.g. change in burn in/run in process.																							ргосевя.
		ALUMIUM ELECTROLYTIC CAPACITORS																										
	_	ANY		Interview to be used if no other type of change	1							_							_			 					-	
	PAS-ALU-AN-01	Any change with impact on agreed upon technical contractual agreements	P P	Intended to be used if no other type of change is applicable but the change affects agreed technical contractual agreements.	Not relevant for technical evaluation.					-		-					-	- -			-	 -		-		-		
	PAS-ALU-AN-02	Any change with impact on processability/manufacturability at customer, which is not covered in the matrix below.	р р		Technical interface means component terminals. See processability on board level.	В															-					-	@• -	
		THE TRADES DATASHEET			See processability on board level.										-							 					6.	
					I							1					T T	-				T T						
	PAS-ALU-DIS-01	Change of datasheet parameters/electrical specification (min/max/hyp. values) and / or AC/DC specification	P P	Change of application relevant information Not included: Editorial changes.	e.g. Sighten of electrical parameter distribution	A	Risk assessment depending on change for each application.			-		-						- -			-			-		-		
				No technical change of product, process or test. New description of behavior which was not specified before or which is different from testal specification. Please redicate clearly, that Infoncie contains this type of change!																								
				New description of behavior which was not																								
	PAS-ALU-DS-02	Correction of data sheet or issue of errats	1 1	specified barons or which is different from initial specification.	e.g. data sheet correction because of new information about component behavior	A				-		-					-	- -			-	 -		-		-		
				this type of change!																								
				Resourced in analysis required																								
				parameter.																								
	PAS-ALU-DIS-03	Specification of additional parameters	I P	(i): no influence	e.g. adding new (tested) parameter.	A				-		-					-				-	 -		-		-		
				Disscription of a new not previously covered parameter. No technical change of the product. (In the influence (IP): Risk assessment depending on change for such application to provide evidence of additional parameters (stat. evaluation)																								
				additional parametes (stat. evaluation)																		 				\perp		
	_	MATERIAL			1	1	Consider effect on surface tension	_				_										 				т т		
							Consider effect on surface tension, mechanical robustness or thermal properties																					
	PAS-ALU-MA-01	Change of material composition - Housing	PP	Change of housing	e.g. change Al alloy for housing	С		•	-	•	- •	-		•		@• -	•	- -	-		-	 -		-		-		
							E: only if a cap holder holds the capacitor body by pressing.																					
			1 1				B: in case of external surface of sealing is changed.																					
	PAS-ALU-MA-02	Change of material composition - Sealing	РР	Change of sealing	e.g. change of rubber compound e.g. change of sealing disc material (axial, Snap in)	с				•		•	• •	• -	• -	@• @5	•		-		-	 -		-		-		
			$\perp \perp$	4			(Consider gluing, laquering, coating of PCB, nano coating, washing,)																				السابك	
	PAS-ALU-MA-03	Change of material composition - External Insulation	P P	Change of external insulation / sleeving	e.g. change from PVC into PET e.g. change of color	С	S: Only for glued capacitors.		@•	•	- •	@•		• -	• -	- @9			- •		-	 -		-		-		Stated Humidity test can be done without applying voltage.
							A: in case of change of lead material							_			-											wholes I wonde
	PAS-ALU-MA-04	Change of material composition - Lead / Termination	P P	Change of lead or outer termination.	e.g. change of lead from iron into copper e.g. change of lead finish from tin/lead into tin	В	A: in case of change of lead material (consider vibration, valid only when the all caps are not additionally fixed in the			-		-		- •			-		В -		-	 -		-		-	@•	
		1										+									-		_	-		+	_	
	PAS-ALU-MA-05	Change of material composition - Internal Insulation / Paper	P P	Change of paper type / internal insulation	e.g. change of paper thickness 50 µm to 40µm	С	A: Only if impedance increase (delta characterization). Check if datasheet is affected (PAS-ALU-05-01).			•		-	• -				-		В -		-			-		-	- @•	
		1					A. Oak (Francisco Instance)												_		-		_	-		+		
	PAS-ALU-MA-06						about a impedance increase (delta														-	 •		-		-	- @•	
		Change of material composition - Electrolyte		Change of electrolyte	e.g. change in formulation		Characteristics), Chick I Calabrellia		•	•		-	• .				•	• -	В -									
	PAS-ALU-MA-07					c	A: Only if impedance increase (delta characterization). Check if datasheet is affected (PAS-ALU-05-01).					-				- ·	•		в -			 		-				
	PAS-ALU-MA-07 PAS-ALU-MA-08				e.g. change in formulation e.g. change of glue or basis material e.g. change of used plastic material	C B						-				@•	-		 B -									
	PAS-ALU-MA-07 PAS-ALU-MA-08			Change of closing tape material	e.g. change of glue or basis material	С		· ·				-	@• -			@• - @• @•	-			: :								Test effort depends on final risk
	PAS-ALU-MA-08	Change of malerial composition - Tapa Malerial Change of malerial composition - Seas Pale	P P	Change of closing tape material Change of base plate material	e.g. change of glue or basis material e.g. change of used plastic material	B				@• @•		-	@• -			@• @•			: :	: :	-							Test effort depends on final risk assessment. Performance test according to affected
	PAS-ALLI-MA-OS PAS-ALLI-MA-OS PAS-ALLI-MA-OS		P P		e.g. change of glue or basis material e.g. change of used plastic material	С					· ·	-	@• -	 		@• . @• @•		: :			-					-	- @•	Test effort depends on final risk assessment. Performance test according to affected material. Assumption material specification
	PAS-ALLI-MA-00	Diarque of material composition - Tigos finiterial Diarque of material composition - Bases Plate Diarque of mageline of material Diarque of supplier of material	P P	Change of closing tape material Change of base plate material	e.g. change of glue or basis material e.g. change of used plastic material	B				@• @•		-	@• -			@• @•			: :		-	 -		-		-	- @•	Test effort depends on final risk assessment. Performance test according to affected resterial. Assumption material specification nemains unchanged. Otherwise see change of material.
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	PAS-ALU-PR-06	Changes in process technology or manufacturing methods - Trim & Form Leaded			e.g. change of tooling shape or bending procedure	В		•	-		-		-	@• -	-			-			-		-			-	-	-	-		-	Solderabilit	By may be influenced
	PAS-ALU-PR-GT	Changes in process technology or manufacturing methods - Trim & Form SMD	. Р	Change of trim & form process (SMD)	e.g. change of tooling shape or bending procedure	В			-		-		-	- •@	-	- @•		- 6	@• -	- @•	@•		-				-				-	Solderabilit	ity may be influenced
		Process inlegitly: tuning within specification		Variation within process specification.		С			-		-		-					-			-		-			-		-	-				
Ī		PACKING / SHIPPING - NEW MATERIAL, CRITICAL DIMENSIONS			*																												
	PAS-ALU-PN-01	Packing / shipping specification change (loosening of tolerances)	P P	Change of packing specification.	e.g. number of pieces on real.	В												-					-					-	-				
									_		+		+ +				_			_	+	_	-	_	_	+		\rightarrow	-	_	_		
	PAS-ALU-PN-02	Dry pack requirements change	I P	Change of dry pack requirements. (R: Relaxation of dry pack requirements (P): Tightening of dry pack requirements	e.g. change in dry pack assurance (HIC, MES) (I): MSL 3 -> MSL 1 (P): MSL 1 -> MSL 3	В					-		-		-			-			-		-			-	-	-	-		-		
	PAS-ALU-PN-03	Change of carrier (tray, reel)		(P): I greening or dry pack requirements Change of carrier	e.g. change by material e.g. change by geometry.	В														_	1 1				_	+		-+	-		_		
-		PACKING / SHIPPING - VISUAL INSPECTION	PP		e.g. change by geometry.		L			- -	<u> </u>					<u> </u>	- -		- -														
-	PAS-ALU-PV-01			1	Mary additional information (Mail Colone)																				_	_							
	PAS-ALU-PV-01	Change of labeling	I P	Change of labeling, also on reel.	(f) e.g. additional information (RbHS stamp) (P) e.g. change of customer specific information	В			-				-		•			-					-			-	-	-	-				
	PAS-ALU-PV-02	Change of product marking	ı P	Marking on device.	e.g. change of content of marking e.g. change of method of marking e.g. change of appearance of marking	В																	- 1										
					e.g. change of appearance of marking																					1							
	PAS-ALU-PV-03	Change of packing/shipping specification	p p	Change in packing specification which does not described a change of dimensions or material of the packing.	e.g. change of documentation in packing																		- 1										
			$oldsymbol{oldsymbol{\sqcup}}$	material of the packing.	specification										oxdot								\bot										
	_	LOGISTICS / CAPACITY / TESTING - EQUIPEMENT		1	1		1		_		т т		т т		г т											_	г т				_	_	
	PAS-ALU-EIQ-01	Production from a new equipment/tool which uses a different technology or which due to its unique form or function can be expected to influence the integrity of the final product		Change in process technique which is not already covered above. Note: Changes affecting the product not covered by the table require also a PCN.	e. c. new equipment supplier with different process	с						_						_	- B					_							@•	Test effort o	depends on final risk nt.
	PAS-ALD-EIG-UI	form or function can be especied to influence the integrity of the final product	P P	Note: Changes affecting the product not covered by the table require also a PCN.	e. g. new equipment supplier with different process concept					• -			1 1	• •				•	- -				- 1			1	-	-	-		e.	Performan process ch	nt. nos test according to affe hange.
																				_	1 1				_	+		-+	-		_	Test effort	depends on final risk
	PAS-ALU-EQ-02	Production from a new equipment/boil which uses the same basic technology (replacement equipment or extension of existing equipment pool)	- P	PCN required for dedicated equipment for sensitive component production.	e.g. additional equipment to increase production capacity e.g. replacement of same equipment	с		• •		• -	-	- •	-		-			•	- B		-		-	•		-	-	-	-		@•	Performan	depends on final risk et. nos test according to affe hance.
					e.g. repacement of same equipment				_		+		+ +				_			_	+	_	-	_	_	+		\rightarrow	-	_	_	process ch	hanos.
	pas-autorom	Chance in final test equipment type that uses a different technology		Change of final test equipment which use different technology. PCN required for dedicated equipment for sensitive parameters.	e.c. change of tester platform	c													- @B												@•	Gang Pres	7 / delta correlation
	PASALULUS.	Company on the same appropriate the same a constant according	P P	PCN required for dedicated equipment for sensitive parameters.	eg. Crange Cranan pascers								1 1					-	. 60				- 1			1	-	-	-		e.	Gago ran	C) data containon
		LOGISTICS / CAPACITY / TESTING - PROCESS FLOW									_		_								_			_		_	_			_			
				Change of manufacturing site. Includes transfer as well as additional site. Note: Reorganization inside one plantisite is	e.g. movement or transfer of manufacturing site or process step(s) to a different location/site.	В													• B														
	PAS-ALU-PF-01	Manufacturing site transfer or movement of a part of production process to a different location/site	PP	Note: Reorganization inside one plant/site is not effected.	a.c. draf arrana / fab start	В		•	•	• @•	•		•		•	•	•	•	• B		•			•							@		
	PAS-ALU-PF-02	Elimination or addition of a manufacturing process step	. Р	not affected. Charge of manufacturing process sequence.	e.g. washing / cleaning process	С			-		-		-		-			-			-		-			-	-	-	-		@	Characteri	isation depends on impa
	PAS-ALU-PT-03	Elimination of final electrical measurement / feet flow block	1 -	Reduction of final testing. PCN required for dedicated final test	e.g. elemination of additional impedance control	С			-																						0.	Characteri	isation depends on impa low.
		LOGISTICS / CAPACITY / TESTING - Q-GATE	1.1.	reductions for sensitive parameters.							لنا		للنا	لنظ	_لــــــــــــــــــــــــــــــــــــ								للنا				لنا				8.	final test fic	DW.
					e.c. change from 100% to sample insperies								1																				
	PAS-ALU-QG-01	Ohange of feat coverage used by the supplier to ensure data sheet compliance (e.g., slimination/addition of electrical measurement/lest flow block, releastion/enhancement of monitoring procedure or sampling)	. P	Change of test coverage.	e.g. change from 100% to sample inspection e.g. test flow block, reduction from three to two temperature measurements e.g. change in burn in/run in process.	С					-		-		-			-			-		-			-	-	-			-	R (electr. fi R (reliability	funct.): test coverage. by) only for change in bu
		monitoring procedure or sampling)	$\perp \perp$		e.g. change in burn in/run in process.																											ргосевя.	
		NTC																															
		MI .		Intended to be used if no other type of chance							1		1 1																		_		
	PAS-NTC-AN-01	Any change with impact on agreed upon technical contractual agreements	P P	Intended to be used if no other type of change is applicable but the change affects agreed technical contractual agreements.	Not relevant for technical evaluation.				-		-		-		-			-			-		-				٠.	-	-				
	PAS-NTC-AN-02	Any change with impact on processability/manufacturability at outsomer, which is not covered in	р р	-	Technical interface means component terminals.	В			-		-		-		-			-			-		-			-		-	-	- @•			
		DATASHEET								_		_																					
	PAS-NTC-DS-01	Change of datasheet parameters/electrical specification (min/max/lyp. values) and / or ACIDC specification	Р Р	Change of application relevant information	e.g. Sighten of electrical parameter distribution	A	Risk assessment depending on change		-				-					-					-			-		-	-				
		secrosen		No technical change of product, process or			tor each accertaion.																			+		_			_		
				No technical change of product, process or test. New description of behasion which was not specified before or which is different from tritial specification. Please indicate clearly, that Infonoise contains this type of change! Assessment in application required?!																													
	PAS-NTC-DS-02	Correction of data sheet or issue of errats	1 1	specified before or which is different from initial specification.	e.g. data sheet correction because of new information about component behavior	A			-		-		-		-			-			-		-			-	-	-	-		-		
				Please indicate clearly, that Infonds contains this type of change!																													
				Assessment in application required? Description of a new not previously covered.									+ +			_		-		_	-			_		+		-	-		+		
				Assumers in apparation required: Description of a new not previously covered parameter. No technical change of the product. (I): no influence (PF): That assessment depending on change for each application to provide evidence of additional carameters into: evaluation)																													
	PAS-NTC-DS-03	Specification of additional parameters	I P	(B: no influence (PI: Risk assessment depending on change for	e.g. adding new (tested) parameter.	A			100		-		-		-			-			-		-			-	-	-	-		-		
				each application to provide evidence of additional parameter (stat. evaluation)																													
		MATERIAL																															
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			РР	Change of Sinder Material to bind ceramics.		С		-	-		-		1-1		- (ე• -	@• @•	-					-			-	-	-	-				
	PAS-NTC-MA-01	Change of material composition - Ceramic Binder	P P	Change of Binder Material to bind ceramics. Change of ceramic composition					-		-		-							_			-			-	-	-	-			Parameter an anticipa	r analyse only necessary
			P P	Change of Sinder Material to bind ceramics. Change of ceramic composition ceramic material class will not be changed, only dopards will be changed.	e.g. changes in additives amount	c					-		-			• .	@• @•						-			-	-	-	-		@•	Parameter an anticipa performanc 5 = SMO d	r analyse only necessary sted impact on electrical rice. device only
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	PAS-NTC-MA-01	Change of material composition - Ceramic Binder	РР	Change of ceramic composition ceramic material class will not be changed, only dopands will be changed	e.g. changes in additives amount e.g. changes from AgPt material to AgPd material			· · ·	•	 	-	 	-	 						_	-	 	-	 		-	-	-	-	 	@•		r analyse only recessary sted impact on electrical ros. device only
	PAS-NTC-MA-03 PAS-NTC-MA-03	Change of makerial composition - Commits Binder Change of makerial composition - Commits Change of makerial composition - New Electrode	РР	Change of ceramic composition ceramic material class will not be changed, only dopends will be changed. Change of more electrode material (ink material). Valid in case of multileyer shuctures only.	e.g. changes in additives amount e.g. change from AgPI malerial to AgPII malerial	c			•		\vdash		-			• - 	• • • •	-	• @B	• @s	-	 	-			-	-	-	-	 	@•	,	
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	PAS-NTC-MA-03 PAS-NTC-MA-03	Change of makerial composition - Commits Binder Change of makerial composition - Commits Change of makerial composition - New Electrode	P P	Change of ceramic composition ceramic material class self not be changed, only doppered self to changed. Change of inner electrods material (pil- material). Valid in case of multilayer shuckness only. Change of encapsulation material.	e.g. changes in additives amount e.g. change from AgPt material to AgPd material e.g. change of cooling e.g. change of additives in an insulation.	c	A: Plak assessment on application lend, if interaction with other material expected. Consider explicity usage where NCC is not mounted on PCB.		•		\vdash		-	· · · · · · · · · · · · · · · · · · ·		• - 	• • • •	-	• @B	• @s	-	 	-	 		-	-	-	-	 	@•	,	
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PAS-NTC-EQ-01	Production from a new equipment/boil which uses a different technology or which due to its unique		Change in process technique which is not already covered above.	e.g. change from wet to dry technology.	с												@B -										- @•	Test effort depends on final risk assessment.
PASAICESOI	Production from a new equipment/bod which uses a different technology or which due to its unique form or function can be expected to influence the integrity of the first product.	, ,	Note: Changes affecting the product not covered by the table require also a PCN.	e. g. change from wet to dry sectnology.	·												@D -										. @•	process change.
PAS-NTC-EQ-02	Production from a new equipment/bol which uses the same basic technology (replacement equipment or extension of existing equipment pool)	. Р	PCN required for dedicated equipment for sensitive component production.	e.g. elimination of manual handling processes	с				-								@B -				-		-			-	- @•	Test effort depends on final risk assessment. Performance test according to affected process change.
PAS-NTC-EQ-03	Change in final test equipment type that uses a different technology	РР	Change of final test equipment which use different technology.	e.g. change of leater platform	С												@B -										- @•	
	LOGISTICS / CARACITY / TESTING . PROCESS II OW		sensow parameters.	eg. Carge Crasas pascers													60 -								ــــــــــــــــــــــــــــــــــــــ	ш		Calgo Part Galactinasti
PAS-NTC-PF-Q1	Manufacturing site transfer or movement of a part of production process to a different location/site	РР	Change of manufacturing site. Includes transfer as well as additional site. Note: Reorganization inside one plantitate is and affected.	e.g. movement or transfer of manufacturing site or process step(s) to a different location/site.	В												в •				-		-			1.1	@• @•	
PAS-NTC-PF-02	Elimination or addition of a manufacturing process step		not affected. Change of manufacturing process sequence.		С													1									- @•	
	LOGISTICS / CAPACITY / TESTING - Q-GATE																							_				production flow.
PAS-NTC-QG-01	Change of test coverage used by the supplier to ensure data sheet compliance (e.g., elimination/addition of electrical measurement/less flow block, relixed/orien/hancement of monitoring procedure or sampling)	. Р	Change of fast coverage.	e.g. change from 100% to sample inspection e.g. test flow block, reduction from three to two temperature measurements e.g. change in burn infrum in process.	с																		-				- @•	Characterisation depends on impact of test coverage. R (electr. funct.): test coverage. R (reliability) only for change in burn in
	monitoring procedure or sampling) PTC	ш	L	e.g. change in burn infrun in process.																						ш	نلك	R (reliability) only for change in burn in process.
	ARY		Intended to be used if no other hose of change		_	T																			_	=		_
PAS-PTC-AN-01	Any change with impact on agreed upon technical contractual agreements Any change with impact on processability/manufacturability at customer, which is not covered in the mention below.	РР	Intended to be used if no other type of change is applicable but the change affects agreed technical contracted assessments		•			-	•												-		-		4	1		
PAS-PTC-AN-02	Pay charge with reject on processability translationary at customer, which is not covered in the traits below. DATASHEET	P P		Technical intertace means component terminals. See processability on board level.	В			-	-											. -	-	- -	- 1	- -	1		@• -	
PAS-PTC-DS-01	Change of datashset parameters/selectrical specification (ntn/max/hyp. values) and / or ACIDC specification	РР	Change of application relevant information Not included: Editorial changes.	e.g. lighten of electrical parameter distribution	А	Risk assessment depending on change for each application.		-	-												-		-					
			Not included: Totinair changes are not all whether of the product, process or set. In the change of the change of the level description of behavior which was not recited apportunition. If different hom recited apportunition, and the change of pleases included clarify, that inforces corbains pleases included clarify, that inforces corbains description of a more of products of the control of the corporation of the control of the corporation of the control of the corporation of (I)*: Fig. as assessment departuring on change for the control of the corporation of (I)*: Fig. assessment departuring on change for the control of the corporation of (I)*: Fig. assessment departuring on change for the control of (I)*: Fig. assessment departuring on (I)*: Fig. assessment	1																								
PAS-PTC-DS-02	Correction of data sheet or issue of emats	1 1	New description of behavior which was not specified before or which is different from initial specification.	e.g. data sheet correction because of new information about component behavior	A			-	-												-		-			/ - /		
			Please indicate clearly, that Infoncte contains this type of change! Assessment in application required?																									
PAS-PTC-DS-03	Specification of additional parameters		Description of a new not previously covered parameter. No technical change of the product.	e.g. adding new (tested) parameter.	A																					/ /		
	April 10 and 10 and and 10 and and 10		(P): Risk assessment depending on change for each application to provide evidence of whitened naremakes (shift makeston)	r g. many me (man) per armer.	_																					/II I/		
PAS-PTC-MA-01	MATERIAL Change of material composition - Ceramic Binder		Change of Sinder Malerial to bind ceramics.		С			i.			T . T .		T.T.	@• -	@• @•			T.T.					1.1			一		
PAS-PTC-MA-02	Unange of material composition - Ceramic pander Change of material composition - Ceramic	P P		e.g. changes in additives amount	c									• .			@B •	@s -									- @•	Parameter analyse only recessary if an anticipated impact on electrical
PAS-PTC-MA-03			only depends will be changed Change of polymer composition	eg crage ii azawa ancos	c						@• @•		- @•		@• -		@B @								#	#	- @•	5 = SMD device only
						A: Risk assessment on application lesst, if interaction with other material expected. Consider explicitly usage where PTC is not mounted on PCB.							. @•															
PAS-PTC-MA-GI	Change of material composition - Encapsulation	РР	Change of encapsulation material.	e.g. change of costing e.g. change of additives in an insulation.			• •	٠	•	•	@• -				@•		@B @		-		-		-				- @•	Parameter analyse only recessary if an anticipated impact on electrical performance.
PAS-PTC-MA-05	Change of material composition - Lead material / Termination	РР	Change of lead (finish) material, termination material or attachment material.	e.g. change from SnPb to pure Sn	В	Risk assessment needed to evaluate compatibility of soldering process.		-	-	- @•	@• @•		@• -	@• -		@• @•	@B -	@• @•			-		-			/ - /		
PAS-PTC-MA-05	Change of supplier of material	. Р	Change to a new or additional material supplier at component manufacturer.	e g. for 2nd source purpose	С			-	•								В •				-		-			- 1	- @•	Assumption material specification remains unchanged. Otherwise see chance of material.
	DESIGN		O		1																				_			
PAS-PTC-DE-01 PAS-PTC-DE-02	Changes of fermination, surface finish, shape, color, appearance or dimension shockers - Lead Diameter Changes of fermination, surface finish, shape, color, appearance or dimension shockers - Sermination Area			e.g. change lead diameter from 0.5 to 0.4 mm e.g. change of termination layer thickness e.g. change in termination dimensions	A B		•		-	- @•							@B -	@• @•			-		-		4	44	- @•	
PAS-PTC-DE-03	Changes of termination, surface finish, shape, color, appearance or dimension structure - Internal Connection	I P	Change of inner connection	e.g. change in termination dimensions e.g. change from soldered connection to welded connection	С								@• -	@• -		@• @•	@B -	@• @•							+	+	- @•	SMD components only!
PAS-PTC-DE-04	Consecutors Apparation fermination, surface finish, shape, color, appearance or dimension structure - Apparations	I P	Change of appearance. Note: Marking on device is defined as separate chance (PAS-PTC-PV-02). Change of electrode layer thickness or	e.g. change or adding of color on component Mainly in combination with other changes!	В																		-					
PAS-PTC-DE-05	Changes of inner construction - Electrode	. Р	Separate change (PAS-PTC-PV-02). Change of electrode byer thickness or geometry.	e.g. change of electrode design	С			-	@• @	2• -		- @-			@• @•			@• @•			-		-			1 - 1	- @•	
PAS-PTC-DE-06	Changes of inner construction - Layer Thickness	. Р	Change of ceramic layer thickness. For multi- layer technology only.	e.g. change from 1.5µm into 1.0µm	с			-	@• @	⊉• -		- @			@• @•			@• @•			-		-			-		
PAS-PTC-DE-07	Changes of inner construction - Number of Layers	. Р	Change of number of ceramic or electrode layers. For multi-layer technology only. Always in combination with PAS-PTC-DE-06.	u see also layer thickness	с			-	@• 6	2• -		- @-			@• @•			@• @•			-		-					
	PROCESS																							_			_	
PAS-PTC-PR-01			Change of lamination / press technique technology	e.g. stamp press to isostatic press	С		•				@• -				@• @•			@• -			-		-		4	4-	- @•	
PAS-PTC-PR-02 PAS-PTC-PR-03	Changes in process technology or manufacturing methods - Firing			e.g. temperature and / or time and / or atmosphere. e.g. from tunnel to batch kiln.	c		•		@• @		- @•					@• -	@B -				-		-		4	44	- @•	
PAS-PTC-PR-04	Changes in process technology or manufacturing methods - Dicing Changes in process technology or manufacturing methods - Termination	. Р		e.g. change from cutting to sawing				@•						@• -			-				-				÷	+	- @•	
PAS-PTC-PR-05											@• -												- 1					
PAS-PTC-PR-06	Changes in process technology or manufacturing methods - Electrode apply		or apply of termination base layer. Change of electrode apply. For multi layer	g e.g. change in plating technology (final termination) e.g. change from dp in paste to plating (apply)	В		• •		-				• •	•											_	N - 1		
PAS-PTC-PR-07	Changes in process technology or manufacturing methods - Assembly	. Р	Change of electrode apply. For multi layer technology only.	e.g. change of inner electrode by down method.	C B		· ·	@•		 	• • @• ·		• •	• .	@• @•	@• -	@B -	@• -					-		-		. @•	
	Process inlegify: tuning within specification	. P	Change of electrode apply. For multi layer technology only. Change in assembly process for leaded or encapsulated devices.	e.g. change of inner electrode by down method. e.g. soldering method for lead attach to element or coating / encapsulation process	С		• •	@•			• • @• ·		• •	• .			@B -	@• -				 	-			-	- @·	
DAS-PTT-PN-01	Process inlegify: turing within specification PACKING / SHIPPING - NEW MATERIAL, CRITICAL DIMENSIONS	. P	Change of electrode apply. For multi layer technology only. Change in assembly process for leaded or encapsulated devices. Variation within process specification.	e.g. change of inner electrode lay down method. e.g. soldering method for lead affach to element or coating in excepsulation process e.g. process control	С В С		· ·	@•		 	• • @• ·		• •	• .	@• @•	@• -	@B -	@• -			-	 	-				- @•	
PAS-PTC-PN-01 PAS-PTC-PN-02	Process integrity: furing within specification PACKING / SHIPPING - NEW MATERIAL, CRITICAL DIMENSIONS Device: Judgment of Processing Advances of Page 1999	- P	Charge of sectods apply, For multi layer sectors apply only. Charge in assembly process for leaded or encapsulated devices. Variation within process specification. Charge of packing specification. Charge of dry pack requirements.	e.g. change of inner electrode by down method. e.g. soldering method for lead attach to element or coating if encapsulation process e.g. process control e.g. process control e.g. number of piaces on reed. e.g. change in dry pack assurance (MC, MED)	C B C		· ·	@• •		 	• • @• ·			• .	@• @•	@• -	@B -	@• -			-		-				- @	
PAS-PTC-PN-01 PAS-PTC-PN-02 PAS-PTC-PN-03	Process inlegify: being withs specification PACKING SIMPING - NEW MATERIAL, CRITICAL DIMENSIONS Packing / Alighing specification charge (cossing of fallerances) Dry pack regularments charge	- P - P - P	Charge of sectods apply, For multi layer sectors apply only. Charge in assembly process for leaded or encapsulated devices. Variation within process specification. Charge of packing specification. Charge of dry pack requirements.	e.g. change of inner electrode by down method. e.g. soldering method for lead attach to element or coating if encapsulation process e.g. process control e.g. process control e.g. number of piaces on reed. e.g. change in dry pack assurance (MC, MED)	С В С		· ·	@•		 	• • @• ·	· · · · · · · · · · · · · · · · · · ·		• • • • • • • • • • • • • • • • • • •	@• @•	@• -	@B -	@• -					-				- @•	
PAS-PTC-PN-02 PAS-PTC-PN-03	Process singlety, turing within your flushor MACKING, ISBAPHIGO - NEW MACKING, CERTAIN, CORRECTIONS Privally diving up station during biomarcy of biomarcy Day part represents cargo Day part represents cargo Day part represents cargo DAY, DAY, DAY, DAY, DAY, DAY, DAY, DAY,	- P - P - P - P	Owege of electrols apply. For mall layer submissing only. Owege is assumed process for leaded or encoupsibled discours. Variation within process specification. Owege of packing specification. Owege of by pack requirements. (i) Relation of by pack requirements of the packing specification of the packing specification. Owege of dry pack requirements. (ii) Relation of the pack requirements. Owege of center	e.g. Change of term shocks by down method. e.g. soldening method for level about to advened or coming? recognishing processes e.g. process control e.g. proc	C B C B B B		· ·	@• •		 	• • @• ·	· · · · · · · · · · · · · · · · · · ·		• • • • • • • • • • • • • • • • • • •	@• @•	@• -	@B -	@• -					-				- @·	
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PAS-PTC-PN-02 PAS-PTC-PN-03 PAS-PTC-PV-01 PAS-PTC-PV-02	Private Happy, being with qualitation PACHASE (SEMPLE), was well-trial, CAPICAL SHEAMONS PACHASE (SEMPLE), with a well-trial, CAPICAL SHEAMONS Dry to harmy properties shape Compared in this pack, SEMPLE, SEMPLE, VIDEA, REPIETEN Compared in this pack, SEMPLE, SEMPLE, VIDEA, REPIETEN Compared in this pack, SEMPLE, SEMPLE, VIDEA, REPIETEN COMPARED SEMPLE, VIDEA, VI	- P - P - P - P - P - P - P - P - P - P	Owege of electronic apply. For mall layer submixing only. Owege is assumed process for leaded or encoupulated divine. Variation within process specification. Owege of pucking specification. Owege of pucking specification. Owege of pucking specification. Owege of specific specification. Owege of specific specification. Owege of short specification. Owege of careful specification. Owege of careful specification. Owege of careful specification of specification sp	App distingue of traver admitted by diston method. App distingue of traver admitted by diston method. App distingue of travers admitted by distinguish of travers admitted by	C B B B B B B B		· ·	@• •		 	• • @• ·	· · · · · · · · · · · · · · · · · · ·		• • • • • • • • • • • • • • • • • • •	@• @•	@• -	@B -	@• -									- @	
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PMS PTC PM-02 PMS PTC PM-03	Prison (Agrin) - Long settin quadradia ARRADIS (Service S. TWA SERVICE ARRADIA SERVICES) ARRADIS (SERVICE S. TWA SERVICES) ARRADIS (SERVICES)	- P - P - P - P - P - P - P - P - P - P	Owage of sections age; for read layer interesting out. Owage of sections age; for read layer interesting out. Owage of sections age of the section of the section of the sections of the sections. Owage of sections generalized interesting of the sections of the process agent for sections. Owage of sections generalized interesting of the section of	La change of the materials by seen related to the control of which the c	C 8 8 8 8 8 C C C C C		· ·	@• •		 	• • @• ·			· · · · · · · · · · · · · · · · · · ·	(a) (b) (c) (c)		@B											Tax after depends on that can Partners be an excellent of which Partners be an excellent of which has been been been been been been been bee
PMS PTC PM-02 PMS PTC PM-03 PMS PTC PM-03 PMS PTC PM-03 PMS PTC PM-04	Private Indign's Leving within quantum (CATOLAL DELINIONS) **PARTIES SERVICE - NEW WITTERS, CATOLAL DELINIONS **PARTIES SERVICE - NEW WITTERS, CATOLAL DELINIONS **PARTIES SERVICE - NEW WITTERS *	- P P P P P P P P P P P P P P P P P P P	Owage of section and to Person layer of the Continues of	In a finite price of manufacturing plane and and a second of a sec	C 8 8 8 8 8 C C C C C		· ·	@• •		 	• • @• ·			• • • • • • • • • • • • • • • • • • •	@• @•		@B											Sea offer deposits on find of the Communities are assembly to direct Communities and the communities are assembly to direct Communities are a
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PAS-VDR-DS-01	Change of datasheet parameters/electrical specification (min/max/typ. values) and / or ACIDC specification	P P	Change of application relevant information Not included: Editorial changes.	e.g. Sghlen of electrical parameter distribution	A	Risk assessment depending on change for each application.																										
	spectrication		No technical change of product, process or			for each approach.																			+				\vdash			_
PAS-VOR-05-02	Connection of data sheet or issue of emale	1 1	sea. New description of behavior which was not specified before or which is different from smills specification. Please indicate clearly, that infoncts contain this type of change! Assessment in application required?	e.g. data sheet correction because of new information about component behavior as	A			-		-		-	- -		-		- -	-	-				-		-	-	-		-	-	- -	
PAS-VDR-DS-03	Specification of additional parameters	I P	Disscription of a new not previously covered parameter. No technical change of the product. (it is influence (P): Role is assument depending on change such application to provide exidence of additional parameters (stat. evaluation)	e.g. adding new (leated) parameter.	A			-		-	-	-			-				-	-							-		-	-		
	MATERIAL																															
PAS-VOR-MA-01	Change of material composition - Ceramic Binder	РР	Change of Binder Material to bind ceramics.	t.	С			٠		-	-	-					@• @		-	-			-		-	-	-		∸	-		_
PAS-VOR-MA-02	Change of material composition - Ceramic	P P	Change of ceramic composition ceramic material class (2hO, etc.) will not be changed, only dopands will be changed	e e.g. changes in additives amount	С		•	•	-	-		-		-	-	@•	@• @	•	@•	@B	@• @S		-		-	-	-			-	- @	
PAS-VOR-MA-03	Change of material composition - Electrode	РР	Change of inner electrode material. Valid in case of multilayer structures only.	e.g. change from AgP1 material to AgPd material	С			•	@• @•	-	- @	9• 6	@• -		-			@•		@B			-		-	-	-		-	-	- @	
PAS-VOR-MA-04	Change of material composition - Encapsulation	РР	Change of encapsulation material.	e.g. change of coating e.g. change of additives in an insulation.	В	A: Risk assessment on application level, if interaction with other material expected.		•	@• @•	-	@• @	9•			-		@• @	•	-	@B	@• -		-		-	-	-		-	-	- @	
PAS-VDR-MA-05	Change of material composition - Lead material / Termination	РР	Change of lead (finish) material, termination material or attachment material.	e.g. change from SnPb to pure Sn	В	Risk assessment needed to evaluate compatibility of soldering process.				-	@• @	Q• @	@• -	- @•		@• -		@•	@•	@B	- @•	@• -					-		-	-		
PAS-VDR-MA-06	Change of supplier of material	. Р	Change to a new or additional material suppl at component manufacturer.	Ser e.g. for 2nd source purpose	с										-	- •				В			-		-				- 1	-	- @	Assumption material specification remains unchanged. Otherwise
	DESIGN					1				_		_						_		_					_		_					Charge or manual
PAS-VOR-DE-01	Changes of termination, surface finish, shape, color, appearance or dimension structure - Lead Diameter	I P	(for soidered 1911 components)	e.g. change lead darreter from 0.8 to 0.5 mm	A		•	-		-	@•	-		@• @•				-	-	@B		@• -	-		-	-	-			-	- @	
PAS-VOR-06-02	Changes of termination, surface finish, shape, color, appearance or dimension shucture - Termination Area Chances of termination, surface finish, shape, color, appearance or dimension shucture - Internal		Change of termination area	e.g. change of termination tayer thickness e.g. change in termination dimensions e.g. change from aridered connection in weight	В					-	@•	-	- @•		-				@•			@• -	-		-	-	-			-	- @	
PAS-VOR-DE-03	Connection		Change of inner connection Change of appearance.	e.g. change from soldered connection to welded connection	С					-	@• @	2• €	_	- @•	•	@• -		@•	@•	@B	- @•	@• -	-		-	-	-			-	- @	
PAS-VOR-DE-04	Changes of termination, surface finish, shape, color, appearance or dimension structure - Appearance Changes of inner construction - Electrode	I P	Change of appearance. Note: Marking on device is defined as asserate chance IPAS-VDR-PV-02. Change of electrode byer trickness or	e.g. change or adding of color on component Mainly in combination with other changes!	В		•			-			- @•		-			-	-	- В		-	-		-	-	-			-		
PAS-VDR-DE-05	Changes of Inner construction - Electrode Changes of Inner construction - Laver Thickness		geometry. Change of ceramic layer thickness. For multi-		c			-		@• @•		-		@• - @• -		-	@• @ @• @	_		В		•			+-	:	-			-	- @ - @	
		- P	Channe of number of centrals or electrode													-				В		_			-		-					
PAS-VOR-DE-07	Changes of inner construction - Number of Layers	- Р	layers. For multi-layer technology only. Allwa in combination with PAS-VDR-DE-06.	nys nee also layer thickness	С			-	•	_	•		•	@• -	-		@• •	-	-	-	- @•	@• -	-		-	٠	-			-	- @	
PAS-VOR-DE-08	Changes of inner construction - Grain size	- Р	Change of grain size. Grain size is a result or process and / or material change.	of e.g. change of grain size.	С					-	-				-			-	-	В			-		-	٠	-		-	-	- @	
PAS-VOR-DE-09	Changes of inner construction - Grain boundary size PROCESS	. P	Change of grain boundary size. Grain boundary size is a result of process and / or material change.	e.g. change of grain boundary size.	С			-		-	•	-	• -		-			•	-	В			-		-	•	-		لت	-	- @	
PAS-VDR-PR-01	PROCESS Changes in process technology or manufacturing methods - Lamination	. Р	Change of lamination / press technique meth	had e.a. stamp areas or lacetatic areas	С					@•	- 6	D•					@• @			@B	- @•		I . I				- 1			- 1	- @	
PAS-VDR-PR-02	Changes in process technology or manufacturing methods - Firing	. р		e.g. temperature and / or time and / or atmosphere. e.g. from tunnel to batch kiln.	С			-						@• -	-					В					-		-		-	-	- @	
PAS-VDR-PR-03	Changes in process technology or manufacturing methods - Dicing	. Р	Change of dicing	e.g. change from cutting to sawing	С				@• •		@•	•		• -	@•	@• -		-		В			-		-	•	-		-	-	- @	
PAS-VDR-PR-04	Changes in process technology or manufacturing methods - Termination			ing e.g. change in plating technology (final termination) e.g. change from dp in paste to plating (apply)	В			-		-	-	-	•		-	- @•		-	•	В	. •	•	-		-	•	-		- 1	-	- @	
PAS-VOR-PR-05	Changes in process technology or manufacturing methods - Electrode apply	. Р	Change of electrode apply. For multi layer technology only.	e.g. change of inner electrode lay down method. e.g. soldering method for lead attach to element or coating / encapsulation process	С		•		@• -	-		9∙			-		@• @			@B	- @•		-		-	-	-			-	- @	
PAS-VOR-PR-05 PAS-VOR-PR-07	Changes in process technology or manufacturing methods - Assembly Process inlegitly: furing within specification	. P	Change in assembly process for leaded or encapsulated devices. Variation within process specification.	e.g. soldering method for lead attach to element or coating / encapsulation process	В				@• @•					@• -		- @•		-	@•		@• -		-		-	-	-		-	-		4
	PACKING / SHIPPING - NEW MATERIAL, CRITICAL DIMENSIONS			eg possicoso																												
PAS-VDR-PN-01	Packing / shipping specification change (loosening of tolerances)		Change of packing specification.	e.g. number of pieces on real.	В			-		-	-	-			-			-	-	-			-		-	-	-		-	-		
PAS-VDR-PN-02	Dry pack requirements change	I P	Change of dry pack requirements. (i): Relaxation of dry pack requirements. (iP): Tightening of dry pack requirements.	e.g. change in dry pack assurance (HIC, MEE) (R: MSL 3 → MSL 1 (P): MSL 1 → MSL 3	В		- F	-		-	-	-			-			-	-	-			-		-	-	-		1 - 1	-		
PAS-VDR-PN-03	Change of carrier (tray, reel)	РР	Change of carrier	e.g. change by material e.g. change by geometry.	В			-	-	-	-	-			-			-	-	-			-		-	-	-		-	-		
PAS-VDR-PV-01	PACKING / SHIPPING - VISUAL INSPECTION Change of labeling		Change of labeling, also on real.	(i) e.g. additional information (RoPG stamp) (IP) e.g. change of customer specific information	В					1.1		.			T.T		Ι.Ι.		1.1	. 1			1.1		Т.					- 1		
PAS-VDR-PV-02	Change of product marking		Marking on device.	e.g. change of content of marking e.g. change of method of marking	В																				1.					.		
PAS-VDR-PV-03	Change of packing/shipping specification	PP	-																													
	Change of packing/shipping specification LOGISTICS / CAPACITY / TESTING - EQUIPMENTENT	- -	Change in packing specification which does not described a change of dimensions or material of the packing.	specification															لنط				انا			النا			ل			
PAS-VOR-EQ-01	Production from a new equipment tool which uses a different technology or which due to its unique form or function can be expected to influence the integrity of the final product	РР	Change in process technique which is not already covered above. Note: Changes affecting the product not covered by the table require also a PCN.	e.g. change from well to dry technology.	с		•	-		-	•	-	• -		-	- •		•	-	В			-	- @		•	-		-	-	- @	process change.
PAS-VOR-EIQ-02	Production from a new equipment/bod which uses the same basic technology (replacement equipment or extension of existing equipment pool)	. Р	PCN required for dedicated equipment for sensitive component production.	e.g. elimination of manual handling processes	с		•	-	- •	-	•	- -	• -		-	- •		•	-	В			-	- @	• -	•	-		-	-	. @	Test effort depends on final risk assessment. Performance test according to process change.
PAS-VOR-ED-03	Change in first last equipment type that uses a different technology	РР	Change of final test equipment which use different technology. PCN required for dedicated equipment for sensitive parameters.	e.g. change of tester platform	С		•	-		-	-	-			-			-	-	@B			-			-	-			-	- @	
	LOGISTICS / CAPACITY / TESTING - PROCESS FLOW		Change of manufacturing site. Includes transfer as well as additional site. Note: Reorganization inside one plantisite is	e.g. movement or transfer of manufacturing site or process step(s) to a different location/site.																												_
PAS-VDR-PF-01	Manufacturing site transfer or movement of a part of production process to a different location/site	P P	not arrected	e.o. dual source / fab strategy	В				• •	-	•	•	• •	• •	-	• •		•	•	В	•	• @•	•			•	-			- @	2• @	
PAS-VDR-PF-02	Elimination or addition of a manufacturing process step	. Р	Change of manufacturing process sequence	e. e.g. sessing / cleaning process e.g. change of order of processes	С		•	-		-	-	-			-			-	-	-			-	- -	-	-	-	- -	-	-	- @	Characterisation depends on in production flow.
PAS-VOR-QG-01	LOGISTICS / CAPACITY / TESTING - Q-GATE Change of leaf coverage used by the supplier to ensure data sheet compliance (e.g., enterestablead for of electrical measure-ensettlest flow block, relaxation/enhancement of monitoring procedure or sumpling).	. Р	Change of last coverage.	e.g. change from 100% to sample inspection e.g. leaf flow block, reduction from three to two temperature researcements e.g. change in burn in/run in process.	С			-		-	-				- 1		- -	-	-	-			-	- -	-	-	-		-	-		R (electr. funct): test coverage R (reliability) only for change in process.
Tests, which should	be considered for the appropriate process change.							-		-	-	-						-	-	-			-		-	-	-			-		
Tests, which should	i be considered for the appropriate process change after selection of condition	n table.						-				-							-	-			-						-	-		
Suppliers performe	d tests (mark with an "X" for done or "G" for generic)											Ŧ																			ī	
	on of tests and/or usage of generic data:																															

-	Not required
1	Information Note required
Р	PCN required

A latter or "*" indicates that performance of that stress test should be considered for the appropriate process change.

A "RE" is recommended additionally by ZVEI

CONDITIONS
Termination equipment of Ceramics only



issempt. => Please mark 'NO' with 'x', default is 'YES'